BCM53161XU

Ultra-Low Power Layer2 GE/FE Switch with 10G Uplinks

General Descriptions

Broadcom's BCM53161XU is a family of highly integrated Ethernet switches that are optimally designed for cost-effective low-power applications in the SMB, Enterprise, Service-Provider, and SOHO markets that rapidly transition to Gigabit-Ethernet connectivity and beyond.

The BCM53161XU is based on the industry-leading 28 nm RoboSwitch™ architecture, also known as Robo 2. The product line includes multiple models with 6 to 15 interfaces that support 100M/1GE/2.5GE and 10GE of bandwidth.

The BCM53161XU is designed for standalone low port-count configurations and high port-count configurations with support for cascading.

The BCM53161XU allows customers to design complete product platforms that target new cost-effective low-power applications demanding 1GE/10GbE connectivity. Among those, SMB switch with 10G uplinks, Enterprise switches, routers and security appliances, next generation Industrial Ethernet switches, and Service Provider access equipment.

The BCM53161XU is also designed to support basic applications that include Auto DOS, Auto VOIP, Auto QoS, and more. The product line takes advantage of a low-power integrated ARM Cortex-M7 CPU to offer on-chip support for certain protocols, including Auto IGMP snooping as well as tools for monitoring and troubleshooting. The product line is offered in Commercial-grade as well as Industrial-grade temperature ranges.

Features

- ARM Cortex-M7 at up to 400 MHz.
- Operational mode: Unmanaged.
- Up to 4×SGMII ports for 1GE/2.5GE connectivity.
- Up to 2×10G XFI with KR support.
- 1 × RGMII.
- Switch cascading.
- 16K entry MAC address table.

- 1K multicast group support.
- 128 KB packet buffer.
- srTCM and trTCM meters (support color aware and color blind modes).
- Eight CoS queues per port with priority flow-control.
- IEEE 802.1p, MAC, and DSCP packet classification.
- Auto Loop detection.
- Auto DoS.
- Auto VOIP.
- Auto QOS.
- Auto IGMP snooping.
- 1K packets and bytes counters.
- IEEE 802.3az Energy Efficient Ethernet (EEE).
- Jumbo frame support: up to 9728 bytes.
- 425-pin, 19×19 mm^2 FBGA package.
- JTAG support.
- Includes one UART and MDIO interface, seven I^{2}C interfaces, and 16 GPIOs (via the MFIO).

Figure 1: Functional Block Diagram
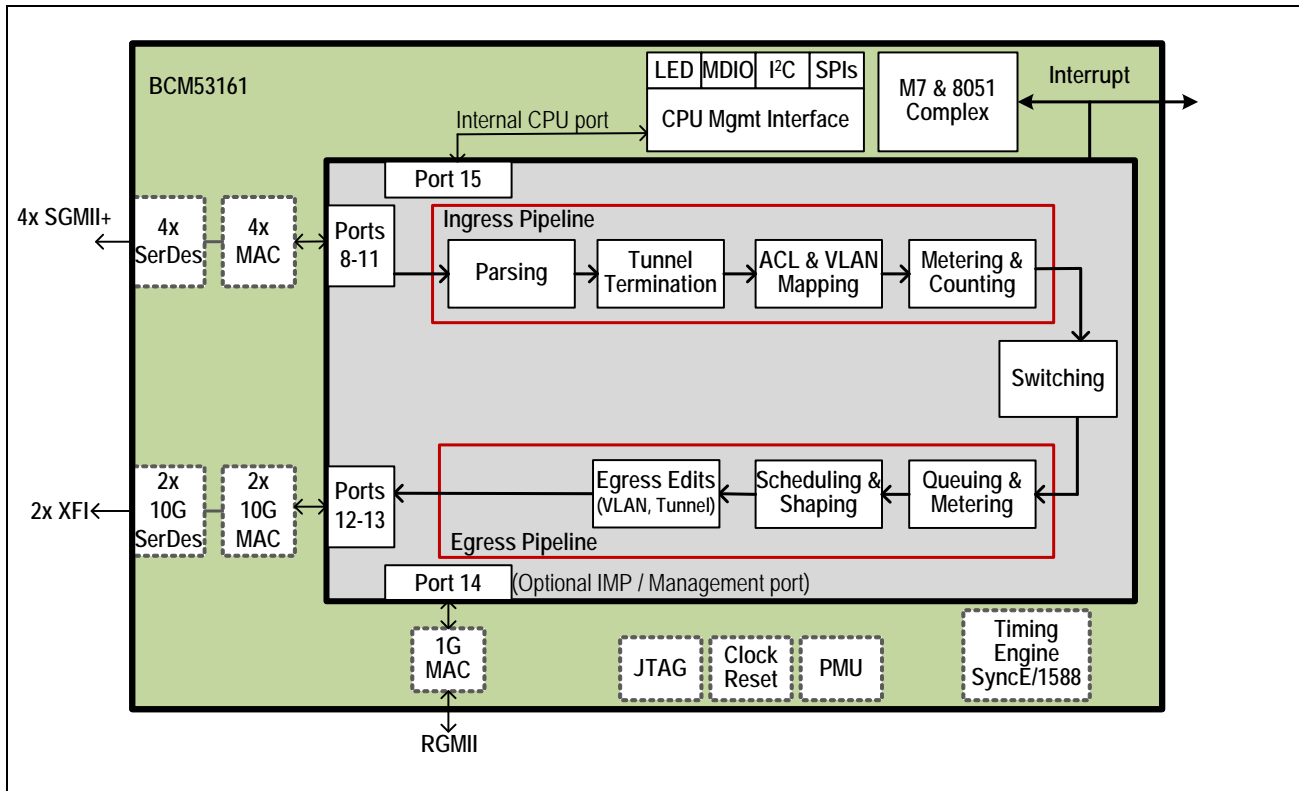
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Chapter 1: Introduction

1.1 Overview

This document provides details of the functional, operational, and electrical characteristics of the Broadcom® BCM53161XU. This document is for designers interested in integrating the BCM53161XU switches into their hardware designs and for others who need specific data about the physical characteristics and operation of the BCM53161XU switches.

The BCM53161XU is a highly integrated Ethernet switches that are optimally designed for cost-effective low-power applications in the SMB, Enterprise, Service-Provider, SOHO, and Industrial-Ethernet markets. The BCM53161XU is the first family of products in the RoboSwitch® product line to introduce 10 GE ports, which are relevant in markets that are rapidly transitioning to Gigabit-Ethernet connectivity anywhere.

The BCM53161XU switch core supports full-duplex packet forwarding bandwidth of 31 Gb/s for all packet lengths (64 byte to 9720 Jumbo frames).

The family is based on a core technology that supports:

- Four 2.5GE/1GE SGMII ports with integrated XMACs
- Two 10GE/2.5GE/1GE XFI ports with integrated XMACs
- One RGMII port for PHY-less connection to the management agent (available only in full-duplex mode)
- An integrated Motorola SPI-compatible interface
- High-performance, integrated packet buffer memory
- An address resolution engine

The GMACs support full-duplex and half-duplex modes for 10 Mb/s and 100 Mb/s, and full-duplex for 1000 Mb/s. Flow control is supported in half-duplex mode with backpressure. In full-duplex mode, IEEE 802.3x frame-based flow control is supported. The GMACs are IEEE 802.3-compliant and support a maximum frame size of 9720 bytes.

The BCM53161XUX supports advanced ContentAware™ processing using a compact field processor (CFP). Up to four intelligent ContentAware processes are performed in parallel for every packet. This flexible engine uses TCAM-based architecture which allows wildcard capabilities. Action examples include dropping, changing the forward port map, adding forward port, assigning the priority of a frame, and so on. These advanced ContentAware processes are well suited for access control lists (ACLs) and DoS prevention.

An integrated address management engine provides address learning and recognition functions at maximum frame rates. The address table provides capacity for learning up to 16K unicast addresses. Addresses are added to the table after receiving an error-free packet.

The MIB statistics registers collect receive and transmit statistics for each port and provide direct hardware support for the EtherLike-MIB, MIB II (interfaces), and the first four groups of the RMON MIB. All nine groups of RMON can be supported by using additional capabilities, such as port mirroring/snooping, together with an external microcontroller to process some MIB attributes. The MIB registers can be accessed through the Serial Peripheral Interface Port by an external microcontroller.

1.2 Target Markets

The BCM53161XU series targets four main markets:

- SMB – Capacity requirement in this market is steadily growing. While 1GE is currently the prominent connectivity speed (about 55% of all links in the SMB), 2016 is the year in which 10GE connectivity is expected to reach the SMB market as well. The BCM53161XU was designed to support this market segment by providing 1GE connectivity toward the SMB customers' end nodes and 2.5GE/10GE connectivity toward the WAN.
- Service Provider – The BCM53161XU is focused on two sub-segments within the Service Provider market: 10G G/EPON MDU ONUs and 10GE small-cells. The first sub-segment mentioned is expected to drive the next cycle of growth in embedded connectivity. The BCM53161XUis designed to complete G/EPON chip-sets in ONU and design and deliver a cost effective and high-speed solution. The series is also designed to be used as an embedded component within a small-cell design as they are upgraded to 2.5GE and 10GE connection.

1.3 Operational Mode

BCM53161XU devices support Unmanaged Mode (U) operational modes.

- Unmanaged mode (U) – This mode should be used by customers who would like to build the most basic switching platform with a single bridging domain, no support for virtual LANs, that is, IEEE 802.1Q VLANS and no ability to rate limit incoming or outgoing traffic. This unmanaged mode does provide customers with 8 traffic classes per port, a default 1:1 mapping between incoming traffic VLAN priority bits and those queues (p-bits with value X will be mapped to queue X+1) and default WRR scheduling weights for improved scheduling of traffic from the queues (the weights are 1:1:2:2:4:4:8:8).

In this mode, the device is shipped to customers with a basic out-of-the-box configuration that activates the switch in a single, no VLAN support, bridging domain. This basic configuration is available on the device's internal ROM and no additional memory is required. However, customers can get additional functionality to that mentioned above by using an external flash and downloading BRDCM's Advanced Unmanaged software. This software supports, in addition to the basic functionality, Auto-Loopdetect, Auto-Dos, and Auto-VoIP functionality, autoQos, and auto IGMP snooping that are further explained here. This mode is termed "Advanced Unmanaged." Note that this mode is not offered separately from the regular Unmanaged mode (U) as it mainly requires that the end user deploy external flash for additional memory.

Table 1: BCM53161XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
System **(CPU, Memory, Basic Software, Power)**	Processor	Integrated M7 CPU
	ROM memory for image and config	Internal ROM + Flash Flash is necessary
	Operating System	Bare Metal
	Software Format Delivered to Customers	Binary Code
	SDK Support	✓ Initialization RSDK
	Direct Register Access Support	✓
	Packet Memory	1 MB
	CPU Memory	8 KB
L1	Cable Diagnostic	✓*
	Cascading	✓*
	EEE power saving (IEEE 802.3az)[a]	✓
	AVS3	✓*
	Link Aggregation (LAG)	✗

Table 1: BCM53161XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
L2 Forwarding	Jumbo Frames	✓ (9720)
	Switching/MAC Learning	✓ (16K)
	Broadcast Storm Control	✓*
	VLAN support (multiple bridging domains)	✗
	VLAN translation	✗
	Isolation group (tree)	✗
	Ingress Mirroring	✗
	Egress Mirroring	✗
	Traffic Sampling	✗
	CFP support (ACLs)	✗
	AutoLoop	✓*
	AutoVOIP	✓* (256 SA)
	AutoDOS	✓*
L2 QoS	Queues per port	8
	IEEE 802.1p Priority mapping	✓* Through AutoQoS – mapping is fixed
	DSCP priority mapping	✓* Through AutoQoS – mapping is fixed
	Scheduling configurable SP	✓* Through AutoQoS
	Scheduling configurable WRR	✓* Through AutoQoS - Weights are configurable
	Metering Rate Limiting	✗
	Shaping queue/port	✗
	Hierarchical Shaping	✗
	Flow Control – PAUSE IEEE 802.3x	✓*
	Flow Control – PFC IEEE 802.1QBB	✓*
Management	Debug CLI	✓
	RESTful API	✗
	Rx and Tx Counters	✗
Multicast	IGMP Snooping	✓*
Protocols and Advanced Features	LLDP	✗
	Rapid Spanning Tree	✗
	Cisco MAC-in-MAC	✗
	Port Extender/IEEE 802.1BR	✗

Table 1: BCM53161XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
Time-Sensitive Networking (TSN) Support	IEEE 802.1AS (subset of 1588) – One Step	✗
	IEEE 802.1AS (subset of 1588) – Two Steps	✗
	IEEE 802.1Qbv (enhancements ftraffic scheduling)	✗
	IEEE 802.1Qcc (Stream Reservation Protocol –SRP, HW support)	✗
	Cut-Through mode	✗
	IEEE 802.1Qav (TSN Forwarding and Queuing)	✗
	AVB (class A and class B)	✗

a. When EEE is enabled (EEE feature is for GPHY port only), the cut-through latency time is impacted causing very high latency (tens of microsceonds). The selection of either EEE or cut-through does not impact performance since both are not available.

1.4 BCM53161XU Devices

The BCM53161X is a 4 SGMII+ port Switch with two 10GE/2.5GE/1GE uplinks. See the full SKU list in .

The BCM53161XU is offered in one 19×19 mm^2 package with 425 pins.

provides a detailed list of the physical characteristics for each device in the BCM53161XU family of switches.

Table 2: BCM5316X Family Features

Features	BCM53161XU
RGMII (port 14)	1
GPHY (ports 0 through 7) 10/100/BASE-T	0
GPHY (ports 0 through 7) 10/100/1000BASE-T	0
SGMII (ports 8 through 11) 100/1000FX/2500FX	4
XFI (ports 12 through 13) 2.5GE/1GE	0
XFI (ports 12 through 13) 10GE/2.5GE/1GE	2
MDIO	1
SPI	3 (QSPI+2SP)
LED (28 pins)	Parallel
LED (2 pins)[a]	Serial
JTAG (w/ 2 jtce)	1
1588	Yes
SyncE	Yes
I^{2}C	7[b]
MFIO	16
WB-FBGA	19×19 mm^2
Package	0.80 mm
	pitch
	425 balls
PCB Layers	4
Weight	1100 mg
Ambient Temp[c]	0°C to 70°C

a. Serial LED uses two bits from the 28-bit parallel LED. Both cannot be active at the same time.

b. 19×19 mm package has seven I^{2}C (six dedicated + one muxed on MFIO) and 13×13 mm^2 package has 7× I^{2}C (all muxed on MFIO).

c. 0°C to 70°C for commercial SKUs

1.5 System Functional Blocks

1.5.1 Overview

The BCM53161XU includes the following blocks:

- Media Access Controller
- Interdevice Interface
- MIB Engine
- Integrated High-Performance Memory
- Robo 2 Switch Core

Each of these blocks is discussed in additional detail in the following sections.

1.5.2 Media Access Controller

The BCM53161XU contains two 1G/2.5G/10G XMACs, and four 10/100/1000/2.5G MACs.

The MAC automatically selects the appropriate speed (CSMA/CD or full-duplex) based on the PHY auto-negotiation result. In full-duplex mode, IEEE 802.3x PAUSE frame-based flow control is also determined through auto-negotiation. The MAC is IEEE 802.3, IEEE 802.3u, and IEEE 802.3x-compliant.

1.5.2.1 Receive Function

The MAC initiates frame reception following the assertion of receive data valid indication from the physical layer. The MAC monitors the frame for the following error conditions:

- Receive error indication from the PHY
- Runt frame error if frame is fewer than 64 bytes
- CRC error
- Long frame error if frame is greater than standard max. frame size or 9,720 bytes for jumbo-enabled ports.

NOTE:　Frames longer than standard max. frame size are considered oversized frames. When jumbo-frame mode is enabled, only the frames longer than 9,720 bytes are bad frames and dropped.

If no errors are detected, the frame is processed by the switch controller. Frames with errors are discarded. Receive functions can be disabled using register settings.

1.5.2.2 Transmit Function

Frame transmission begins with the switch controller queuing a frame to the MAC transmitter. The frame data is transmitted as received from the switch controller. The transmit controller is responsible for preamble insertion, carrier deferral, collision back-off, and inter-packet gap enforcement.

In 10/100 Mb/s half-duplex mode, when a frame is queued for transmission, the transmit controller behaves as specified by the IEEE 802.3 requirements for frame deferral. Following deferral, the transmitter adds 8 bytes of preamble and SFD to the frame data received from the switch controller. If, during frame transmission, a collision is observed and the collision window timer has not expired, the transmit controller asserts jam and then executes the back-off algorithm. The frame is retransmitted when appropriate. On the 16th consecutive collision, the back-off algorithm starts over at the initial state, the collision counter is reset, and attempts to transmit the current frame continue. Following a late collision, the frame is aborted, and the switch controller is allowed to queue the next frame for transmission.

While in full-duplex mode, the transmit controller ignores carrier activity and collision indication. Transmission begins after the switch controller queues the frame and the 96-bit times of IPG have been observed. Transmit functions can be disabled using register settings.

1.5.2.3 Flow Control

The BCM53161XU implements an intelligent flow-control algorithm to minimize the system impact resulting from traffic congestion. Buffer memory allocation is adaptive to the status of each port's speed and duplex mode, providing an optimal balance between flow management and per-port memory depth. The BCM53161XU initiates flow control in response to buffer memory conditions on a per-port basis.

The MACs are capable of flow control in full-duplex mode.

1.5.2.3.1 10/100 Mb/s Half-Duplex

In 10/100 half-duplex mode, the MAC back-pressures a receiving port by transmitting a 96-bit time jam packet to the port. A single jam packet is asserted for each received packet for the duration of the time the port is in the flow-control state.

1.5.2.3.2 10/100/1000 Mb/s Full-Duplex

Flow control in full-duplex mode functions as specified by the IEEE 802.3x requirements. In the receiver, MAC flow-control frames are recognized and, when properly received, set the flow-control pause time for the transmit controller. The pause time is assigned from the 2-byte pause time field following the pause opcode. MAC control PAUSE frames are not forwarded from the receiver to the switch controller.

When the switch controller requests flow control, the transmit controller transmits a MAC control PAUSE frame with the pause time set to maximum. When the condition that caused the flow control state is no longer present, a second MAC control PAUSE frame is sent with the pause time field set to 0.

1.5.2.3.3 Priority Flow Control

Priority Flow Control (PFC) is a mechanism of conveying the per priority XON/XOFF information for 8 different classes using MAC control frames. Unimac provides the flexibility to program the DA, TYPE, and OPCODE fields for the PFC frames. The PFC feature can be independently enabled inside the MAC and pause should be disabled while PFC is operational to ensure IEEE compliance.

1.5.3 Interdevice Interface

The BCM53161XU can connect to two types of external devices: another BCM53161XU (cascade) and/or and external processor (CP). The information required for these two application is similar and uses a common header.

The processor can be connected to any port including the internal processor. In Robo terminology, this port is designated as an IMP (internal management port). Frames that are sent to these destinations use the same forwarding rules as any other destination, for example DLIs. There are various ways frames can be directed to each of these destinations including the CFP, ARL, and various filters. Part of the DLI instruction could be to insert the CB tag which provides additional information to aid in processing the frames.

There is one type of IMP header designs which the BCM53161XU supports: CB TAG – 8B CB tag which is inserted directly after the MAC-SA

- This format is parseable via the CT-TAG Ethertype.
- This format might include an optional timestamp with a separate Ethertype.

Figure 2: IMP/CB Header Formats

CB_TAG Header

Original MAC DA[47:0]
Original MAC SA[47:0]
EType | CB_TAG
EType | CB_TAG
Original Frame Data, Excluding the Original FCS
Original FCS (Optional)
New FCS
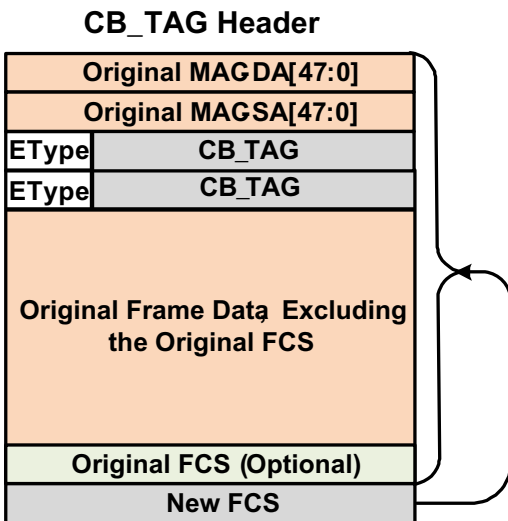
The following rules and guidelines are used for:

- All frames on a cascade port will carry the CB tag.
- Traffic on the IMP port may or may not have the CB tag.
- Normal processing (for example, a port is the destination of the frame) can be sent without a tag.
- When a CB receives a frame with a CB_TAG, the SPG, SLI, and VSI are reconstituted based on information in the tag. It is presented to the ARL lookups as if the frame was processed by the receive logic.
- There are few exceptions to this i.e. traps, mirroring and directed forwarding.
- After the tag is parsed it is removed.

NOTE: For unicast, multicast, traps, and exception forwarding, it is intended that the source information (SPG, LIN, VSI) is populated in the receive header. This enables the CPU to use this in processing to determine the how to forward the frame. In addition, it is expected the CPU properly sets these fields when it sends a frame to the switch which is sent out.

The Switch to CP and CP to Switch tag formats are purposely defined to be consistent across the IMP and Cascade modes. The forwarding codes (fwd_op) are defined to allow the hardware to interpret the intended function from the code point regardless of the specific IMP or Cascade type in most cases.

1.5.3.1 Switch to Control Plane: CB Tag

This tag is used to communicate information to an attached CPU or cascaded BCM53161XU. The format and fields are defined in the following tables. The tag is attached to frames using editing directives. The directive could be associated with a port (PET table) or DLI. The Ethertype for this tag is taken from a configuration register. The format and fields are defined in Table 3.

Table 3: Switch to CB TAG Format

15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
Ethertype															
TC			DP			FWD_OP			DEV	LBH/TRAP_GROUP/SPP/DPP					
DEST[11:0] - depends on FWD_OP {for example, DLLI/DG/EXCEPTION}												R	R	SPG	
SPG		T		N_VSI [11:0] (VSI or LIN based on T)											

Table 4: Switch to CP Header Format Fields

Field	Function
Ethertype	Configured value
TC	TC value classified for the packet by the switch
DP	Discard precedence
DEV	Source device identifier; configured by software
SPG	Source Port Group – SPG determined for the frame
FWD_OP	Forwarding Operation – see table
T	LIN Type indicator. 0 is LIN, 1 is PV format
N_VSI	Source Local Logical Interface: If T = 1 (type PV), SLLI = {1,0,SPG}; VSI=N_VSI else(type LIN) SLLI={0,N_VSI}; VSI=LIN2VSI(N_VSI);
DEST - overlay	Overlay field with one of the following depending on FWD_OP
DLLI	Destination Logical Local Interface: If FWD_OP = UNICAST
DG	Destination Group (multicast/broadcast): If FWD_OP = MULTICAST
EXCEPTION	Exception – Identifies the reason a trap was triggered (TRAP, SLIC, CFP): If FWD_OP = TRAP
LBH - overlay	Trap Group/Load Balancing Hash : If FWD_OP=TRAP, TRAP_GROUP else LBH
LBH	Load balancing hash- Valid for all op codes except 2
Trap_group	Trap group for the SLICT and CFP traps in FWD_OP=2
SPP	Source Physical Port for traps (FWD_OP=2)
DPP	Destination Physical Port
RSVD	Reserved – write as zero, ignore on receipt

The forwarding operation (FWD_OP) field defines the content of the DEST field and provides information to the CPU regarding why the frame was delivered. The DEST field in the header is overlay with number of meanings summarized in the following table.

Table 5: IMP Header Forwarding Operation: Switch to CP

FWDOP	Function	DEST	LRN?	TG/LBH/SPP	Notes – processing at EPP
0	CP Directed Forwarding	0	No	DPP	Frame is directly sent on port specified by LBH/DPP field.
0	Unicast Directed Forwarding	DLLI	Yes	LBH	Unicast forwarding with known destination, that is, the DLI. The SPG, N_VSI, and T fields are used to reconstitute the SLI for the frame before the ARL Source lookup is done.
1	Multicast Directed Forwarding	DG	Yes	LBH	Multicast forwarding with known destination i.e. DG. The SPG, N_VSI, and T fields are used to reconstitute the SLI for the frame before the ARL Source lookup is done.
2[a]	SA Learn	SA_LRN (trap_id)	Yes	LBH	Learning message: This is generated based on SA Miss in the source device ARL lookup. The SPG, T and N_VSI are used to in the ARL lookup. This is converted to CA_SA_LRN trap.
2[a]	SA Move	SA_MOVE (trap_id)	Yes	LBH	SA Move message: This is generated based on SA move in the source device ARL lookup. The SPG, T and N_VSI are used to in the ARL lookup. This is converted to CA_SA_LRN trap.
2[a]	Mirror	128-191 (mirror_Id)	No	LBH	This is a copy generated due to mirroring, the mirror id is extracted from the DEST and the MTGT is used to determine how the frame is handled.
2[a]	Trap	1-127 (trap_id)	No	SPP	This is a copy generated due to a trap condition. The trap_id is extracted from the DEST field and the TCT table will govern the handling of this frame.
2[a]	SLIC_TRAP	256-511 (slic_trap)	No	Trap_group	This is a copy generated due to a SLIC trap condition. The trap_group is extracted from the LBH field and the MTGT table is use to determine how the frame is handled.
2[a]	CFP_TRAP	2048-3071 (action_idx)	No	Trap_group	This is a copy generated due to a CFP trap condition. The trap_group is extracted from the LBH field and the MTGT table is use to determine how the frame is handled.
2[a]	NULL TAG	0x0	Yes	X	NOP TAG – CB tag is removed and processed as if it arrived on the CPU port (backwards compatibility so all frames can have a tag), This use and unused trap_group code point.
3–7	Reserved	n/a	n/a	Na/	Reserved for future use.

a. For FWD_OP = 2 the DEST is defined as an EXCEPTION following the encoding shown in Figure 24.

Here are some notes on processing frames at the CPU/Cascaded Device:

- The CB tag is removed on ingress.
- If fwd_op = 0x0 and DLLI is zero, a valid destination was not determined by the switch (DLF destination lookup failure).
- Flooding uses a multicast forwarding with a zero DG. In this case, the flooding map (pg_map) comes from the VSIT based on the VSI in the frame (or LIN2VSI).
- Multicast is handled by used the DG as multicast group.
- For FWD_OP = 2 the encoding the DEST field is used to identify the type of frame (SA-Learn, Mirror, TRAP). The encoding follows the EXCEPTION space shown in Figure 24.
- The DEV field must be preserved if the frame is sent to a CPU with CB_TAG. This allows the CPU to determine which of the two devices the originated exception frame.
- SA learning and SA movement traps are converted to cascaded version of the trap and the {vsi, smac} is inserted in the ARL table if possible.
- Mirror implies the frame was mirrored or sampled; the mirror_group is extracted from the DEST field and the mirror is handled group gives further information or will be used by a cascaded BCM53161XU to process the mirror.
- SA learn packets will be locally learned and converted to local cascaded traps for cascade processing.

■ The trap packet uses the trap_group to process the frame. Note this is the only format that has a SPP versus a SPG.

1.5.3.2 Switch to Control Plane: Time Stamp Tag

This section describes the tag used from the switch to CPU to send the time stamp. This tag is added using an egress editing directive. The format and fields are defined in the following tables. The Ethertype for this tag is taken from a configuration register.

Table 6: Egress CB TS Tag

15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
Ethertype															
TIMESTAMP[47:32]															
TIMESTAMP[31:16]															
TIMESTAMP[15:0]															

The Ethertype is taken from a software configured register. Timestamp is the 48 bit value sampled at Start of Packet when the frame arrived.

1.5.3.3 Control Plane to Switch: CB Tag

This section describes the tag used from the Control Plane to Switch. The fields are the same as the Switch to CP format described above. Normal frame processing (Unicast, Multicast, and Flooding) rely on the SPG, T and N_VSI field being set properly by the CPU. As noted before, this fields will be valid for frames received by the CPU. It is therefore possible, to direct this frame to a DLI by simply populating the DLI, FWD_OP and sending the frame back into the switch using this format. The following notes apply to sending frames from the CPU:

■ To send a Unicast frame out a port group ; Frame learned by ARL and egress edits ARE applied:
  – Set FWD_OP=0 to Unicast Directed Forwarding
  – Set DEST = DLLI - frame will be forwarded based specified DLI
  – Set T, SPG, N_VSI - frame will be learned in this context
■ To send a Unicast frame out a physical port without any checks (VLAN membership, STP, or filters); Frame is not learned by ARL and egress edits ARE NOT applied:
  – Set FWD_OP=0 to Unicast Directed Forwarding
  – Set DEST = 0
  – Set LBH/DPP field to desired port (DPP); Note this is the only format that has a DPP vs DPG.
■ To send a frame to a multicast group:
  – Set FWD_OP=1 to Multicast Directed Forwarding;
  – Set DEST to DG - frame will be forwarded based specified DLI
  – Set T, SPG, N_VSI - the SLLID to SLLID for frame will be derived from these fields for source port knock-out.
■ To send a frame and have the switch forward the frame; Frame is learned by ARL:
  – Send the frame without the IMP/CP tag

1.5.4 MIB Engine

The MIB Engine is responsible for processing status words received from each port. Based on whether it is a receive status or transmit status, appropriate MIB counters are updated. The BCM53161XU implements 66 MIB counters on a per-port basis. MIB counters can be categorized into three groups: receive-only counters, transmit-only counters, and receive or transmit counters. This latter group can, as a group, be selectively steered to the receive or transmit process on a per-port basis. The section below describes each individual counter.

The BCM53161XU offers the MIB snapshot feature per port. A snapshot of a selected port MIB registers can be captured and available to the users while MIB counters are continuing to count.

1.5.4.1 MIB Counters

All counters can be read/write access. The reset values are all zero.

Table 7: Receive MIB Counters (per port)

Receive Counter	Width	Description
RxDropPkts	32	Number of good packets received by a port that were dropped due to a lack of resources (for example, lack of input buffers) or were dropped due to a lack of resources before a determination of the validity of the packet was able to be made (for example, receive FIFO overflow). The counter is only incremented if the receive error was not counted by the RxExcessSizeDisc, the RxAlignmentErrors, or the RxFCSErrors counters.
RxOctets	64	Number of data bytes received by a port (excluding preamble, but including FCS), including bad packets.
RxBroadcastPkts	32	Number of good packets received by a port that are directed to the broadcast address. This counter does not include errored broadcast packets or valid multicast packets. The maximum packet size can be programmed.
RxMulticastPkts	32	Number of good packets received by a port that are directed to a multicast address. This counter does not include errored multicast packets or valid broadcast packets. The maximum packet size can be programmed.
RxSAChanges	32	Number of times the SA of good receive packets has changed from the previous value. A count greater than 1 generally indicates the port is connected to a repeater-based network. The maximum packet size can be programmed.
RxUndersizePkts	32	Number of good packets received by a port that are less than 64 bytes long (excluding framing bits, but including the FCS).
RxOversizePkts	32	Number of good packets received by a port that are greater than standard max frame size. The maximum packet size can be programmed.
RxFragments	32	Number of packets received by a port that are less than 64 bytes (excluding framing bits) and have either an FCS error or an alignment error.
RxJabbers	32	Number of packets received by a port that are longer than standard max frame size and have either an FCS error or an alignment error.
RxUnicastPkts	32	Number of good packets received by a port that are addressed to a unicast address. The maximum packet size can be programmed.
RxAlignmentErrors	32	Number of packets received by a port that have a length (excluding framing bits, but including FCS) between 64 and standard max frame size, inclusive, and have a bad FCS with a nonintegral number of bytes.
RxFCSErrors	32	Number of packets received by a port that have a length (excluding framing bits, but including FCS) between 64 and standard max frame size inclusive, and have a bad FCS with an integral number of bytes.
RxGoodOctets	64	Total number of bytes in all good packets received by a port (excluding framing bits, but including FCS). The maximum packet size can be programmed.
JumboPktCount	32	Number of good packets received by a port that are greater than the standard maximum size and less than or equal to the jumbo packet size, regardless of CRC or alignment errors.

Table 7: Receive MIB Counters (per port) (Continued)

Receive Counter	Width	Description
RxPausePfcPkts	32	When PAUSE is configured: This counter counts the number of PAUSE frame on the port. When the port is configured in PFC mode it counts the number of PFC frames. Number of PAUSE frames received by a port. The PAUSE frame must have a valid MAC Control Frame EtherType field (88–08h), have a destination MAC address of either the MAC Control frame reserved multicast address (01-80-C2-00-00-01) or the unique MAC address associated with the specific port, a valid PAUSE opcode (00–01), be a minimum of 64 bytes in length (excluding preamble but including FCS), and have a valid CRC. Although an IEEE 802.3-compliant MAC is only permitted to transmit PAUSE frames when in full-duplex mode with flow control enabled and with the transfer of PAUSE frames determined by the result of auto-negotiation, an IEEE 802.3 MAC receiver is required to count all received PAUSE frames, regardless of its half/full-duplex status. An indication that a MAC is in half-duplex with the RxPausePkts incrementing indicates a noncompliant transmitting device on the network.
RxSymbolErrors	32	Total number of times a valid-length packet was received at a port and at least one invalid data symbol was detected. The counter only increments once per carrier event and does not increment on detection of a collision during the carrier event.
RxDiscard	32	Number of good packets received by a port that were discarded by the Forwarding Process. This would include any shaping or DOS filters.
RxPkts64Octets	32	Number of packets received (including error packets) that are 64 bytes long.
RxPkts65to127Octets	32	Number of packets received (including error packets) that are between 65 and 127 bytes long.
RxPkts128to255Octets	32	Number of packets received (including error packets) that are between 128 and 255 bytes long.
RxPkts256to511Octets	32	Number of packets received (including error packets) that are between 256 and 511 bytes long.
RxPkts512to1023Octets	32	Number of packets received (including error packets) that are between 512 and 1023 bytes long.
RxPkts1024toMaxPktOctets	32	Number of packets received (include error packets) that are between 1024 and the standard maximum packet size inclusive.

Table 8: Transmit MIB Counters

Transmit Counter	Width	Description
TxDropPkts	32	This counter is incremented every time a transmit packet is dropped due to lack of resources (for example, transmit FIFO underflow), or an internal MAC sublayer transmit error not counted by either the TxLateCollision or the TxExcessiveCollision counters.
TxOctets	64	Total number of good bytes of data transmitted by a port (excluding preamble but including FCS).
TxBroadcastPkts	32	Number of good packets transmitted by a port that are directed to a broadcast address. This counter does not include errored broadcast packets or valid multicast packets.
TxMulticastPkts	32	Number of good packets transmitted by a port that are directed to a multicast address. This counter does not include errored multicast packets or valid broadcast packets.
TxCollisions	32	Number of collisions experienced by a port during packet transmissions.
TxUnicastPkts	32	Number of good packets transmitted by a port that are addressed to a unicast address.
TxSingleCollision	32	Number of packets successfully transmitted by a port that have experienced exactly one collision.
TxMultipleCollision	32	Number of packets successfully transmitted by a port that have experienced more than one collision.
TxDeferredTransmit	32	Number of packets transmitted by a port for which the first transmission attempt is delayed because the medium is busy. This only applies to the Half Duplex mode, while the Carrier Sensor Busy.
TxLateCollision	32	Number of times that a collision is detected later than 512 bit-times into the transmission of a packet.
TxExcessiveCollision	32	Number of packets that are not transmitted from a port because the packet experienced 16 transmission attempts.
TxPausePfcPkts	32	Number of PAUSE control frames sent when the port is configured in PAUSE mode. In PFC mode, it counts the number of PFC frames sent.
TxFrameInDisc	32	Number of valid packets received which are discarded by the forwarding process due to lack of space on an output queue (not maintained or reported in the MIB counters). This attribute only increments if a network device is not acting in compliance with a flow control request or the ROBO GE Switchcore internal flow-control/buffering scheme has been configured incorrectly.
TxQ0PKT	32	Total number of good packets transmitted on COS0, which is specified in MIB queue select register when QoS is enabled.
TxQ1PKT	32	Total number of good packets transmitted on COS1, which is specified in MIB queue select register when QoS is enabled.
TxQ2PKT	32	Total number of good packets transmitted on COS2, which is specified in MIB queue select register when QoS is enabled.
TxQ3PKT	32	Total number of good packets transmitted on COS3, which is specified in MIB queue select register when QoS is enabled.
TxQ4PKT	32	Total number of good packets transmitted on COS4, which is specified in MIB queue select register when QoS is enabled.
TxQ5PKT	32	Total number of good packets transmitted on COS5, which is specified in MIB queue select register when QoS is enabled.

Table 8: Transmit MIB Counters (Continued)

Transmit Counter	Width	Description
TxQ6PKT	32	Total number of good packets transmitted on COS6, which is specified in MIB queue select register when QoS is enabled.
TxQ7PKT	32	Total number of good packets transmitted on COS7, which is specified in MIB queue select register when QoS is enabled.
TxPkts64Octets	32	Number of transmitted packets (including error packets) that are 64 bytes long.
TxPkts65to127Octets	32	Number of transmitted packets (including error packets) that are between 65 and 127 bytes long.
TxPkts128to255Octets	32	Number of transmitted packets (including error packets) that are between 128 and 255 bytes long.
TxPkts256to511Octets	32	Number of transmitted packets (including error packets) that are between 256 and 511 bytes long.
TxPkts512to1023Octets	32	Number of transmitted packets (including error packets) that are between 512 and 1023 bytes long.
TxPkts1024toMaxPktOctets	32	Number of transmitted packets that (include error packets) are between 1024 and the standard maximum packet size inclusive.

1.5.5 Integrated High-Performance Memory

The BCM53161XU embeds a high-performance SRAM for storing packet data and associated metadata.

The integrated memory is 1 MB and can be flexibly partitioned into a packet buffer region, and a region available to the M7/8051 for instruction/data memory as well as storage for packets forwarded to the CPU (UM mode is restricted by OTP to only 128 KB of the 1 MB of memory). The BCM53161XU M7 processor also has 32 KB ITCM, 64 KB DCTM, 16 KB I-Cache, and 16 KB D-Cache.

In addition, instead of the IVM and EMV, the following tables exist:
- Logical Interface Mapper (LIM): 2K entry hash table to support virtual ports and double-tagged frames, etc.
- VSI Tag Control (VTC): 4K entry with per port controls for egress edits

This eliminates the need for external memory and allows for the implementation of extremely low-cost systems.

The internal RAM controller efficiently executes memory transfers and achieves nonblocking performance for stand-alone 8-port applications and for applications with up to 15 ports and 33 Gb/s throughput.

1.5.6 Robo 2 Switch Core

The core of the BCM53161XU devices is a cost-effective and high-performance switch controller. The controller manages packet forwarding between the MAC receive and transmit ports through the frame buffer memory with a store and forward architecture. The switch controller encompasses the functions of buffer management, memory arbitration, and transmit descriptor queuing.

1.5.6.1 Buffer Management

The frame buffer memory is divided into pages (units of data consisting of 256 bytes each). Each received packet may be allocated more than one page. For example, six pages are required to store a 1522-byte frame. Frame data is stored in the buffer memory as the packet is received. After reception, the frame is queued to the egress port(s) transmit queue. This list tracks the transmission of the packet. After successful packet transmission, the buffer memory is released to the free buffer pool.

1.5.6.2 Memory Arbitration

Processes requesting access to the internal memory include the receive and transmit frame data handlers, egress descriptor update, and output-port queue managers. These processes are arbitrated to provide fair access to the memory and minimize the latency of critical processes to provide a fully nonblocking solution.

1.5.6.3 Transmit Output Port Queues

Frames are maintained in the egress port using a linked list. Two levels of linked lists are used to maintain one output queue (see Figure 3). The first level is the TXQ linked list, and the second level is the buffer tag linked list. The TXQ linked list is used to maintain frame TC order for each port. For each frame, the buffer tag linked list is used to maintain the order of the buffer pages corresponding to each frame.

Each egress port supports up to eight transmit queues for servicing Quality of Service (QoS). All eight transmit queues share the all entries of the TXQ table. The TXQ table is maintained as a linked list, and each node in the TXQ uses one entry in the TXQ table.

When the QoS function has been turned off, the switch controller maintains one output queue for each egress port. The TXQ table is maintained in a per-port individual internal memory. Each node in the queue represents a pointer that points to a frame buffer tag. Each buffer tag includes frame information and a pointer to the next buffer tag. Each buffer tag has an associated page allocated in the frame buffer. For a packet with a frame size larger than 256 bytes, multiple buffer tags are required. For instance, a 9720-byte jumbo frame requires 38 buffer tags for handling the frame.

Figure 3: TXQ and Buffer Tag Structure
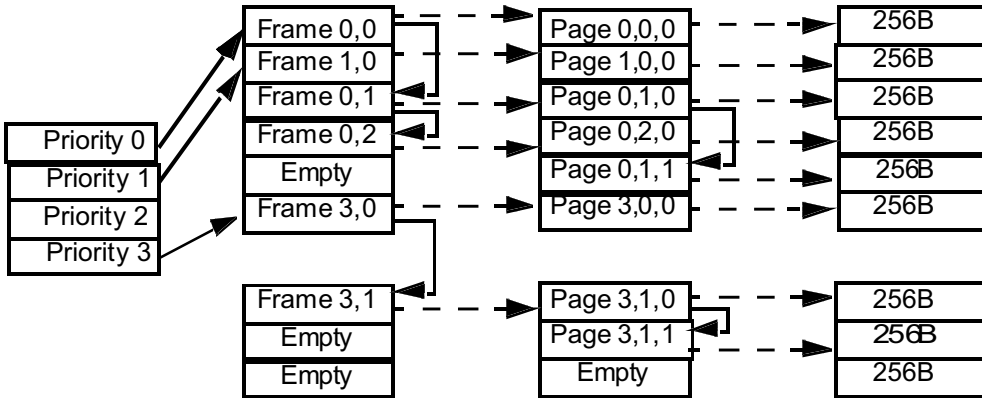
1.6 Notational Conventions

The following notational conventions are used in this document:

- Signal names are shown in uppercase letters (such as DATA).
- A bar over a signal name indicates that it is active low (such as CE).
- In register and signal descriptions, [n:m] indicates a range from bit n to bit m (such as [7:0] indicates bits 7 through 0, inclusive).
- The use of R or Reserved indicates that a bit or a field is reserved by Broadcom for future use. Typically, R is used for individual bits and Reserved is used for fields.
- Numerical modifiers such as K or M follow traditional usage (for example, 1 KB means 1,024 bytes, 100 Mb/s [referring to fast Ethernet speed] means 100,000,000 b/s, and 133 MHz means 133,000,000 Hz).

Chapter 2: Features and Operation

2.1 Overview

The BCM53161XU switches include the following features:

- ARM Cortex-M7 Core
- Software Reset
- Jumbo Frame Support
- AutoDOS
- AutoVOIP
- AutoQoS
- Auto LoopDetect
- Auto IGMP Snooping
- Cascading
- Cable Diagnosis
- Power-Saving Modes

The following sections discuss each feature in more detail.

2.2 ARM Cortex-M7 Core

The BCM53161XU integrates a low-power and high-performance ARM Cortex-M7 processor core with a clock speed of up to 400 MHz. The ARM Cortex-M7 core includes integrated 16 KB two-way set-associative I-Cache and 16 KB four-way set-associative D-Cache. The BCM53112/BCM5315X/BCM5316X also supports a 32 KB ITCM and 64 KB DTCM.

2.3 Software Reset

The BCM53161XU provides software resets. Software resets can be triggered by setting the register.

NOTE: Software reset sets all the register to the default values. Software reset does not latch in the strap pin values, but the previous latched strap pin values are retained.

2.4 Jumbo Frame Support

The BCM53161XU can receive and transmit frames of extended length on ports linked at Gigabit speed. Referred to as jumbo frames, these packets are longer than the standard maximum size, but shorter than 9728 bytes.

Jumbo packets can be received or forwarded to 1000BASE-T, and 2.5G, and 10G linked ports that are jumbo-frame enabled.

Up to 38 buffer memory pages are required for storing and the longest allowed jumbo frame. While there is no physical limitation to the number of ports that can be jumbo enabled, it is recommended that no more than two be enabled simultaneously to ensure system performance. There is no performance penalty for enabling additional jumbo ports beyond the potential strain on memory resources that can occur due to accumulated jumbo packets at multiple ports.

2.5 AutoDOS

The Automatic Denial-Of-Service (AutoDOS) feature detects potential DOS attacks and drops suspected incoming packets to defeat the attack. There are several possible DOS attacks that are identified based on simple classification rules that are applied to the incoming packet. Those rules, or a subset of them, must be selected for detection and dropping in unmanaged mode. Table 9 lists the DOS related classification rules that we support.

Table 9: DOS Prevention Supported in UM

DOS Type (Rule Type)	Description
MAC_LAND	MACDA=MADSA in an Ethernet packet.
IP_LAND	IPDA=IPSA in an IP (v4/v6) datagram.
TCP_BLAT	DPort=SPort in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
UDP_BLAT	DPort=SPort in a UDP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_NULLScan	Seq_Num=0 & All TCP_FLAGs=0, in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_XMASScan	Seq_Num= 0 & FIN=1 & URG=1 & PSH = 1 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_SYNFINScan	SYN=1 & FIN=1 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_SYNError	SYN=1 & ACK=0 & SRC_Port<1024 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.

Table 9: DOS Prevention Supported in UM (Continued)

DOS Type (Rule Type)	Description
TCP_FragError	The first IP fragment is not large enough to contain all required TCP header information. The total length of fragment as indicated in IP header is lesser than the combined size of IP header and TCP header.
ICMPv4_Fragment	The ICMPv4 protocol data unit carried in a fragmented IPv4 datagram.
ICMPv6_Fragment	The ICMPv6 protocol data unit carried in a fragmented IPv6 datagram.
ICMPv4_LongPing	The ICMPv4 Ping (Echo Request) protocol data unit carried in an unfragmented IPv4 datagram with its Total Length indicating a value greater than the MAX_ICMPv4_Size + size of IPv4 header.
ICMPv6_LongPing	The ICMPv6 Ping (Echo Request) protocol data unit carried in an unfragmented IPv6 datagram with its Payload Length indicating a value greater than the MAX_ICMPv6_Size.

The AutoDOS feature needs to be enabled in the configure command interface along with the set of rules that the customer would like to activate.

2.6 AutoVOIP

The Automatic Voice-Over-IP (AutoVOIP) feature detects likely VOIP streams and assigns high priority to the associated packets. The purpose is to provide better quality of service to VOIP traffic flows that are sensitive to frame delay and thus influenced by lower qualities of service. When talking on a voice-over-IP phone, a user expects to have no interruptions in the conversation and excellent voice quality. The concept is to assume that packets going to or from an IP phone vendor's equipment are likely VOIP packets, and this distinction is done based on MAC OUI field (the highest order 24 bit of the MAC Source Address). Internally, the packets with matching OUIs are assigned to traffic class (TC) of 4.

The following table lists the eight OUIs IP phone vendors which are configured for Auto VOIP by default and will be functional when AutoVOIP feature is turned on.

Table 10: Default Vendor OUIs Supported

Vendor	OUI
Siemens ag phone	00:01:E3
Avaya	00:04:0D
Cisco	00:03:6B
3COM	00:E0:BB
Polycom	00:E0:75
Pingtel	00:D0:1E
H3C	00:0F:E2
NEC	00:60:B9

2.7 AutoQoS

Automatic Quality-Of-Service (AutoQOS) feature supports changing the scheduling policy at egress, enabling flow control and setting up flood limiting for broadcast, unknown unicast and multicast streams (also known as BUM traffic). Each of these features is explained in the following sections.

2.7.1 Egress Scheduling

The UM software allows users to set an egress scheduling algorithm for each queue, on each port. Scheduling can be set to either Strict Priority (SP) or Weighted Round Robin (WRR) on each port queue.

Under strict priority, a higher numbered queue is completely served before serving other lower numbered queues. In WRR, each queue is served depending on the weights specified for each queue. The WRR defaults weights are set to 1:1:2:2:4:4:8:8 weight values corresponding to queue0 to queue7. The weights for WRR can be set in range 1 to 255. Setting a weight value of zero for any queue configures strict priority for that particular queue on the specified port.

2.7.2 Flow Control

The UM software supports 802.1x PAUSE generation on enabling the AutoQoS feature. By default, Avenger responds to PAUSE frames even without enabling any AutoQoS feature. Once the AutoQoS feature is enabled, there is a separate command to enable PAUSE generation. The Avenger generates 802.1x PAUSE frames with a SMAC of 02:00:00:00:00:00.

2.7.3 Flood Limiting

The BCM53161XU UM supports a storm control/flood limit feature using forwarding meters. This provides the ability to control the rate at which broadcast, multicast, and unknown unicast packets are received. Users can set a threshold receive rate for each of the mentioned traffic type on per port basis. If the receive rate of any of the mentioned traffic type is more than the threshold set, the excess packets are dropped.

This feature is implemented in UM as SrTCM (Single rate Three Color Marking) meters defined in RFC2697 which expects users to provide Committed Information Rate (CIR) along with Committed Burst Size (CBS) and Excess Burst Size (EBS). By default, none of the meters are configured and the user must configure a profile and add it to a meter by using config commands.

UM allows users to configure 31 different profiles and assign them to a meter for a particular traffic type on a per port basis.

2.8 Auto LoopDetect

This feature is a non-spanning tree loop detect. The purpose is to provide effectively an indication (LED) of a loop, optionally disable the port, and expect that someone else will eliminate that loop (usually manually). The process is to send a Loop Detect PDU, periodically, based on a timer.

Loopdetect PDU format:

field	width	value	description
Loop_det_da	48b	0x0900090913A6	multicast destination address
Loop_det_sa	48b	MAC	system source address
Loop_det_type	16b	0x88b7	OUI extended ethertype
Protocol ID	40b	0x000AF70001	Broadcom OUI (0x000AF7), protocol # (0x0001)

field	width	value	description
Payload	24b	0x01, egress port #	Version =0x01, egress port # (2 bytes)

The source MAC address for the loopdetect PDU should be set along with config command for enabling auto loopdetect.

2.8.1 Auto Loop Detect Configurations

Each port may be enabled to send Loop Detect PDUs. The loop detect feature may be globally enabled. The loopdetect PDUs are transmitted at the interval of "5" seconds.

2.8.2 Port Shutdown Feature

The port shutdown feature will disable the port when a loop detect PDU sourced from this device returns. The feature will re-enable the port to test if the loop is still active.The desired functionality is:

1. Detect the port with loop.

2. Shut down the loop port. Set LED to show the port with loop.

3. After X minutes, re-enable the looped port (X is initially 2 minute).

4. Check for loop again.

5. If a loop is found, goto 2 (set X to 2X (max = 1024 mins)).

6. If a loop is no longer active, re-enable looped port and return port LED to normal operation (set X to 2 min).

2.9 Auto IGMP Snooping

IGMP snooping feature allows the BCM53156XU/BCM53158XU/BCM53161XU switch to listen on IGMP traffic exchanged between routers and hosts in the network. By listening, the switch learns the multicast information and program the switch hardware with multicast groups and the ports associated with them.

2.9.1 General IGMP Snooping

By default the switch floods the multicast traffic to all the ports in the broadcast domain. IGMP snooping feature tracks the multicast routers and the hosts interested in receiving the traffic for multicast groups. It uses this learned information to program the switch to forward the traffic for a specific multicast address on the interested ports rather than broadcasting to the entire domain. The maximum number of multicast groups supported is 64.Standards

The snooping implementation is based on the IETF RFC 4541. It supports the IGMPv1, IGMPv2, and IGMPv3 protocols.

- IGMPv1 (RFC 1112): Supports processing of all IGMPv1 messages. IGMPv1 does not send the explicit Leave message; the switch software removes the group membership information when the group membership interval expires.
- IGMPv2 (RFC 2236): Supports processing of all IGMPv2 messages. For the Leave messages, instead of immediately removing the group waits for the default interval expiry.
- IGMPV3 (RFC 3376): Supports the processing of IGMV3 messages, but ignores the source addresses as the switch does not support Source Specific Multicasting (SSM). If the host is interested to receive for a multicast group coming from a specific source, the switch does not support it. Instead it allows the traffic from all the sources to the host for that multicast group.

2.9.2 Static Multicast Router Interface

This feature allows static multicast router interface configuration. When an interface is configured as multicast router interface, all the IGMP report and leave messages will be sent out on the configured interface. Unlike dynamically learned multicast router interfaces, the configured ones will never expire.

2.9.3 Block Unknown Multicast Interface

This feature allows configuring the behavior of unlearned multicast traffic. If it is configured as 1 (TRUE), it drops all unlearned multicast traffic on all the ports. By default it is zero, which allows the flooding of unlearned multicast traffic.

2.9.4 Leave Implementation

Multicast groups are not removed immediately after IGMP leave messages are received. Instead waits for the configured leave time out or the max response time in the next group specific query message from the multicast routers. Implementation uses the minimum of these two values, for removing the groups. If the leave time out is configured as zero, then the multicast group is removed immediately after the IGMP leave is received.

2.10 Cascading

UM Advanced supports cascading of two BCM53161XU chips together to increase port count. The setup works as if a single high port count switch. One Avenger is primary and another is secondary based on the strap settings. The strap setting on primary is configured to a value corresponding to cascading enabled - primary and secondary device to cascading enabled – secondary. The primary Avenger is responsible for configuring both devices and is configured to boot from the M7 from flash.

These devices are connected with a SPI interface. The hardware supports memory mapping model across this interface to facilitate using the same drivers for local and remote devices. One port from each BCM53161XU is connected to facilitate packet switching across the BCM53161XU units. Customer can also configure a static LAG across any two ports (preferably 10G interfaces) in each BCM53161XU to achieve non-blocking operation.

By default, no ports are configured for cascading.

NOTE: The avenger adds 8 byte header to the frame transmitted on cascading ports.

2.11 Cable Diagnosis

UM Advanced supports Cable diag on internal GPHY ports via Enhanced Cable Diag functionality provided in phy. The cable diag feature can be initiated either through config command or through GPIO pins.

If config command is used to run the cable diags, then cable diags will run during switch init only. It can also be executed through GPIO pins on need basis. It takes approximately two seconds to run cable diags and print the results.

The config command to run the cable diags is described under section 3.2.8.

The result from Enhanced Cable Diags can be one of the following five :
- ECD busy – ECD engine is busy, not able initiate cable diags
- ECD time out – Cable diag initiated but not completed successfully in given time.
- Invalid – Cable diag completed successfully, but result is invalid.

- Fault – Cable diag completed successfully, one/more pairs have fault.
- No Fault – Cable diag completed successfully, all 4 pairs are terminated properly.

In case of ECD busy result, the cable diag will stop running immediately. In case of any other result, the cable diag will continue to run on remaining ports.

The Fault result indicates that one/more pairs of the port have one of the following three faults:

- Open
- Intra short
- Inter short (cross talk)

NOTE: Any traffic flowing through the ports under cable diag will be disrupted for the duration of diagnostics, hence it is not recommended to run cable diags with traffic flowing.

2.12 Power-Saving Modes

The BCM53161XU offers different power savings modes for different operating states. All the power saving scheme are implemented without any external CPU requirement.

The various power savings modes are:

- **Auto Power Down mode:** This is a stand alone PHY feature which is enabled by a register bit setting. The PHY shuts off the analog portion of the circuitry when cable is not connected or the link partner power is down.
- **Energy Efficient Ethernet (EEE) mode:** Energy Efficient Ethernet is IEEE 802.1az, an extension of the IEEE 802.3 standard. IEEE defines support for the PHY to operate in Low Power Idle (LPI) mode. When enabled, this mode supports QUIET times during low link utilization, allowing the both sides of link to disable portions of each PHY's operating circuitry and save power.

NOTE: The EEE function is for the GPHY port only

2.12.1 Auto Power Down Mode

Auto Power Down mode saves PHY power consumption while the link is down. When the user enables the Auto Power Down mode through a PHY register bit setting, the PHY goes into the power savings mode automatically whenever it is in link-down state. During the Power Down state, the PHY wakes up every 2.7 or 5.4 seconds, depending on the register settings, and checks for a link signal. If no link signal is detected, then the PHY goes back to Power Down state, or the PHY wakes up and resumes the link process.

Automatic Power Down mode applies to the following conditions:

1. Cable is plugged in, but the link partner is shut down (for example, when a PC is off), so the port is in link down state.

2. Cable is unplugged, so the port is in link down state.

2.12.2 Energy Efficient Ethernet Mode

Energy Efficient Ethernet (EEE) power savings mode saves PHY power consumption while the link is up but when extended idle periods may exist between packet traffic. In EEE power savings mode PHY power consumption is scalable to the actual bandwidth utilization. The PHY can go in to "Quiet" mode (low-power idle mode) when there is no data to be transmitted. This feature is based on the latest IEEE 802.3az standard. The EEE supporting capability of the link partner is a must for this feature to work, and the discovery of the capability is during auto-negotiation through Link Layer Discovery Protocol (LLDP). This EEE feature is an embedded PHY feature and no external CPU is required.

In this mode, the MAC determines when to enter low power mode by examining the state of the transmit queues associated with each MAC. Four simple adjustments (settings) are used to trigger (optimize) the behavior of EEE control policy. These adjustments are:

- Two-part sleep delay timer
- Minimum low-power idle duration timer
- Wake transition timer

The two-way communication between the PHY and its link partner is required for the PHY to achieve the power savings on both sides. The transmit PHY sends a sleep symbol to the link partner, and the link partner enters low power state. When the transmit PHY sends a wake symbol, the regular packet transfer mode resumes.

Chapter 3: Applications and Configuration

3.1 Overview

The BCM53161XU supports unmanaged, web managed, and fully managed modes of operation. Each of these modes is discussed in more detail in the following sections.

3.2 Unmanaged Applications (UM)

UM operation is an out-of-box operation. When power is applied to the box, it will initialize and forward frames without any other configuration or external interaction. This configuration uses the integrated M7 CPU. The device automatically forwards frames after power is applied. The configuration of the system is static and completely contained within the Flash. Figure 4 provides an overview of the SKUs supported.

Figure 4: Unmanaged Applications
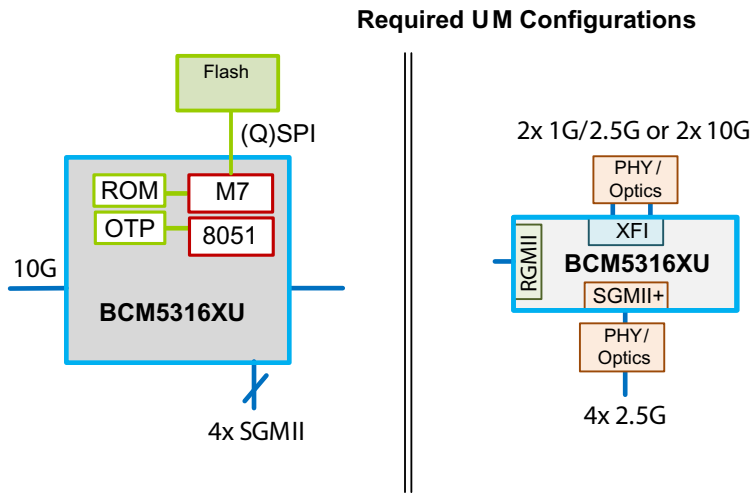
3.2.1 Unmanaged Base Configuration

The basic unmanaged configuration is the simplest possible application for BCM53161XU. In this case, only the internal PHY are used (8x1G). Figure 5 depicts the unmanaged base configuration.

Figure 5: Basic Unmanaged Configuration
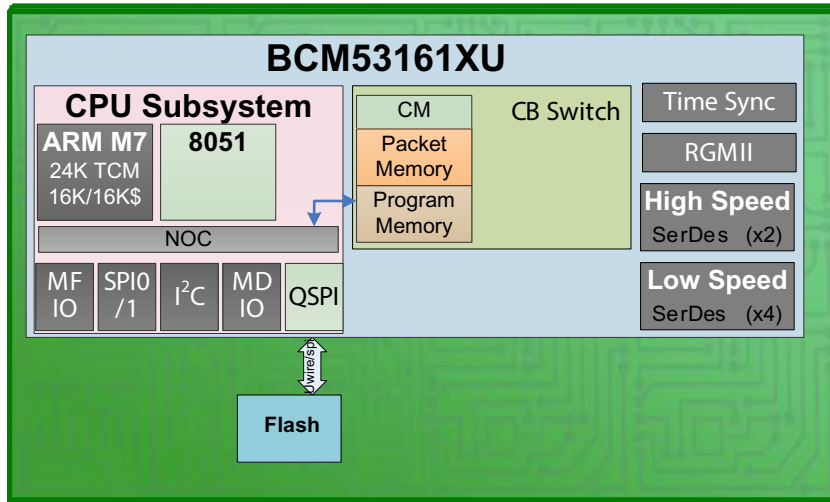
The operational processors are the internal 8051 and integrated M7 CPU. The 8051 recognizes OTP and activates the M7. AVS and the rest of the Unmanaged software is running on the M7. An external Flash is required for AVS and is also used for optional customer configuration or bug fixes. Table 11 shows the valid straps and OTP in this configuration.

Table 11: Basic Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Enabled (off)	M7_Boot_src	M7 Flash
QSMII Disabled	Enabled (off)	Enable_qspi	Disable
ARL SIZE	8K Entries	Cascading_config	Stand-alone, hardware forwarding.
LIM Disable	Enabled (off)	–	–
CFP Disable	Enabled (off)	–	–
Robo 2 switch Buffer Size[a]	512-8K PB, 8 KB 8051	–	–
RGMII Disable	Disabled (on)	–	–
GPHY Disable	Enabled (off)	–	–
1G Disable	Disabled (on)	–	–

a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

The embedded 8051 is responsible for the following features in this mode:

- Processing of straps and OTP configurations (ROM CODE)
- 8051 enters sleep mode and periodically runs link scan and error code (ROM CODE)

The integrated M7 CPU is responsible for the following features in this mode:

- AVS mechanism running (M7 Flash code)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Enabling internal PHYs (M7 Flash code)
- Enable forwarding (ROM CODE)
- Periodically runs link scan and error code (M7 Flash code)

3.2.2 Unmanaged with Advanced Features

The unmanaged applications have four value added features: AutoVOIP, AutoDOS, AutoQoS, and AutoLoopDetect. These four features require an external SPI Flash to hold the configuration and program data for the integrated M7 CPU. The following is a list of functions performed:

- Processing of straps and OTP configurations (ROM CODE)
- AVS mechanism running (M7 Flash code)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Enabling AutoVOIP, AutoDOS, and AutoQoS configuration (M7 Flash code)
- Enabling internal PHYs (M7 Flash Code)
- Enable forwarding (M7 Flash Code)
- Vectoring (executing from Flash) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash code)
- Periodically runs link scan and error code (ROM CODE)

3.2.3 High-Speed Unmanaged

The internal SerDes or external devices (PHY, PSE, etc.) require additional code space and complexity. Figure 6 on page 36 provides a sample configuration of this application with external PSE, 10G, and 1G copper PHYs.

Figure 6: High-Speed Unmanaged
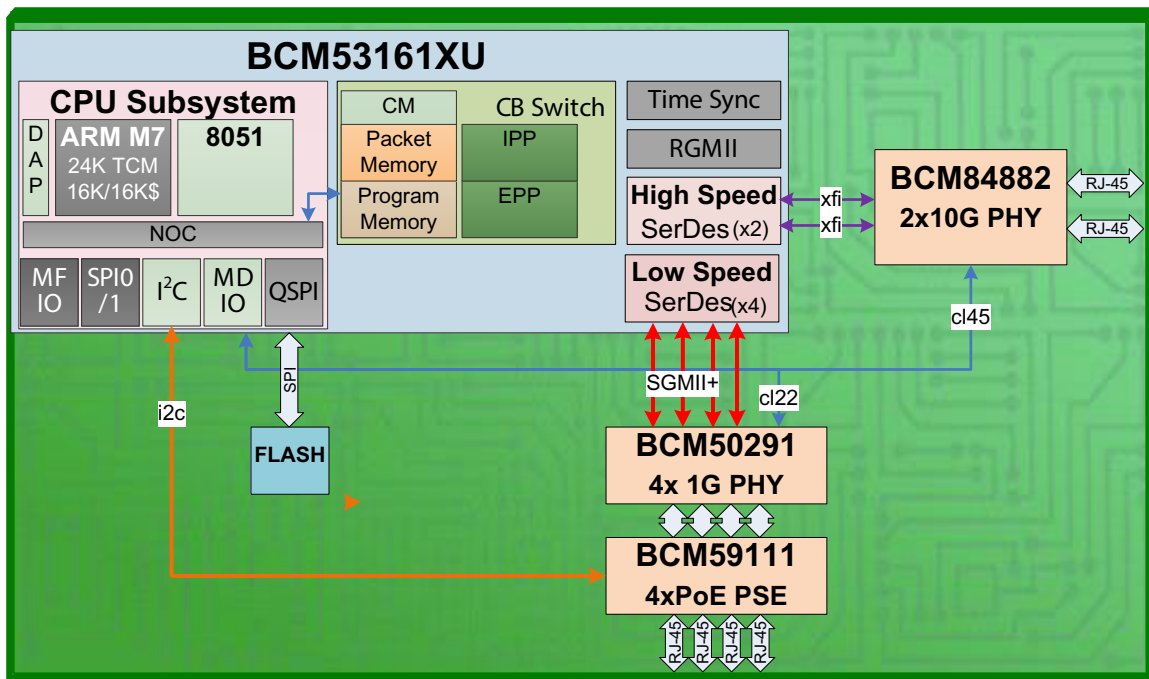
Table 12 describes the values for the valid OTP and strap settings.

Table 12: High-Speed Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Disabled (on)	M7_Boot_src	M7 Flash

Table 12: High-Speed Unmanaged OTP and Strap Configuration (Continued)

OTP Feature	Values	Strap Feature	Values
QSMII Disabled	Disabled (on)	Enable_qspi	Disable
ARL SIZE	16K Entries	Cascading_config	Stand-alone, hardware forwarding.
LIM Disable	Enabled (off)	–	–
CFP Disable	Enabled (off)	–	–
Robo 2 switch Buffer Size[a]	1 MB-8K PB, 8 KB 8051	–	–
RGMII Disable	Disabled (on)	–	–
GPHY Disable	Enabled (off)	–	–
1G Disable	Disabled (on)	–	–

    a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

In this mode, the advanced 'auto' features are also available. The M7 Flash code in this case implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash CODE)
- Configuration of the internal SerDes (M7 Flash Code)
- Configuration of external PHYs, PSE, etc. (M7 Flash Code)
- Enabling AutoVOIP, AutoDoS, AutoQoS, AutoLoopDetect configuration (M7 Flash Code)
- Play out customer specific configuration from to both internal and external devices (I^2C, MDIO) (M7 Flash Code)
- Enabling internal PHYs (M7 Flash Code)
- Enable forwarding (M7 Flash Code)
- Vectoring (executing from Flash XIP) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash Code)
- Periodically runs link scan and error code (ROM CODE)

3.2.4 Unmanaged Cascade Support

In this application, two BCM53161XU are connected together to provide more ports to the system. There are two different configurations shown. Figure 7 shows the first, which is a blocking configuration that provides 8x1G port with 2x10G external ports.

Figure 7: Unmanaged Cascade 8+2 Blocking
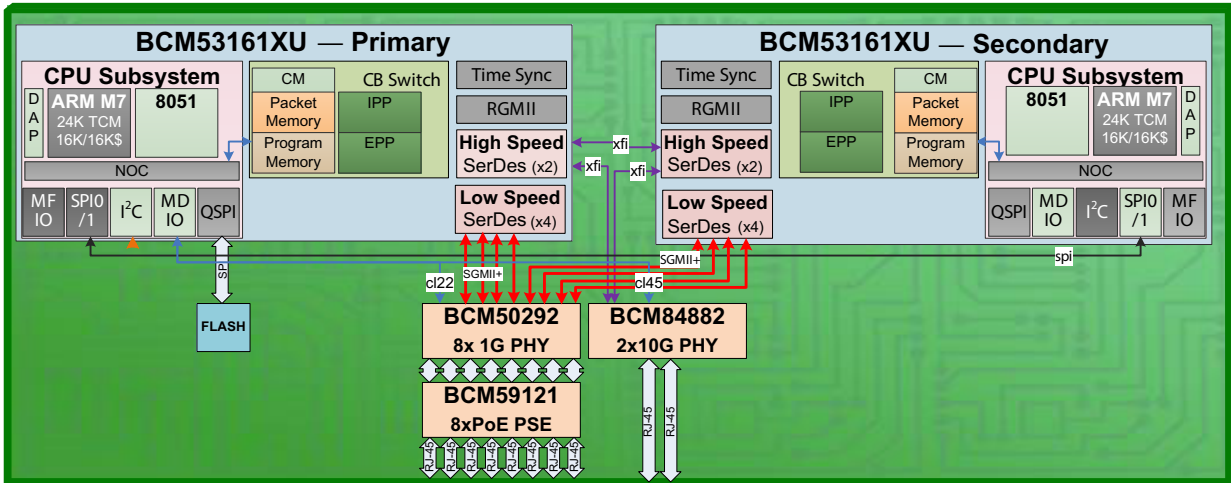
Figure 8 on page 38 has a similar configuration, except a LAG is used across the 10G interface between two BCM53161XU to achieve non-blocking operation.

Figure 8: Unmanaged Nonblocking 8G Solution
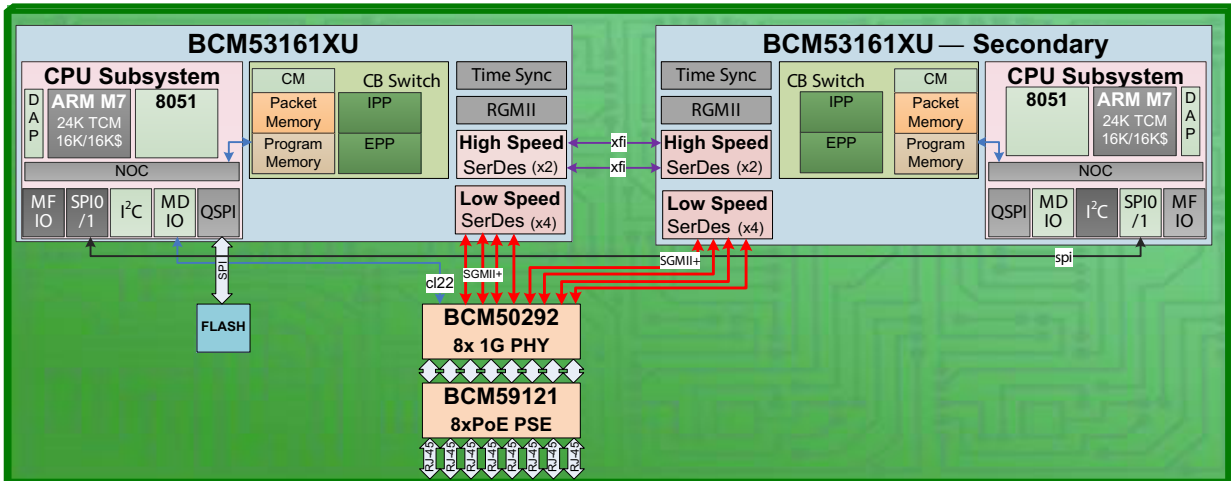
Table 13 describes the values for the valid OTP and strap settings.

Table 13: High-Speed Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Disabled (on)	Boot_src	M7 Flash
QSMII Disabled	Disabled (on)	Enable_qspi	Disable
ARL SIZE	16K Entries	Cascading_config	Primary vs Secondary
LIM Disable	Enabled (off)	–	–
CFP Disable	Enabled (off)	–	–

Table 13: High-Speed Unmanaged OTP and Strap Configuration (Continued)

OTP Feature	Values	Strap Feature	Values
Robo 2 switch Buffer Size[a]	1 MB-8K PB, 8 KB 8051	–	–
RGMII Disable	Disabled (on)	–	–
GPHY Disable	Enabled (off)	–	–
1G Disable	Disabled (on)	–	–

a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

In this mode, the advanced 'auto' features are also available. In this system, there are two BCM53161XU where one is the primary and one is the secondary based on a strapping. The primary BCM53161XU is responsible for configuring both devices. These devices are connected with an SPI interface. The hardware supports memory mapping model across this interface to facilitate using the same drivers for local and remote devices. External devices, such as PHYS and PSE are connected to the Primary BCM53161XU.

The M7 Flash code on the primary BCM53161XU implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Configuration of the SerDes on Primary (M7 Flash code)
- Configuration of cascade on Primary (M7 Flash code)
- Configuration of the SerDes on Secondary (M7 Flash code)
- Configuration of cascade on Secondary (M7 Flash code)
- Configuration of external PHYs, PSE, and so forth (M7 Flash code)
- Enabling AutoVOIP, AutoDoS, and AutoQoS configuration (M7 Flash code)
- Play out customer specific configuration from Flash to both internal and external devices (I^2C, MDIO) (M7 Flash code)
- Enable internal PHYs on Primary (M7 Flash code)
- Enable internal PHYs on Secondary this is via the MDIO on in the secondary device (M7 Flash code)
- Enable external PHYs (M7 Flash code)
- Enable forwarding on both Primary and Secondary devices (M7 Flash code)
- Vectoring (executing from flash) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash code)

The M7 on the secondary BCM53161XU device implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Identified as secondary based on straps (M7 Flash code)
- Does NOT enable PHYS or unmanaged forwarding (M7 Flash code)

Chapter 4: Software Components

This section describes on of the software components the will run on the BCM53161XU. This is not an exhaustive list.

4.1 8051 and M7 Running Environment

The operating environment is a bare metal environment. The following is list of components in the ROM environment:

Running on the 8051:

■ SKU/OTP/Strap processing (ROM) – Process straps, OTP and SKUS options.

Running on the M7:

■ AVS mechanism
■ Based device setup (ROM) – Configures PLL, clocks, and central memory.
■ Basic Unmanaged Configuration (ROM) – Configures the Robo 2 switch core for default unmanaged configuration.
■ Internal GPHY configuration (ROM) – Configures and enables GPHY ports.
■ Link scan/error handling (ROM) – handles links going up and down as well and any errors (ECC).

The following are advanced unmanaged features:

■ Advanced registered playback – Reads register play-back data from the QSPI Flash and applies it to the device and external components via MDIO and I^{2}C.
■ AutoVOIP/AutoQoS/AutoDOS – Configures these features (that is, OUI and voice VLAN) from flash.
■ AutoLoopDetect – Operation code which performs autoloopdetect feature. This runs from flash.

4.2 M7 Operating System Environment

The M7 uses an operating system environment based on OpenRTOS/FreeRTOS. The following is a list of features:

- ARM CMSIS-Driver (ARM) – Portable device driver infrastructure.

4.3 Unmanaged Application

Figure 9 shows the basic unmanaged software components.

Figure 9: Unmanaged Software Components
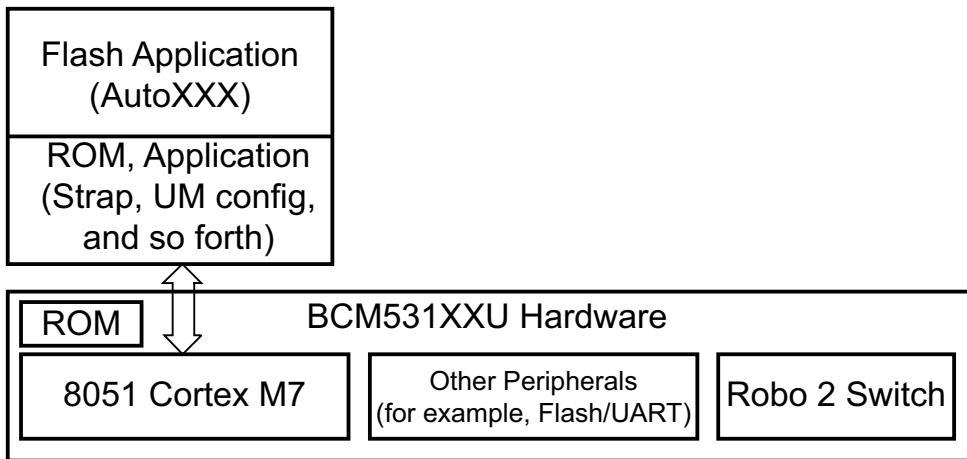
Chapter 5: System Interfaces

5.1 Overview

The BCM53161XU include the following interfaces:

- Copper Interface
- Frame Management Port Interface
- SerDes Interface
- Configuration Pins
- Programming Interfaces
- LED Interfaces
- Digital Voltage Regulator (LDO)

Each interface is discussed in detail in these sections.

5.2 Copper Interface

The internal PHYs transmit and receive data using the analog copper interface. This section discusses the following topics:

- Auto-Negotiation
- Lineside (Remote) Loopback Mode

5.2.1 Auto-Negotiation

The BCM53161XU negotiate a mode of operation over the copper media using the auto-negotiation mechanism defined in the IEEE 802.3u and IEEE 802.3ab specifications. When the auto-negotiation function is enabled, the BCM53161XU automatically choose the mode of operation by advertising its abilities and comparing them with those received from its link partner. The BCM53161XU can be configured to advertise the following modes:

- 1000BASE-T full-duplex and/or half-duplex.
- 100BASE-TX full-duplex and/or half-duplex.
- 10BASE-T full-duplex and/or half-duplex.

The transceiver negotiates with its link partner and chooses the highest common operating speed and duplex mode, commonly referred to as highest common denominator (HCD). Auto-negotiation can be disabled by software control, but is required for 1000BASE-T operation.

5.2.2 Lineside (Remote) Loopback Mode

The lineside loopback mode allows the testing of the copper interface from the link partner. This mode is enabled by setting bit 15 of the Miscellaneous Test register. The MDI receive packet is passed through the PCS and sent back out as the MDI transmit packet. The PCS receive data appears on the internal MAC interface.

5.3 Frame Management Port Interface

The dedicated frame management port provides high-speed connection to transfer management packets to an external management agent. For more information about frame management, see "Interdevice Interface" on page 15. The port is configurable to RGMII using strap pins or software configuration.

NOTE: The Frame Management port interface supports only full-duplex mode.

The BCM53161XU supports EEE features for external PHYs connected on the IMP and GMII (port5) only through the GMII interface.

5.3.1 RGMII Interface

The Reduced Gigabit Media Independent Interface (RGMII) serves as a digital data interface between the BCM53161XU and an external management entity or an external PHY to provide additional data port capacity. Transmit and receive data is clocked on the rising and falling edge of the clocks. This reduces the number of data signals crossing the MAC interface without affecting the data transmission rate. The RGMII transmits data synchronously using the TXD[3:0] and RXD[3:0] data signals. The BCM53161XU offers either 2.5V or 1.5V RGMII interface with an external device.

5.4 SerDes Interface

The BCM53161XU provides 4x SGMII + 2x XFI interfaces.

5.5 Configuration Pins

Initial configuration of the BCM53161XU takes place during power-on/reset by loading internal control values from hardware strap pins. The value of the pin is loaded when the reset sequence completes, and the pin transitions to normal operation. Pull-up or pull-down resistors can be added to these pins to control the device configuration. If the pins are left floating, the default value is determined based on the internal pull-up or pull-down configuration. See "Signal Descriptions" on page 61 for additional information.

5.6 Programming Interfaces

The BCM53161XU can be programmed using the SPI interface. The interfaces share a common pin set that is configured using the strap pin. The "SPI Interface" provides access for a general-purpose microcontroller, allowing read and write access to the internal BCM53161XU register space. It is configured to be compatible with the Motorola Serial Peripheral Interface (SPI) protocol.

An explanation follows for using the serial interface with an SPI-compatible CPU ("SPI Interface"). Either mode can be selected with the strap pin. Either mode has access to the same register space.

5.6.1 SPI Interface

One way to access the BCM53161XU internal registers is to use the SPI-compatible interface. This four-pin interface is designed to support a fully functional, bidirectional Motorola serial peripheral interface (SPI) for register read/write access. In addition, there is another SPI master for cascading configuration. The maximum speed of operation is 25 MHz.

5.6.2 SPI Slave

The SPI2 is a four-pin interface that comprises the following:
- SS2 – Slave select is used to signal start, end of transaction by the master.
- SCK2 – Slave Clock driven by Master.

- MOSI2 – Master output/slave input is used to send command, address and write data from the master. Data is received by slave one bit per clock; the endian-ness is Big endian.
- MISO2 – Master input/slave output is used to send read data from Slave. Data is sending one bit per clock, the endian-ness is Big endian.

NOTE: In the BCM53161XU, the maximum SPI slave SCK frequency can be
25 MHz when the internal clock is 400 MHz and 20 MHz when internal the clock is 200 MHz.

5.6.2.1 SPI Transactions

In the idle state, the SSN should remain high and the SCK should be low. The master driving the SSN low indicates the start of the transaction. The SSN is held low until the end of the transaction. The clock is given by the master only when the SSN is low. The MOSI is used by the master to send the command, read the address, write the address, and write Data. The MISO is used to send back read data and status from the slave.

5.6.2.1.1 Clock Polarity and Phase

Figure 10: CPOL and CPHA
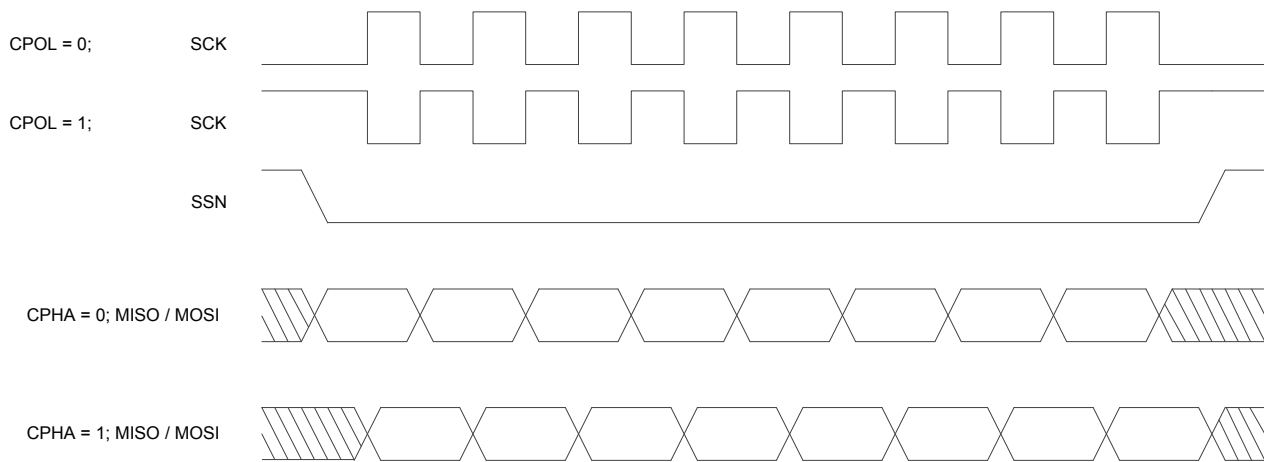
The CPOL are used to specify the base value of SCK, such as, value of SCK when in an idle state. The CPHA specifies the edges at which the data needs to be launched and captured. CPHA = 0 means transmitting data on the active to an idle state transition of SCK and capturing it on idle to active state transition. CPHA = 1 means transmitting data on the idle to active state transition of SCK and capturing it on active to idle state transition.

The SPI slave in the BCM53161XU supports mode 1 (CPOL = 0/CPHA = 1) only on the A1 version. No other combination is supported. The SCK is low when idle. Transmit data is on the positive edge and receive is on the negative edge of SCK.

The SPI slave in the BCM53161XU supports mode 1 (CPOL = 0/CPHA = 1) and mode 3 (CPOL = 1/CPHA = 1) on the B0 version. The default configuration is mode 3 support and can change to mode 1 support through a software override.

5.6.2.1.2 Fields

The following fields are used by SPI in BCM53161XU.

Table 14: Fields used in SPI

Field	No. of Bits	Description
Command	8	The command word specifies the operation to be performed.
Address	32	Address to be read/written to, given by SPI Master.
Status	16	Status of the latest Reads/Writes from SPIS. Separate status bytes are kept for reads and writes. And for overall SPI status.
Ack/Nack	8	Used only in Fast mode, to convey status of read, from SPIS.
Write Data	32x	Write Data is of variable length, but always in chunks of 32 bits as specified in the command word by the Master.
Read Data	32x	Read data will be of variable length, but always read in chunks of 32 bits from SPIS.

5.6.2.1.3 Command Word Format

Every transaction starts with the SSN going low. The first field after the SSN going low is the command. Multiple command word fields cannot exist in the same transaction. An 8-bit command word is used in the SPIS. The organization of the command word is as shown in Table 15 on page 45.

Table 15: Command Word Format

7	6	5	4	3	2	1	0
Transaction (Txn[3:0])				blen[2:0]			unused

To avoid confusion, read and write are termed as operations, while a transaction starts with SSN (active) going low and ends when the SSN goes high. A read or write operation may contain one or more transactions. The first field (in this case byte) is the command word.

5.6.2.1.4 Burst Length

Burst length is specified by the "blen" field in the command word for both read and write. Burst length is defined as follows:

```
Burst_length = blen[2:0]+1.
```

One burst equals 4 bytes. Write/read data needs to always be in multiples of 4 bytes.

5.6.2.1.5 Supported Transactions

The SPI slave supports the following transactions, encoded using txn[3:0] as shown in Table 16.

Table 16: Transactions

Transaction	Tnx 3:0	Sequence of Steps
Read Request	0	
Read "Status"	1	

Table 16: Transactions (Continued)

Transaction	Tnx 3:0	Sequence of Steps
Read "Read Data"	2	
Write Request	4	
Read "Write Status"	5	
Fastmode Read	6	
Fastmode Write	7	
Read SPI Status	8	
Clear SPI Status	9	
Reset SPIS	10	
Reset Chip	11	

The total outstanding for both read and write is eight. The burst size limit is eight. In case the SPI slave receives more than eight requests for either a read or write, all requests after the limit (eight) is reached are aborted and an error status is reported through the SPI status register.

5.6.2.1.6 SPIS and Chip Reset

Two following reset transactions are provided in SPI Slave:

- SPIS Reset – Used to reset the SPI slave. This does not look at the state of the module before resetting it.
- Chip Reset – Tis generates a chip reset request, which goes to the CRU.

5.6.2.1.7 Read/Write Status Format

Read/Write status registers are 16-bit registers implemented as 2-bits per outstanding. The maximum number of outstanding transfers in which the slave can report status is eight. This 2-bit status reported by slave is encoded as follows:

- 2'b00 – Idle
- 2'b01 – Incomplete/Transaction Ongoing
- 2'b10 – Transaction finished successfully.
- 2'b11 – Transaction finished with error.

This only indicates the transaction status. In case of an error, the master can read the SPI status register to find the cause.

Table 17: Read/Write Status Register Format

15:14	13:12	11:10	9:8	7:6	5:4	3:2	1:0
Status $_N$	Status $_{N-1}$	Status $_{N-2}$	Status $_{N-3}$	Status $_{N-4}$	Status $_{N-5}$	Status $_{N-6}$	Status $_{N-7}$

5.6.2.1.8 SPI Status

SPI status will be implemented as a 16-bit status register as shown in Table 18.

Table 18: SPI Status Register Format

Bits	Field	Description
0	wr_ovf	Indicates that write requests overflowed. BCM5315X/BCM5316X supports up to 8 outstanding requests. Outstanding in this context of write means the status of write had not been read.
1	wr_abort	Indicates a write transaction on SPI had been terminated before it is complete.
2	wr_fm_oveflow	Fast mode write request received when there are outstanding write transactions. Fast mode should only be use when there are no outstanding transactions.
3	wr_fm_abort	Fast mode transaction aborted by SPI master
4	wr_axi_slverr	Slave error from NIC. Used when the access has reached the slave successfully, but the slave wishes to return an error condition to the originating master.
5	wr_axi_decerr	Decode error from NIC. Generated, typically by an interconnect component, to indicate that there is no slave at the transaction address.
6	–	Unused
7	–	Unused
8	rd_ovf	Indicates that read requests overflowed. BCM5315X/BCM5316X supports up to 8 outstanding requests. Outstanding in this context of read means that the data had not been read.
9	rd_abort	Indicates a read request transaction on SPI had been terminated during the address phase.
10	rd_fm_oveflow	Fast mode read request received when there are outstanding write transactions. Fast mode should only be used when there are no outstanding transactions.
11	rd_fm_abort	Fast mode read transaction aborted by External master
12	rd_axi_slverr	Slave error from NIC. Used when the access has reached the slave successfully, but the slave wishes to return an error condition to the originating master
13	rd_axi_decerr	Decode error from NIC. Generated, typically by an interconnect component, to indicate that there is no slave at the transaction address.
14	–	Unused
15	–	Unused

5.6.2.1.9 ACK/NACK Byte Format

ACK/NACK bytes are used to convey the status of fast mode read and write transactions.

Table 19: ACK/NACK Byte Format

7	6	5	4	3	2	1	0
Unused (0)						txn_error	txn_done

The txn_error field is used to indicate that an error has occurred in the fast mode transaction. It is valid only if a transaction is done, that is, txn_done = 1;

5.6.2.2 SPI Slave Operation

The BCM53161XU supports the following SPI slave operations:

5.6.2.2.1 Slave Mode Normal Write

In a Normal Write operation, an 8-bit command, which specifies the operation to be performed and the size of write data in chunks of 32-bit words, is followed by 32-bit write address and write data.

Out of reset, all eight status fields in status a register are in an IDLE status. When a write request is received, the corresponding status field is updated to an INCOMPLETE status. When the write is done or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status, respectively. This status is retained until the Master reads this status, after which it is cleared to IDLE status.

The status is implemented like a shift register. Every new request would result in the status being left-shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate writes, and hence, results in the status being right-shifted by N*2(with INCOMPLETE status). In case the burst write request results in the number of outstanding transactions crossing the limit of eight, the whole write request is discarded and the write status is not updated, such as, it remains IDLE. Only the SPI status register flags the error status.

A write operation is considered finished only after the write done status is conveyed to the master. Until the status is given to the master, the status is retained in the write status register.

Figure 11: Slave Mode Normal Write

5.6.2.2.2 Slave Mode Normal Read

Out of reset, all eight status fields in the read status register are in an IDLE status. When a read request is received, the corresponding status field is updated to an INCOMPLETE status. When the read data is ready or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status respectively. This status is retained until the Master reads this status, after which it is cleared to IDLE status.

The status is implemented like a shift register. Every new request results in the status being left-shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate reads, and hence, results in the status being right-shifted by N*2(with INCOMPLETE status). In case the a burst read request results in the number of outstanding transactions crossing the limit of eight, the whole read request is discarded. The read status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

In this case, the status of the transaction is incomplete in the status field, but the data is read, and the read data given out, is incorrect. A read operation is considered finished only after the read done status is conveyed to the master and master has read the data. Until the read data is given to the master, the status is retained in the read status register.

Figure 12: Slave Mode Normal Read
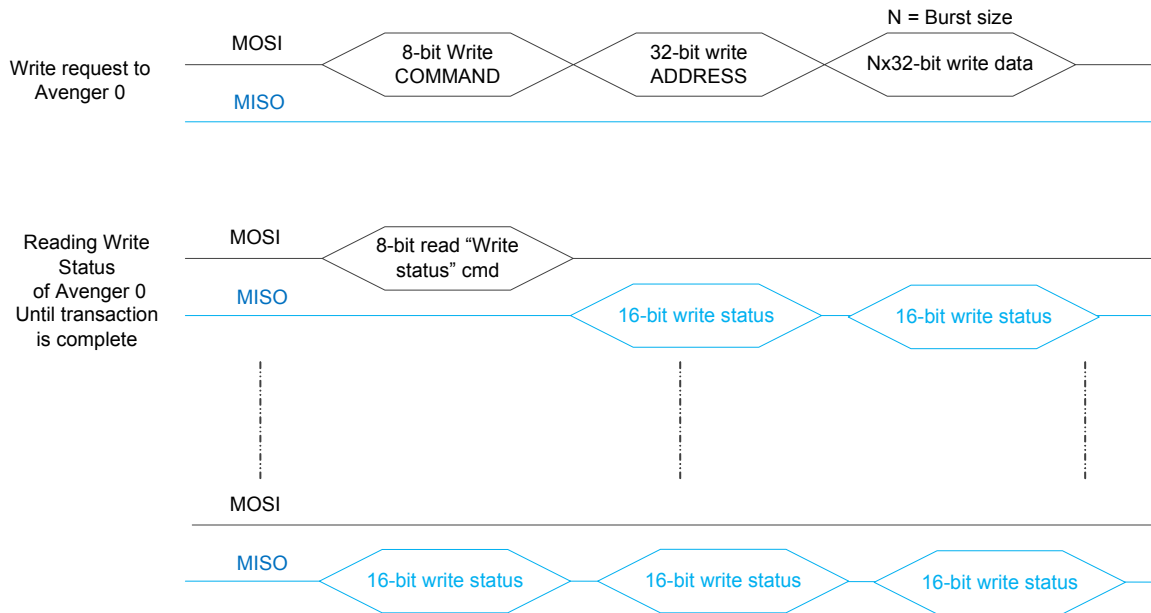
5.6.2.2.3 Slave Mode Fast Read

Fast mode (FM) read finishes in a single transaction. After the address field is sent the slave starts send NACK bytes, until the data is ready. Once the ready, it sends an ACK followed by 32-bit read data.

Fast mode does not support burst. It should not be done when there are outstanding transactions. If a fast read transaction is terminated in the middle of a transfer, the read data is lost.

This is the fastest way SPI can be used for a single read.

If a fast mode read is abandoned, the status and data are forever lost. An error is reported only using SPI status register.

Figure 13: Slave Mode Fast Read
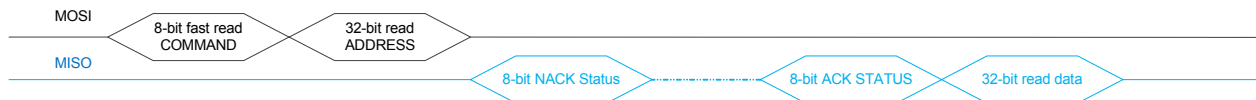
5.6.2.2.4 Slave Mode Fast Write

FM write finishes in a single transaction. After the address and 32-bit data fields are sent, the slave starts to send NACK bytes until the data is ready. Once ready, it sends ACK bytes.

Fast mode does not support burst. It should not be done when there are outstanding transactions. If a fast write transaction is terminated in the middle of a transfer, the action depends on the field being sent. If the write data is not fully received, the transaction is aborted unless the write data is received at SPI slave. The transaction happens but the status is lost.

This is the fastest way an SPI can be used for a single write.

If a fast-mode write transaction is aborted, the status is lost. The write may or may not happen on NIC based on the stage at which the transaction was aborted.

Figure 14: Slave Mode Fast Write
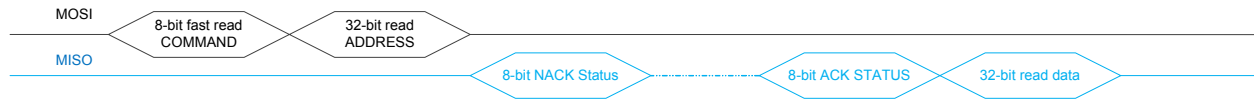
5.6.3 SPI Master

In cascaded mode, BCM53161XU_0 and BCM53161XU_1 are connected together using an SPI interface. SPI1 is an SPI Master-only interface; SPI2 is an SPI Slave-only interface. Figure 15 illustrates this scenario.

Figure 15: Block Diagram of SPI Connection for Cascading
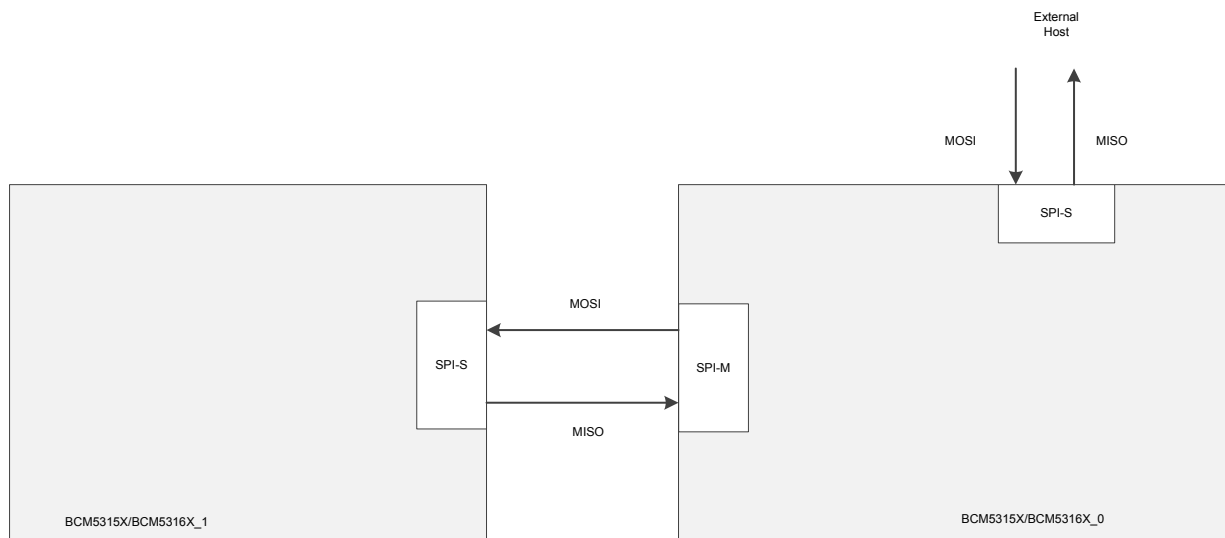
5.6.3.1 SPI Master Operation

The BCM53161XU supports the following SPI master operations:

5.6.3.1.1 Master Mode Normal Write

In a Normal Write operation, an 8-bit command, which specifies the operation to be performed and the size of write data in chunks of 32-bit words, is followed by 32-bit write address and write data.

After the write data is sent, the master may choose to start sending another set of address/data in the same transaction.

Out of reset, all eight status fields in the status register are in an IDLE status. When a write request is received, the corresponding status field is updated to an INCOMPLETE status. When the write is done or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status, respectively. This status is retained until the Master reads this status, after which it is cleared to an IDLE status.

The status is implemented like a shift register. Every new request results in the status being left shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate writes, and hence, results in status being right shifted by N*2(with INCOMPLETE status). In case the a burst write request result in the number of outstanding transactions crossing the limit of eight, the whole write request is discarded. The write status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

A write operation is considered finished only after the write done status is conveyed to the master. Until the status is given to the master, the status is retained in the write status register.

**Figure 16: Master Mode Normal Write**
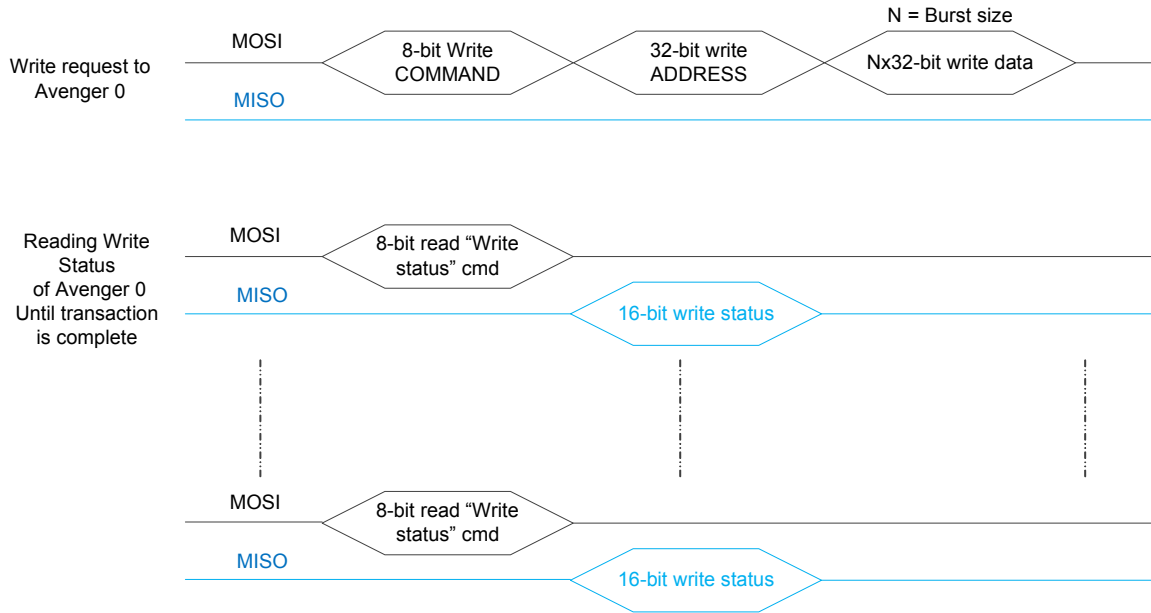
5.6.3.1.2 Master Mode Normal Read

Out of reset, all eight status fields in the read status register are in an IDLE status. When a read request is received, the corresponding status field is updated to an INCOMPLETE status. When the read data is ready or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status respectively. This status is retained until the Master reads this status, after which it is cleared to an IDLE status.

The status is implemented like a shift register. Every new request results in the status being left shifted by two (with INCOMPLETE status). A burst of length N is treated like N separate reads, and hence, results in the status being right shifted by N*2(with INCOMPLETE status). In case the a burst read request would result in the number of outstanding transactions crossing the limit of eight, the whole read request is discarded. The read status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

In case the status of the transaction is incomplete in the status field but the data is read, the read data given out is incorrect. A read operation is considered finished only after the read done status is conveyed to the master and the master has read the data. Until the read data is given to the master, the status is retained in the read status register.

If the SPI Master has the capability to detect the read status live (without delay), it can choose to continue with the read status transaction and poll for the status, or if it is known that the status is ready, the master can use the read "read status + data" transaction, which can send data in the same transaction.

Figure 17: Master Mode Normal Read
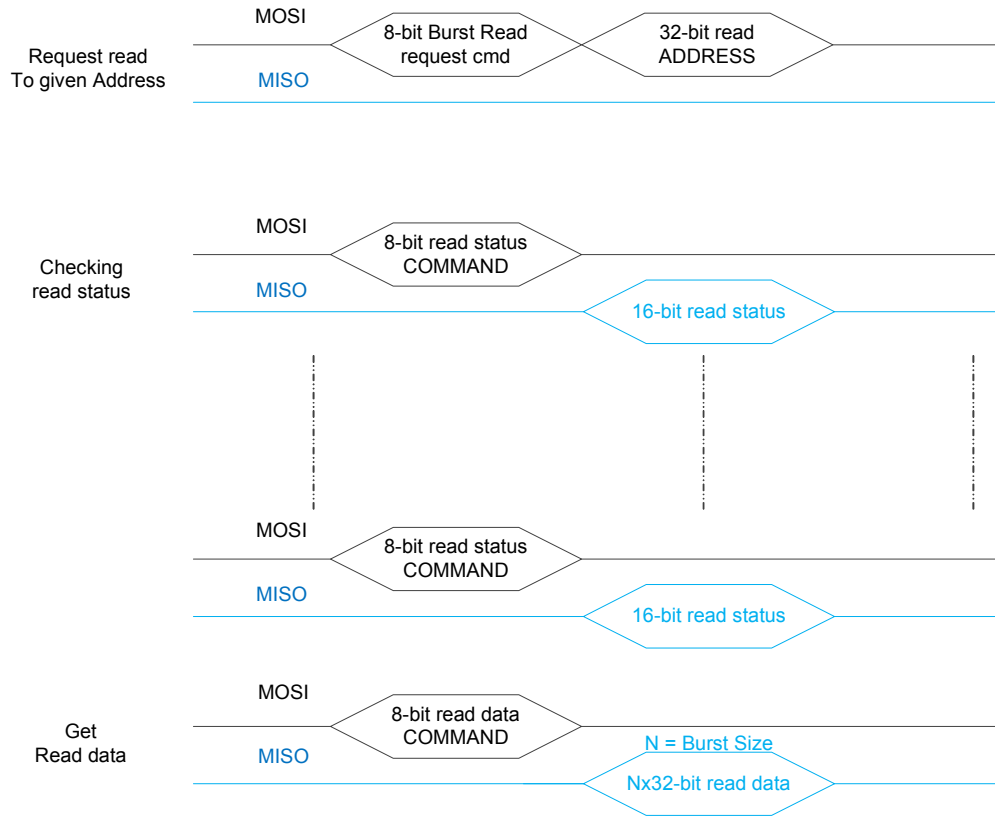
5.6.4 Quad SPI Flash Interface

The BCM53161XU offers a quad SPI interface and supports Execute in Place (XIP) as a boot source configured by a strapped option. The interface comprises six signal pins: chip select (SS), Flash clock (SCK), Data input/output (DATA0~3).

NOTE: EPROM and QSPI are both muxed in the same pins, therefore these two interfaces are exclusive.

5.6.5 MDC/MDIO Interface

The BCM53161XU offers an MDC/MDIO interface (support both CL22 and CL45) for accessing the PHY registers. The PHY registers are accessed directly by using direct PHY addresses from 0x01~0x08.

5.6.5.1 MDC/MDIO Interface Register Programming

The BCM53161XU are designed to be fully compliant with the MII clause of the IEEE 802.3u Ethernet specification. The MDC pin of the BCM53161XU sources a 2.5 MHz clock. Serial bidirectional data transmitted using the MDIO pin is synchronized with the MDC clock. Each MII read or write instruction is initiated by the BCM53161XU and contains the following:

- **Preamble (PRE)** – To signal the beginning of an MII instruction after reset, at least 32 consecutive 1-bits must be written to the MDIO pin. A preamble of 32 1-bits is required only for the first read or write following reset. A preamble of fewer than 32 1-bits causes the remainder of the instruction to be ignored.
- **Start of Frame** (**ST)** – A 01 pattern indicates that the start of the instruction follows.
- **Operation Code** (**OP**) – A read instruction is indicated by 10, while a write instruction is indicated by 01.
- **PHY Address** (**PHYAD**) – A 5-bit PHY address follows, with the MSB transmitted first. The PHY address allows a single MDIO bus to access multiple PHY chips.
- **Register Address** (**REGAD**) – A 5-bit register address follows, with the MSB transmitted first.
- **Turnaround** (**TA)** – The next bit times are used to avoid contention on the MDIO pin when a read operation is performed. When a write operation is being performed, 10 must be sent by the BCM53161XU chip during these two bit times. When a read operation is being performed, the MDIO pin of the BCM53161XU must be put in a high-impedance state during these bit times. The external PHY drives the MDIO pin to 0 during the second bit time.
- **Data** – The last 16 bits of the Instruction are the actual data bits. During a write operation, these bits are written to the MDIO pin with the most significant bit (MSB) transmitted first by the BCM53161XU. During a read operation, the data bits are driven by the external PHY with the MSB transmitted first.

Table 20 summarizes the complete management frame format.

Table 20: MII Management Frame Format

Operation	PRE	ST	OP	PHYAD	REGAD	TA	Data	Direction
Read	1 ... 1	01	10	AAAAA	RRRRR	ZZ Z0	Z ... Z D ... D	Driven by master Driven by slave
Write	1 ... 1	01	01	AAAAA	RRRRR	10	D ... D	Driven to master

Table 21: PHY MDIO Address Map

MDIO Slave	MDIO Address
GPHY0-0	1
GPHY0-1	2

Table 21: PHY MDIO Address Map (Continued)

MDIO Slave	MDIO Address
GPHY0-2	3
GPHY0-3	4
GPHY1-0	5
GPHY1-1	6
GPHY1-2	7
GPHY1-3	8
EAGLE PHY 0	9
EAGLE PHY 1	10
QSGMII/Combo PHY	11
Reserved for QSGMII	12-14

5.7 LED Interfaces

The CMICd provides two LED processors capable of retrieving status information from the ports in the device. After the status information has been retrieved and stored in the LED processor's memory, a user-created program is run that allows the LED process to build a serial bit-stream based on the LED status information. The BCM53161XU splits the task of LED managements across the two LED processors, such that LED processor 0 is responsible for all of the Warpcore®-based and UNICORE-based ports, and LED processor 1 is responsible for the two Ethernet interfaces in the iProc and the Gigabit SerDes port. Each LED processor has a two-wire (clock and data) interface to control system LEDs. Both signals are held low during periods of inactivity. A single LED refresh cycle consists of clocking out a programmable number of LED data bits. The LED data signal is pulsed high at the start of each LED refresh cycle (see Figure 18).

Figure 18: Single LED Refresh Cycle
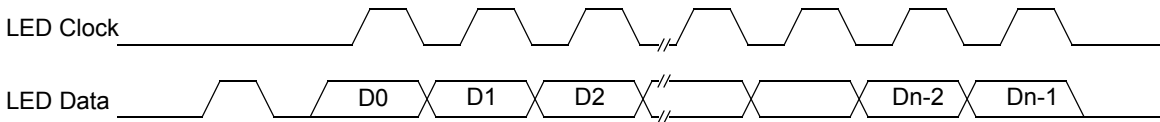
The LED refresh cycle is repeated periodically to refresh the LEDs (see).

Figure 19: LED Refresh Timing
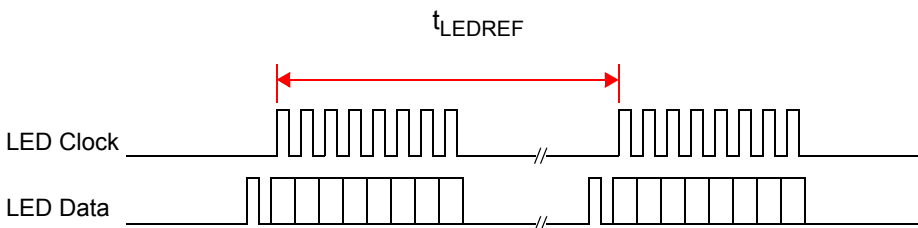
5.8 Digital Voltage Regulator (LDO)

The BCM53161XU LDO generates a 1.8V power supply. The 1.8V is used internally as an intermediate voltage level in 28 nm technology.

5.9 MFIO Interface

The BCM53161XU offers a total of 16 MFIO (Multi-Function I/O) pins. Those MFIO pins can be programmable to operate in different function modes, such UART, GPIO, and so forth.

Table 22 lists the modes of each MFIO pin.

Table 22: MFIO Interface Pins

Pins	Debug Mode	Direction	Notes	GPIO Mode	Direction	Notes	XFP Management Mode	Direction	Notes	I²C Mode	Direction
MFIO_0	uart_rxd	Input		GPIO_0	Inout	–	GPIO_0	Inout		GPIO_0	Inout
MFIO_1	uart_txd	Output		GPIO_1	Inout	–	clkout	Output	Test, debug	**SDA13**	Inout
MFIO_2	clkout	Output		GPIO_2	Inout	–	XFP0_Mod_ABS	Input	XFP0 interface signals	SDA12	Inout
MFIO_3	pwm0	Output		GPIO_3	Inout	–	XFP0_intr_n	Input		**SDA11**	Inout
MFIO_4	Reset_out	Output		GPIO_4	Inout	–	XFP0_TX_DIS	Output		SDA10	Inout
MFIO_5	pwm1	Output		GPIO_5	Inout	–	**XFP0_Mod_DeSel**	Output		SDA9	Inout
MFIO_6	pwm2	Output		GPIO_6	Inout	–	XFP0_RX_LOS	Input		SDA8	Inout
MFIO_7	pwm3	Output	Power on default (clkout can be any selected internal clock, for debug and test.)	GPIO_7	Inout	–	**XFP0_RST**	Output		SDA_gphy	Inout
MFIO_8	FRAME_SYNC_O	Output		GPIO_8	Inout	–	XFP0_Mod_NR	Input		SCL	Output
MFIO_9	FRAME_SYNC_I	Input		GPIO_9	Inout		XFP1_Mod_Desel	Output	XFP1 interface signals	**GPIO_9**	Inout
MFIO_10	GPHY_MUX_CLK1	Output		GPIO_10	Inout		**XFP1_intr_n**	Input		GPIO_10	Inout
MFIO_11	GPHY_MUX_VALID1	Output		GPIO_11	Inout	Not bonded out on smallpackage	XFP1_TX_DIS	Output		GPIO_11	Inout
MFIO_12	GPIO_12	Input		GPIO_12	Inout		XFP1_Mod_ABS	Input		GPIO_12	Inout
MFIO_13	GPIO_13	Input		GPIO_13	Inout		**XFP1_RX_LOS**	Input		GPIO_13	Inout
MFIO_14	GPIO_14	Input		GPIO_14	Inout		XFP1_RST	Output		GPIO_14	Inout
MFIO_15	GPIO_15	Input		GPIO_15	Inout		XFP1_Mod_NR	Input		GPIO_15	Inout

NOTE:

1. Each MFIO function can be selected independently using respective sel_mfio*.

2. The function of words in bold can be muxed to different functions for coexisting UART/I²C and both XFIs control signal problems as Errata description (AVR-ER 04 and AVR-ER 05) through register – CRU_CRU_MFIO_control_register_2 bit 31: MFIO_COMPATIBILITY_MODE in the B0 version.

Table 23: MFIO Muxing Function in the B0 Chip for the 19x19 mm^2 Package

Mode	MFIO_COMPATIBILITY_MODE	XFP Mode				I^{2}C Mode		
MFIO	Address: 0x40200374 Bit 31	MFIO_5	MFIO_7	MFIO_10	MFIO_13	MFIO_1	MFIO_3	MFIO_9
A0/A1	0	XFP0_Mod_DeSel	XFP0_RST	XFP1_intr_n	XFP1_RX_LOS	SDA13	SDA11	GPIO_9
B0	1	XFP1_intr_n	XFP1_RX_LOS	XFP0_Mod_DeSel	XFP0_RST	GPIO_1	SDA13	SDA11

Chapter 6: Hardware Signal Definitions

6.1 I/O Signal Types

Table 24 shows the conventions that are used to identify the I/O types. The I/O pin type is useful in referencing the DC pin characteristics.

Table 24: I/O Signal Type Definitions

Abbreviation	Description
XYZ	Active-low signal
3T	3.3V tolerant
A	Analog pin type
B	Bias pin type
CS	Continuously sampled
D	Digital pin type
DNC	Do not connect
GND	Ground
I	Input
Bi	Bidirectional
IPU	Input with internal pull-up
O3S	Tristated signal
ODO	Open-drain output
O	Output
PD	Internal pull-down
SOR	Sample on reset
PWR	Power pin supply
PU	Internal pull-up
XT	Crystal pin type

6.2 Signal Descriptions

6.2.1 19×19 mm^2 Package

Table 25: Signal Descriptions (19x19 mm^2 Package)

Signal Name	Type and Default State	Description
RESET/Clock		
RESET_L	I, Pu	**Hardware Reset Input**. Active low Schmitt-triggered input. Resets the BCM53161XU. Active low.
XTAL_P	I	**25 MHz Crystal Oscillator Input/Output.** A continuous 25 MHz reference clock must be supplied to the BCM53161XU by connecting a
XTAL_N	I	25 MHz crystal between these two pins or by driving XTALI with a clock. When using a crystal, connect a loading capacitor from each pin to external 25 MHz oscillator GND.
XTAL_CML_P	O	Positive leg of the CML Driver Output from the internal XTAL circuit. Internal debug use only.
XTAL_CML_N	O	Negative leg of the CML Driver Output from the internal XTAL circuit. Internal debug use only.
PLL_TESTP/N	O	DNC, for internal use only.
LCPLL_FREFP/N	O	DNC, for internal use only.
PLL_TVCO_[2:1]	O	DNC, for internal use only.
RGMII Interface (for port 14)		
IMP_RXCLK	In, Pd	IMPRGMII Interface Receive Clock 125 MHz for 1000 Mb/s operation, 25 MHz for 100 Mb/s operation and 2.5 MHz for 10 Mb/s operation.
IMP_RXD_0	I, Pd	IMP port RGMII Receive Data Inputs. For 1000 Mb/s operation, data bits RXD[3:0] are clocked-out on the rising edge of RXCLK, and data bits RXD[7:4] are clocked on the falling edge of RXCLK. In 10 Mb/s and 100 Mb/s modes, data bits RXD[3:0] are clocked on the rising edge of RXCLK.
IMP_RXD_1	I, Pd	
IMP_RXD_2	I, Pd	
IMP_RXD_3	I, Pd	
IMP_RXDV	I, Pd	**IMP port Receive Data Valid.** Active high. Indicates the data on the RXD[3:0] pins are encoded and transmitted. Connects to the TXEN of the external MAC/management entity.
IMP_TXCLK	O, Pd	**IMP Port RGMII Transmit Clock.** This clock is driven to synchronize the transmit data in RGMII mode (125 MHz for 1000 Mb/s operation, 25 MHz for 100 Mb/s operation, and 2.5 MHz for 10 Mb/s operation). In RGMII mode, both edges of the clock are used to align with TXD[3:0].
IMP_TXD_0	O, Pd	**IMP Port RGMII Transmit Data Output.** For 1000 Mb/s operation, data bits TXD[3:0] are clocked on the rising edge of TXCLK, and data bits TXD[7:4] are clocked on the falling edge of TXCLK. For 10 Mb/s and 100 Mb/s, data bits TXD[3:0] are clocked on the rising edge of TXCLK. These output pins have internal 25Ω series termination resistor.
IMP_TXD_1	O, Pd	
IMP_TXD_2	O, Pd	
IMP_TXD_3	O, Pd	
IMP_TXEN	O, Pd	IMP Port RGMII Transmit Enable
SGMII Interface (for ports 8, 9, 10, and 11)		
SGMII_RDN[3:1]	I	SGMII_Receive Pair
SGMII_RDP[3:1]	I	
Q_SGMII_RDN0	I	
Q_SGMII_RDN0	I	
SGMII_REFCLKN	I	Differential clock input negative leg
SGMII_REFCLKP	I	Differential clock input positive leg

Table 25: Signal Descriptions (19x19 mm² Package) (Continued)

Signal Name	Type and Default State	Description
SGMII_TDN[3:1]	O	SGMII Transmit Pair
SGMII_TDP[3:1]	O	
Q_SGMII_TDN0	O	
Q_SGMII_TDP0	O	
SGMII_TESTN	O	Differential clock output negative leg
SGMII_TESTP	O	Differential clock output positive leg
SFP		
SFP[11:8]_LOS	I	Receiver Loss of Signal
SFP[11:8]_MOD_DEF0	I	Module Definition (0)
SFP[11:8]_TX_DISABLE	O	Transmitter Disable
SFP[11:8]_TX_FAULT	I	Transmitter Fault
MDC/MDIO Interface		
MDC	Bi, Pd	**Management Data I/O.** In Master mode, this serial input/output data signal is used to read from and write to the MII registers of the external transceivers. In slave mode, it is used by an external entity to read/write to the switch registers using the pseudo-PHY. See the MDC/MDIO interface for additional information.
MDIO	Bi, Pd	**Management Data Clock.** In master mode, this 2.5 MHz clock sourced by BCM53161XU to the external PHY device. In Slave mode, it is sources by an external entity.
SPI Interfaces (SPI1 is an SPI master-only interface; SPI2 is an SPI slave-only interface.)		
SCK2 SCK1/en_eee	I, Pu O, Pu	**SPI Serial Clock.** The clock input to the BCM53161XU SPI interface is supplied by the SPI master, which supports up to 25 MHz; sck1 is used as the strap pin for EN_EEE (Energy Efficient Ethernet). ■ 1'b0 – Disable EEE feature for switch MAC ■ 1'b1 – Enable EEE feature for switch MAC (default).
SS2 SS1/swd_jtag_sel	I, Pu O, Pu	**SPI Slave Select.** Active low signal that enables an SPI interface read or write operation. SS1 is also used as the strap pin for CM7DAP operation. ■ 1'b1 – CM7DAP is in JTAG mode ■ 1'b0 – CM7DAP is in SW mode
MISO2/boot_src0 MISO1	O, Pd I, Pd	**SPI Master-In/Slave-Out**. Output signal which transmits serial data during an SPI interface read operations. MISO2 is used as the strap pin for boot source selection 1. To set the boot source, use the values below: ■ 2'b00 – Reserved ■ 2'b01 – Reserved ■ 2'b10 – M7 boot from Flash ■ 2'b11 – Boot M7 from internal memory
MOSI2 MOSI1/cascading_config1	I, Pd O, Pd	**SPI Master-Out/Slave-In.** Input signal which receives control and address information for the SPI interface, as well as serial data during write operations. MOSI1 is used as the strap pin for cascading_config1. To set the cascading_config[1:0] to below operation mode. ■ 2'b00 – Avenger standalone; hardware forwarding (unmanaged) ■ 2'b01 – Avenger cascading enabled; primary ■ 2'b10 – Avenger cascading enabled; secondary ■ 2'b11 – Avenger standalone; no hardware forwarding. **NOTE:** This signal is tristated during RESET.

Table 25: Signal Descriptions (19x19 mm^2 Package) (Continued)

Signal Name	Type and Default State	Description
JTAG Interface		
TMS	Bi	JTAG Mode Select Input.
TRST_L	Bi	**JTAG Test Reset**. Active low. Resets the JTAG controller. This signal must be pulled low during normal operation.
TCK	Bi	**JTAG Test Clock Input.** Clock Input used to synchronize JTAG control and data transfers. If unused, may be left unconnected.
TDI	Bi	**JTAG Test Data Input**. Serial data input to the JTAG TAP Controller. Sampled on the rising edge of TCK. If unused, may be left unconnected.
TDO	Bi	**JTAG Test Data Output**. Serial data output to the JTAG TAP Controller. Sampled on the rising edge of TCK. If unused, may be left unconnected.
JTCE0, JTCE1	I	JTAG Capability; select as shown below: ■ 2b'00: DFT LVTAP ■ 2b'01: AVS ■ 2b'10: 8051 debug ■ 2b'11: M7 DAP
LED Interface **NOTE:** LED_[0-7][26][27]: The LED active state is the inverse of the state of strap setting. LED_[8-25]: The LED active state are always low.)		
LED_0/xtal_bypass	O, Pd	LED_0; LED_0 is also used as the strap pin for xtal bypass configuration. ■ 1'b1 – external clock is driven in XTAL pads ■ 1'b0 – crystal is present on board to drive the XTAL pads ■ This strap goes to i_bypass pin of XTAL IP.
LED_1	O, Pd	LED1;
LED_2/xtal_freq_sel	O, Pd	LED2; LED_2 is also used as the strap pin for xtal frequency selection. ■ 1'b1 – 50 MHz XTAL clock ■ 1'b0 – 25 MHz XTAL clock
LED_3/enable_qspi	O, Pd	LED3;LED_3 is also used as the strap pin for QSPI selection. ■ 1'b1 – reserved ■ 1'b0 – QSPI is connected or no connection in SPI0
LED_4/mdio_vol_sel	O, Pd	LED4; LED_4 is also used as the strap pin for MDIO voltage selection. ■ 1'b0 – 3.3V mode MDIO ■ 1'b1 – 1.2V mode MDIO
LED_5	O, Pd	LED5;
LED_6/mdio_master	O, Pu	LED6; LED_6 is also used as the strap pin for MDIO mode selection. ■ 1'b1 – avenger is MDIO master ■ 1'b0 – avenger is MDIO slave (Partial register access) This strap pin must set to 1 for chip normal function and full register access.
LED_7/led_parallel_mode	O, Pd	LED7; LED_7 is also used as the strap pin for LED mode selection. ■ 1'b1 – LED is in parallel mode ■ 1'b0 – LED is in serial mode This strap selects led26/27 as serial led or parallel led.
LED_8	O, Pd	LED8
LED_9	O, Pd	LED9
LED_10	O, Pd	LED10
LED_11	O, Pd	LED11

Table 25: Signal Descriptions (19x19 mm^2 Package) (Continued)

Signal Name	Type and Default State	Description
LED_12	O, Pd	LED12
LED_13	O, Pd	LED13
LED_14	O, Pd	LED14
LED_15	O, Pd	LED15
LED_16	O, Pd	LED16
LED_17	O, Pd	LED17
LED_18	O, Pd	LED18
LED_19	O, Pd	LED19
LED_20	O, Pd	LED20
LED_21	O, Pd	LED21
LED_22	O, Pd	LED22
LED_23	O, Pd	LED23
LED_24	O, Pd	LED24
LED_25	O, Pd	LED25
LED_26_SCLK/ cascading_config0	O, Pd	LED_26_CLK is the LED Shift Clock. This clock is periodically active to enable LEDDATA to shift into external registers. LED_26_CLK is used as the strap pin for cascading_config0. To set the cascading_config[1:0] to below operation mode. ■ 2'b00 – Avenger stand-alone; hardware forwarding (unmanaged) ■ 2'b01 – Avenger cascading enabled; primary ■ 2'b10 – Avenger cascading enabled; secondary ■ 2'b11 – Avenger stand-alone; no hardware forwarding.
LED_27_SDATA/boot_src1	O, Pd	LED_27_SDATA is Serial LED Data Output. Serial LED data for all ports is shifted out when LEDCLK is active. LED_27_SDATA is used as the strap pin for boot source selection 1. To set the boot source, use the values below. ■ 2'b00 – Reserved ■ 2'b01 – Reserved ■ 2'b10 – M7 boot from flash ■ 2'b11 – Boot M7 from internal memory
I^{2}C Interface		
I2C_SCL	OD	BSC master clock
I2C_SDA_[13:8]	OD	BSC master data
QSPI Interface		
SS0	O	QUAD-SPI flash
DATA0	Bi	QUAD-SPI flash IO0
DATA1	BI	QUAD-SPI flash IO1
DATA2	BI	QUAD-SPI flash IO2
DATA3	BI	QUAD-SPI flash IO3
SCK0/imp_vol_sel	O, Pd	QUAD-SPI flash; SCK0 is also used as the strap pin for IMP port voltage selection. ■ 1'b0 – IMP port works at 2.5V ■ 1'b1 – IMP port works at 1.5V
XFI Interface (for port 12 and port 13)		

Table 25: Signal Descriptions (19x19 mm^2 Package) (Continued)

Signal Name	Type and Default State	Description
XFI_TDP0	O	**XFI Transmit Serial Data, Port 0.** Serial data stream signals normally connected to an optical transmitter module. Internal 100Ω differential termination. Requires external A/C coupling.
XFI_TDN0	O	
XFI_TDP1	O	**XFI Transmit Serial Data, Port 1.** Serial data stream signals normally connected to an optical transmitter module. Internal 100Ω differential termination. Requires external A/C coupling.
XFI_TDN1	O	
XFI_RDP0	I	**XFI Receive Serial Data, Port 0.** Serial data stream signals normally connected to an optical receiver module. Internally biased with internal differential 100Ω termination.
XFI_RDN0	I	
XFI_RDP1	I	**XFI Receive Serial Data, Port 1.** Serial data stream signals normally connected to an optical receiver module. Internally biased with internal differential 100Ω termination.
XFI_RDN1	I	
XFI_REFCLKP/N	I	XFI reference clock, default the 156.25 MHz reference clock of SerDes will be generated by CRU internally. It could be feed in reference clock by those pins.
XFI_TESTP/N	O	DNC; for internal use only
REXT	O	External calibration resistor must connect 4.53 kΩ resistor to GND and place as close as possible to the BGA pin.
MFIO		
MFIO[15:0]	Bi	**MultiFunctional I/O.** For multiple functions and strap pin function for these pins. See Table 22 on page 58.
Interrupt		
INTR_L	O, Pu	**Interrupt.** This interrupt pin generates an interrupt based on the configuration in the Interrupt Enable register. It can be programmed to generate based on link status change of any port, or to generate an interrupt to a CPU entity when there is a packet(s) queued in the IMP transmit queue. This signal is active low.
SyncE Interface		
SYNCE_REFCLKOUT	O	Recovered clock outputs from internal source. Can be selected from any of the switch internal cores. For details on mux selection, refer to 5315X-PG10X, CRU TS Core and CRU TS Top registers.
SYNCE_REFCLKOUT_VALID	O	Recovered clock output valid indicators.
SYNCE_RECOV_CLK [1:0]	I	Recovered clock inputs to DPLL function from external source.
SYNCE_RECOV_CLK_VALID[1:0]	I	Recovered clock inputs to DPLL function valid indicators.
SYNCIN_1588	I	Signal input be used to perform a Freq Sync with an External Source using the HW DPLL inside the Time-Sync Block of switch.
SYNCOUT_1588	O	Signal output from the Time-Sync Block that can be used for synchronization with the receiver of this signal.
NOTE: SYNCIN_1588 and SYNCOUT_1588 are used for Frequency and Phase Sync. These two pins can be used in conjunction with Frame_Sync_I(MFIO_9) and Frame_Sync_O(MFIO_8) for Phase alignment in addition to Frequency alignment, or they can be used alone (without Frame_Sync_In and Frame_Sync_Out) for freq and phase alignment but then the accuracy and convergence time of the SYNC "slave" to the SYNC "master" are lower than using SYNC + FRAME_SYNC.		

Table 25: Signal Descriptions (19x19 mm² Package) (Continued)

Signal Name	Type and Default State	Description
Mode Selection		
TESTMODE0	I	Func/Test mode select.
TESTMODE1	I	TESTMODE0 must be low for normal working mode.
TESTMODE2	I	
TESTMODE3	I	
TESTMODE4	I	
Power Interface		
VDDC_1P0	PWR, In	1.0V Digital Core Power (AVS)
VDDO_3P3	PWR, In	3.3V Digital I/O
VSS	–	GND
VDDP_1P8	PWR, In	1.8V input for intermediate state for internal use. (The output is from LDO_VOUT.)
PLL_AVDD	PWR, In	1.8V for PLL
PHY_PLL_VDD1P0_1	PWR, In	1.0V for PHY 0~3 PLL
PHY_PLL_VDD1P0_2	PWR, In	1.0V for PHY 4~7 PLL
AVDD1P0_PHY_0	PWR, In	1.0V for GPHY I/O 0~3
AVDD1P0_PHY_4	PWR, In	1.0V for GPHY I/O 4~7
AVDD3P3_PHY_0	PWR, In	3.3V for GPHY I/O 0~3
AVDD3P3_PHY_4	PWR, In	3.3V for GPHY I/O 4~7
AVDD_1P8	PWR, In	1.8V analog power
XTAL_AVDD	PWR, In	XTAL power supply 1.8V
BVDD3P3_1	PWR, In	3.3V for GPHY 0~3
BVDD3P3_2	PWR, In	3.3V for GPHY 4~7
SGMII_PVDD1P0	PWR, In	SFI Power Supply 1.0V
SGMII_RVDD1P0	PWR, In	SFI Power Supply 1.0V
SGMII_T_VDD1P0	PWR, In	SFI Power Supply 1.0V
XFI[0:1]_P_VDD1P0	PWR, In	XFI Port Power Supply 1.0V
XFI_T_R_VDD1P0	PWR, In	XFI Port Power Supply 1.0V
MDIO_VDDO	PWR, In	2.5/1.2V I/O power for MDC/MDIO
MDIO_VDDP	PWR, In	1.8/1.2V I/O VDDP doe MDC/MDIO
IMP_VDDO	PWR, In	2.5V/1.5V I/O power for IMP port
IMP_VDDP	PWR, In	1.8V/1.5V I/O VDDP for IMP port
IMP_VOL_REF	PWR, In	GND/0.75V I/O Vref for IMP port
LDO Interface		
LDO_AVDD	PWR, In	3.3V for LDO power input
LDO_VOUT	PWR, Out	1.8V output from LDO. Maximum output current 300 mA.
LDO_VSENSE	PWR, In	1.8V LDO sense in
LDO_AVSS	GND	Ground for LDO
Miscellaneous		
DNP	–	No physical ball (no solder mask)
NC	–	No Connect
PHY_RDC_[2:1]	–	6.04 kΩ resistor to GND is required.

Table 25: Signal Descriptions (19x19 mm^2 Package) (Continued)

Signal Name	Type and Default State	Description
REXT	–	External calibration resistor must connect 4.35 kΩ resistor to GND and place as close as possible to the BGA pin.
PVTMON_ADC PVTMON_DAC	O	Temperature and voltage monitor of internal analog DA/AD converter for internal use only; for internal use only. These two pins are needed to implement the AVS function for 1.0V core voltage. Refer to the Design Guide application note for more detailed information.

Chapter 7: Pin Assignment

7.1 Pin List by Pin Number (19×19 mm^2 Package)

Ball No.	Ball Name
A1	VSS
A2	NC
A3	NC
A4	I2C_SCL
A5	VSS
A6	NC
A7	NC
A8	DNP
A9	NC
A10	NC
A11	DNP
A12	NC
A13	NC
A14	DNP
A15	NC
A16	NC
A17	DNP
A18	NC
A19	NC
A20	NC
A21	NC
A22	VSS
B1	NC
B2	NC
B3	NC
B4	I2C_SDA9
B5	I2C_SDA10
B6	NC
B7	NC
B8	NC
B9	NC
B10	NC
B11	VSS
B12	NC
B13	NC
B14	VSS
B15	NC

Ball No.	Ball Name
B16	NC
B17	VSS
B18	NC
B19	NC
B20	VSS
B21	NC
B22	NC
C1	NC
C2	NC
C3	NC
C4	I2C_SDA11
C5	I2C_SDA12
C6	NC
C7	NC
C8	NC
C9	NC
C10	NC
C11	PLL_TVCO_2
C12	NC
C13	NC
C14	VSS
C15	NC
C16	NC
C17	PHY_RDC1
C18	NC
C19	NC
C20	PLL_TVCO_1
C21	NC
C22	NC
D1	VSS
D2	VSS
D3	VSS
D4	DNP
D5	DNP
D6	VSS
D7	I2C_SDA13
D8	VSS

Ball No.	Ball Name
D9	NC
D10	NC
D11	VSS
D12	NC
D13	NC
D14	VSS
D15	NC
D16	NC
D17	VSS
D18	NC
D19	NC
D20	VSS
D21	NC
D22	NC
E1	XFI_TDN0
E2	VSS
E3	XFI_RDN0
E4	VSS
E5	XFI_REFCLKN
E6	DNP
E7	I2C_SDA8
E8	VSS
E9	PHY_RDC2
E10	VSS
E11	PHY_PLL_VDD1P0_2
E12	AVDD1P0_PHY_4
E13	VSS
E14	VSS
E15	VSS
E16	VSS
E17	PHY_PLL_VDD1P0_1
E18	AVDD1P0_PHY_0
E19	NC
E20	NC
E21	NC
E22	NC

Ball No.	Ball Name
F1	XFI_TDP0
F2	VSS
F3	XFI_RDP0
F4	VSS
F5	XFI_REFCLKP
F6	VSS
F7	DNP
F8	DNP
F9	DNP
F10	DNP
F11	DNP
F12	DNP
F13	DNP
F14	DNP
F15	DNP
F16	DNP
F17	DNP
F18	VSS
F19	NC
F20	NC
F21	NC
F22	NC
G1	VSS
G2	VSS
G3	VSS
G4	VSS
G5	VSS
G6	DNP
G7	VDDC_1P0
G8	VDDC_1P0
G9	VSS
G10	BVDD3P3_2
G11	VSS
G12	VSS
G13	VDDC_1P0
G14	VDDC_1P0
G15	VSS

Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name
G16	BVDD3P3_1	J14	VSS	L12	VSS	N10	VSS
G17	DNP	J15	VSS	L13	VDDO_3P3	N11	VSS
G18	VSS	J16	AVDD3P3_PHY_0	L14	VDDO_3P3	N12	VSS
G19	VSS	J17	DNP	L15	VSS	N13	VSS
G20	VSS	J18	LED_5	L16	VSS	N14	VSS
G21	VSS	J19	LED_7	L17	DNP	N15	VSS
G22	DNP	J20	LED_6	L18	LED_14	N16	VDDC_1P0
H1	XFI_TDN1	J21	LED_8	L19	LED_15	N17	DNP
H2	VSS	J22	LED_9	L20	LED_16	N18	LED_24
H3	XFI_RDN1	K1	VSS	L21	LED_17	N19	LED_25
H4	VSS	K2	VSS	L22	LED_18	N20	VSS
H5	XFI_TESTN	K3	VSS	M1	SGMII_RDP3	N21	MFIO15
H6	DNP	K4	VSS	M2	VSS	N22	DNP
H7	VSS	K5	XFI_T_R_VDD1P0	M3	SGMII_TDP3	P1	SGMII_TDN2
H8	VSS	K6	DNP	M4	VSS	P2	VSS
H9	VSS	K7	XFI1_P_VDD1P0	M5	SGMII_REFCLKP	P3	SGMII_RDN2
H10	AVDD3P3_PHY_4	K8	VSS	M6	DNP	P4	SGMII_TESTP
H11	AVDD3P3_PHY_4	K9	VSS	M7	REXT	P5	TESTMODE_1
H12	VSS	K10	VSS	M8	VSS	P6	DNP
H13	VSS	K11	VSS	M9	VSS	P7	SGMII_P_VDD1P0
H14	VSS	K12	VSS	M10	VSS	P8	VSS
H15	VSS	K13	VSS	M11	VSS	P9	VSS
H16	AVDD3P3_PHY_0	K14	VSS	M12	VSS	P10	VSS
H17	DNP	K15	VSS	M13	VSS	P11	VSS
H18	LED_1	K16	VSS	M14	VSS	P12	VSS
H19	LED_0	K17	DNP	M15	VSS	P13	VSS
H20	LED_3	K18	LED_10	M16	VDDC_1P0	P14	VSS
H21	LED_2	K19	LED_11	M17	DNP	P15	VSS
H22	LED_4	K20	LED_12	M18	LED_19	P16	VSS
J1	XFI_TDP1	K21	LED_13	M19	LED_20	P17	DNP
J2	VSS	K22	DNP	M20	LED_21	P18	JTCE_0
J3	XFI_RDP1	L1	SGMII_RDN3	M21	LED_22	P19	INTR_L
J4	VSS	L2	VSS	M22	LED_23	P20	MFIO14
J5	XFI_TESTP	L3	SGMII_TDN3	N1	VSS	P21	MFIO13
J6	DNP	L4	VSS	N2	VSS	P22	MFIO12
J7	XFI0_P_VDD1P0	L5	SGMII_REFCLKN	N3	VSS	R1	SGMII_TDP2
J8	VSS	L6	DNP	N4	SGMII_TESTN	R2	VSS
J9	VSS	L7	VSS	N5	TESTMODE_0	R3	SGMII_RDP2
J10	VSS	L8	VSS	N6	DNP	R4	VSS
J11	VSS	L9	VDDP_1P8	N7	VSS	R5	VDDC_1P0
J12	VSS	L10	VDDC_1P0	N8	VSS	R6	DNP
J13	VSS	L11	VSS	N9	VSS	R7	VSS

Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name
R8	VSS	U6	DNP	W4	VSS	Y22	IMP_RXD3
R9	VSS	U7	DNP	W5	PLL_TESTN	AA1	Q_SGMII_TDP0
R10	VDDP_1P8	U8	DNP	W6	VSS	AA2	VSS
R11	VSS	U9	DNP	W7	LDO_VSENSE	AA3	Q_SGMII_RDN0
R12	VSS	U10	DNP	W8	PVTMON_ADC	AA4	VSS
R13	VSS	U11	DNP	W9	SFP9_TX_DISABLE	AA5	XTAL_CML_P
R14	VSS	U12	DNP	W10	SFP9_LOS	AA6	XTAL_AVDD
R15	IMP_VDDP	U13	DNP	W11	SFP9_MOD_DEF0	AA7	VSS
R16	VDDC_1P0	U14	DNP	W12	SFP10_TX_FAULT	AA8	VSS
R17	DNP	U15	DNP	W13	SFP10_TX_DISABLE	AA9	SYNCIN_1588
R18	JTCE_1	U16	DNP	W14	MDC	AA10	SYNCE_RECOV_CLK_VALID0
R19	RESET_L	U17	DNP	W15	MDIO	AA11	SYNCE_RECOV_CLK0
R20	MFIO11	U18	TDO	W16	MISO2	AA12	SYNCE_REFCLKOUT
R21	MFIO10	U19	MFIO5	W17	SS2		
R22	MFIO9	U20	MFIO4	W18	VSS		
T1	VSS	U21	MFIO3	W19	IMP_VOL_REF		
T2	SGMII_T_VDD1P0	U22	MFIO2	W20	IMP_RXD0		
T3	SGMII_R_VDD1P0	V1	SGMII_TDP1	W21	IMP_RXCLK		
T4	VSS	V2	VSS	W22	DNP		
T5	TESTMODE_2	V3	SGMII_RDN1	Y1	Q_SGMII_TDN0		
T6	DNP	V4	VSS	Y2	VSS		
T7	TESTMODE_3	V5	LCPLL_FREFP	Y3	VSS		
T8	PLL_AVDD	V6	VSS	Y4	VSS		
T9	TESTMODE_4	V7	LDO_AVDD	Y5	PLL_TESTP		
T10	VSS	V8	LDO_VOUT	Y6	VSS		
T11	VDDC_1P0	V9	SFP8_TX_FAULT	Y7	VSS		
T12	VDDC_1P0	V10	SFP8_TX_DISABLE	Y8	PVTMON_DAC		
T13	VDDC_1P0	V11	SFP8_LOS	Y9	SFP10_LOS		
T14	VDDC_1P0	V12	SFP8_MOD_DEF0	Y10	SFP10_MOD_DEF0		
T15	IMP_VDDO	V13	SFP9_TX_FAULT	Y11	SFP11_TX_FAULT		
T16	VDDC_1P0	V14	MDIO_VDDP	Y12	SYNCE_REFCLKOUT_VALID		
T17	DNP	V15	MDIO_VDDO	Y13	SFP11_TX_DISABLE		
T18	TDI	V16	SCK2	Y14	VSS		
T19	MFIO8	V17	MOSI2	Y15	DATA3		
T20	MFIO7	V18	TCK	Y16	DATA2		
T21	MFIO6	V19	TRST_L	Y17	MISO1		
T22	DNP	V20	TMS	Y18	SS1		
U1	SGMII_TDN1	V21	MFIO1	Y19	IMP_RXDV		
U2	VSS	V22	MFIO0	Y20	IMP_RXD1		
U3	VSS	W1	VSS	Y21	IMP_RXD2		
U4	VSS	W2	VSS				
U5	LCPLL_FREFN	W3	SGMII_RDP1				

Ball No.	Ball Name		Ball No.	Ball Name		Ball No.	Ball Name
AA13	SFP11_LOS		AB4	VSS		AB16	DNP
AA14	SFP11_MOD_DEF0		AB5	XTAL_CML_N		AB17	SCK1
AA15	DATA1		AB6	XTALN		AB18	LED_27_SDATA
AA16	SS0		AB7	XTALP		AB19	DNP
AA17	MOSI1		AB8	VSS		AB20	IMP_TXD0
AA18	LED_26_SCLK		AB9	SYNCOUT_1588		AB21	IMP_TXD2
AA19	IMP_TXEN		AB10	DNP		AB22	VSS
AA20	IMP_TXD1		AB11	SYNCE_RECOV_CLK1			
AA21	IMP_TXD3		AB12	SYNCE_RECOV_CLK_VALID1			
AA22	IMP_TXCLK		AB13	DNP			
AB1	VSS		AB14	SCK0			
AB2	VSS		AB15	DATA0			
AB3	Q_SGMII_RDP0						

7.2 Pin List by Pin Name (19×19 mm² Package)

Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name
E18	AVDD1P0_PHY_0	L17	DNP	Y22	IMP_RXD3	H22	LED_4
E12	AVDD1P0_PHY_4	M6	DNP	Y19	IMP_RXDV	J18	LED_5
H16	AVDD3P3_PHY_0	M17	DNP	AA22	IMP_TXCLK	J20	LED_6
J16	AVDD3P3_PHY_0	N6	DNP	AB20	IMP_TXD0	J19	LED_7
H10	AVDD3P3_PHY_4	N17	DNP	AA20	IMP_TXD1	J21	LED_8
H11	AVDD3P3_PHY_4	N22	DNP	AB21	IMP_TXD2	J22	LED_9
G16	BVDD3P3_1	P6	DNP	AA21	IMP_TXD3	W14	MDC
G10	BVDD3P3_2	P17	DNP	AA19	IMP_TXEN	W15	MDIO
AB15	DATA0	R6	DNP	T15	IMP_VDDO	V15	MDIO_VDDO
AA15	DATA1	R17	DNP	R15	IMP_VDDP	V14	MDIO_VDDP
Y16	DATA2	T6	DNP	W19	IMP_VOL_REF	V22	MFIO0
Y15	DATA3	T17	DNP	P19	INTR_L	V21	MFIO1
A8	DNP	T22	DNP	P18	JTCE_0	R21	MFIO10
A11	DNP	U6	DNP	R18	JTCE_1	R20	MFIO11
A14	DNP	U7	DNP	U5	LCPLL_FREFN	P22	MFIO12
A17	DNP	U8	DNP	V5	LCPLL_FREFP	P21	MFIO13
D4	DNP	U9	DNP	V7	LDO_AVDD	P20	MFIO14
D5	DNP	U10	DNP	V8	LDO_VOUT	N21	MFIO15
E6	DNP	U11	DNP	W7	LDO_VSENSE	U22	MFIO2
F7	DNP	U12	DNP	H19	LED_0	U21	MFIO3
F8	DNP	U13	DNP	H18	LED_1	U20	MFIO4
F9	DNP	U14	DNP	K18	LED_10	U19	MFIO5
F10	DNP	U15	DNP	K19	LED_11	T21	MFIO6
F11	DNP	U16	DNP	K20	LED_12	T20	MFIO7
F12	DNP	U17	DNP	K21	LED_13	T19	MFIO8
F13	DNP	W22	DNP	L18	LED_14	R22	MFIO9
F14	DNP	AB10	DNP	L19	LED_15	Y17	MISO1
F15	DNP	AB13	DNP	L20	LED_16	W16	MISO2
F16	DNP	AB16	DNP	L21	LED_17	AA17	MOSI1
F17	DNP	AB19	DNP	L22	LED_18	V17	MOSI2
G6	DNP	A4	I2C_SCL	M18	LED_19	E17	PHY_PLL_VDD1P0_1
G17	DNP	B5	I2C_SDA10	H21	LED_2	E11	PHY_PLL_VDD1P0_2
G22	DNP	C4	I2C_SDA11	M19	LED_20		
H6	DNP	C5	I2C_SDA12	M20	LED_21	C17	PHY_RDC1
H17	DNP	D7	I2C_SDA13	M21	LED_22	E9	PHY_RDC2
J6	DNP	E7	I2C_SDA8	M22	LED_23	T8	PLL_AVDD
J17	DNP	B4	I2C_SDA9	N18	LED_24	W5	PLL_TESTN
K6	DNP	W21	IMP_RXCLK	N19	LED_25	Y5	PLL_TESTP
K17	DNP	W20	IMP_RXD0	AA18	LED_26_SCLK	C20	PLL_TVCO_1
K22	DNP	Y20	IMP_RXD1	AB18	LED_27_SDATA	C11	PLL_TVCO_2
L6	DNP	Y21	IMP_RXD2	H20	LED_3	W8	PVTMON_ADC

Ball No.	Ball Name
Y8	PVTMON_DAC
AA3	Q_SGMII_RDN0
AB3	Q_SGMII_RDP0
Y1	Q_SGMII_TDN0
AA1	Q_SGMII_TDP0
R19	RESET_L
M7	REXT
AB14	SCK0
AB17	SCK1
V16	SCK2
Y9	SFP10_LOS
Y10	SFP10_MOD_DEF0
W13	SFP10_TX_DISABLE
W12	SFP10_TX_FAULT
AA13	SFP11_LOS
AA14	SFP11_MOD_DEF0
Y13	SFP11_TX_DISABLE
Y11	SFP11_TX_FAULT
V11	SFP8_LOS
V12	SFP8_MOD_DEF0
V10	SFP8_TX_DISABLE
V9	SFP8_TX_FAULT
W10	SFP9_LOS
W11	SFP9_MOD_DEF0
W9	SFP9_TX_DISABLE
V13	SFP9_TX_FAULT
P7	SGMII_P_VDD1P0
T3	SGMII_R_VDD1P0
V3	SGMII_RDN1
P3	SGMII_RDN2
L1	SGMII_RDN3
W3	SGMII_RDP1
R3	SGMII_RDP2
M1	SGMII_RDP3
L5	SGMII_REFCLKN
M5	SGMII_REFCLKP
T2	SGMII_T_VDD1P0
U1	SGMII_TDN1
P1	SGMII_TDN2

Ball No.	Ball Name
L3	SGMII_TDN3
V1	SGMII_TDP1
R1	SGMII_TDP2
M3	SGMII_TDP3
N4	SGMII_TESTN
P4	SGMII_TESTP
AA16	SS0
Y18	SS1
W17	SS2
AA10	SYNCE_RECOV_CLK_VALID0
AB12	SYNCE_RECOV_CLK_VALID1
AA11	SYNCE_RECOV_CLK0
AB11	SYNCE_RECOV_CLK1
AA12	SYNCE_REFCLKOUT
Y12	SYNCE_REFCLKOUT_VALID
AA9	SYNCIN_1588
AB9	SYNCOUT_1588
V18	TCK
T18	TDI
A15	NC
B15	NC
C15	NC
D15	NC
D18	NC
C18	NC
B18	NC
A18	NC
A20	NC
B21	NC
C21	NC
D21	NC
F22	NC
E21	NC
E20	NC
E19	NC
B3	NC
C1	NC
B1	NC

Ball No.	Ball Name
A3	NC
A6	NC
B6	NC
C6	NC
C8	NC
D9	NC
C9	NC
B9	NC
A9	NC
A12	NC
B12	NC
C12	NC
D12	NC
U18	TDO
A16	NC
B16	NC
C16	NC
D16	NC
D19	NC
C19	NC
B19	NC
A19	NC
A21	NC
B22	NC
C22	NC
D22	NC
E22	NC
F21	NC
F20	NC
F19	NC
C3	NC
C2	NC
B2	NC
A2	NC
A7	NC
B7	NC
C7	NC
B8	NC
D10	NC
C10	NC
B10	NC
A10	NC

Ball No.	Ball Name
A13	NC
B13	NC
C13	NC
D13	NC
N5	TESTMODE_0
P5	TESTMODE_1
T5	TESTMODE_2
T7	TESTMODE_3
T9	TESTMODE_4
V20	TMS
V19	TRST_L
G7	VDDC_1P0
G8	VDDC_1P0
G13	VDDC_1P0
G14	VDDC_1P0
L10	VDDC_1P0
M16	VDDC_1P0
N16	VDDC_1P0
R5	VDDC_1P0
R16	VDDC_1P0
T11	VDDC_1P0
T12	VDDC_1P0
T13	VDDC_1P0
T14	VDDC_1P0
T16	VDDC_1P0
L13	VDDO_3P3
L14	VDDO_3P3
L9	VDDP_1P8
R10	VDDP_1P8
A1	VSS
A5	VSS
A22	VSS
B11	VSS
B14	VSS
B17	VSS
B20	VSS
C14	VSS
D1	VSS
D2	VSS
D3	VSS
D6	VSS
D8	VSS

Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name	Ball No.	Ball Name
D11	VSS	J10	VSS	N3	VSS	R11	VSS
D14	VSS	J11	VSS	N7	VSS	R12	VSS
D17	VSS	J12	VSS	N8	VSS	R13	VSS
D20	VSS	J13	VSS	N9	VSS	R14	VSS
E2	VSS	J14	VSS	N10	VSS	T1	VSS
E4	VSS	J15	VSS	N11	VSS	T4	VSS
E8	VSS	K1	VSS	N12	VSS	T10	VSS
E10	VSS	K2	VSS	N13	VSS	U2	VSS
E13	VSS	K3	VSS	N14	VSS	U3	VSS
E14	VSS	K4	VSS	N15	VSS	U4	VSS
E15	VSS	K8	VSS	N20	VSS	V2	VSS
E16	VSS	K9	VSS	P2	VSS	V4	VSS
F2	VSS	K10	VSS	P8	VSS	V6	VSS
F4	VSS	K11	VSS	P9	VSS	W1	VSS
F6	VSS	K12	VSS	P10	VSS	W2	VSS
F18	VSS	K13	VSS	P11	VSS	W4	VSS
G1	VSS	K14	VSS	P12	VSS	W6	VSS
G2	VSS	K15	VSS	P13	VSS	W18	VSS
G3	VSS	K16	VSS	P14	VSS	Y2	VSS
G4	VSS	L2	VSS	P15	VSS	Y3	VSS
G5	VSS	L4	VSS	P16	VSS	Y4	VSS
G9	VSS	L7	VSS	R2	VSS	Y6	VSS
G11	VSS	L8	VSS	R4	VSS	Y7	VSS
G12	VSS	L11	VSS	R7	VSS	Y14	VSS
G15	VSS	L12	VSS	R8	VSS	AA2	VSS
G18	VSS	L15	VSS	R9	VSS	AA4	VSS
G19	VSS	L16	VSS				
G20	VSS	M2	VSS				
G21	VSS	M4	VSS				
H2	VSS	M8	VSS				
H4	VSS	M9	VSS				
H7	VSS	M10	VSS				
H8	VSS	M11	VSS				
H9	VSS	M12	VSS				
H12	VSS	M13	VSS				
H13	VSS	M14	VSS				
H14	VSS	M15	VSS				
H15	VSS	N1	VSS				
J2	VSS	N2	VSS				
J4	VSS						
J8	VSS						
J9	VSS						

Ball No.	Ball Name
AA7	VSS
AA8	VSS
AB1	VSS
AB2	VSS
AB4	VSS
AB8	VSS
AB22	VSS
E3	XFI_RDN0
H3	XFI_RDN1
F3	XFI_RDP0
J3	XFI_RDP1
E5	XFI_REFCLKN
F5	XFI_REFCLKP
K5	XFI_T_R_VDD1P0
E1	XFI_TDN0
H1	XFI_TDN1
F1	XFI_TDP0
J1	XFI_TDP1
H5	XFI_TESTN
J5	XFI_TESTP
J7	XFI0_P_VDD1P0
K7	XFI1_P_VDD1P0
AA6	XTAL_AVDD
AB5	XTAL_CML_N
AA5	XTAL_CML_P
AB6	XTALN
AB7	XTALP

7.3 Ball Map (19×19 mm^2 Package)

Figure 20: Ball Map (19×19 mm^2 Package)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	
A	VSS	NC	NC	I2C_SCL	VSS	NC	NC	DNP	NC	NC	DNP	NC	NC	DNP	NC	NC	DNP	NC	NC	NC	NC	VSS	A
B	NC	NC	NC	I2C_SDA9	I2C_SDA10	NC	NC	NC	NC	NC	VSS	NC	NC	VSS	NC	NC	VSS	NC	NC	VSS	NC	NC	B
C	NC	NC	NC	I2C_SDA11	I2C_SDA12	NC	NC	NC	NC	NC	PLL_TVCO_2	NC	NC	VSS	NC	NC	PHY_RDC1	NC	NC	PLL_TVCO_1	NC	NC	C
D	VSS	VSS	VSS	DNP	DNP	VSS	I2C_SDA13	VSS	NC	NC	VSS	NC	NC	VSS	NC	NC	VSS	NC	NC	VSS	NC	NC	D
E	XFI_TDN0	VSS	XFI_RDN0	VSS	XFI_REFCLKN	DNP	I2C_SDA8	VSS	PHY_RDC2	VSS	PHY_PLL_VDD1P0_2	AVDD1P0_PHY_4	VSS	VSS	VSS	VSS	PHY_PLL_VDD1P0_1	AVDD1P0_PHY_0	NC	NC	NC	NC	E
F	XFI_TDP0	VSS	XFI_RDP0	VSS	XFI_REFCLKP	VSS	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	VSS	NC	NC	NC	NC	F
G	VSS	VSS	VSS	VSS	VSS	DNP	VDDC_1P0	VDDC_1P0	VSS	BVDD3P3_2	VSS	VSS	VDDC_1P0	VDDC_1P0	VSS	BVDD3P3_1	DNP	VSS	VSS	VSS	VSS	DNP	G
H	XFI_TDN1	VSS	XFI_RDN1	VSS	XFI_TESTN	DNP	VSS	VSS	VSS	AVDD3P3_PHY_4	AVDD3P3_PHY_4	VSS	VSS	VSS		AVDD3P3_PHY_0	DNP	LED_1	LED_0	LED_3	LED_2	LED_4	H
J	XFI_TDP1	VSS	XFI_RDP1	VSS	XFI_TESTP	DNP	XFI0_P_VDD1P0	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	AVDD3P3_PHY_0	DNP	LED_5	LED_7	LED_6	LED_8	LED_9	J
K	VSS	VSS	VSS	XFI_T_R_VDD1P0	DNP		XFI1_P_VDD1P0	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	DNP	LED_10	LED_11	LED_12	LED_13	DNP	K
L	SGMII_RDN3	VSS	SGMII_TDN3	VSS	SGMII_REFCLKN	DNP	VSS	VSS	VDDP_1P8	VDDC_1P0	VSS	VDDO_3P3	VDDO_3P3	VSS	VSS	VSS	DNP	LED_14	LED_15	LED_16	LED_17	LED_18	L
M	SGMII_RDP3	VSS	SGMII_TDP3	VSS	SGMII_REFCLKP	DNP	REXT	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VDDC_1P0	VSS	DNP	LED_19	LED_20	LED_21	LED_22	LED_23	M
N	VSS	VSS	VSS	SGMII_TESTN	TESTMODE_0	DNP	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VDDC_1P0	VSS	DNP	LED_24	LED_25	VSS	MFIO15	DNP	N
P	SGMII_TDN2	VSS	SGMII_RDN2	SGMII_TESTP	TESTMODE_1	DNP	SGMII_P_VDD1P0	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	DNP	JTCE_0	INTR_L	MFIO14	MFIO13	MFIO12	P
R	SGMII_TDP2	VSS	SGMII_RDP2	VSS	VDDC_1P0	DNP	VSS	VSS	VSS	VDDP_1P8	VSS	VSS	VSS	VSS	IMP_VDDP	VDDC_1P0	DNP	JTCE_1	RESET_L	MFIO11	MFIO10	MFIO9	R
T	VSS	SGMII_T_VDD1P0	SGMII_R_VDD1P0	VSS	TESTMODE_2	DNP	TESTMODE_3	PLL_AVDD	TESTMODE_4	VSS	VDDC_1P0	VDDC_1P0	VDDC_1P0	VDDC_1P0	IMP_VDDO	VDDC_1P0	DNP	TDI	MFIO8	MFIO7	MFIO6	DNP	T
U	SGMII_TESTN1	VSS	VSS	VSS	LCPLL_FREFN	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	TDO	MFIO5	MFIO4	MFIO3	MFIO2	U
V	SGMII_TDP1	VSS	SGMII_RDN1	VSS	LCPLL_FREFP	VSS	LDO_AVDD	LDO_VOUT	SFP8_TX_FAULT	SFP8_TX_DISABLE	SFP8_LOS	SFP8_MOD_DEF0	SFP9_TX_FAULT	MDIO_VDDP	MDIO_VDDO	SCK2	MOSI2	TCK	TRST_L	TMS	MFIO1	MFIO0	V
W	VSS	VSS	SGMII_RDP1	VSS	PLL_TESTN	VSS	LDO_VSENSE	PVTMON_ADC	SFP9_TX_DISABLE	SFP9_LOS	SFP9_MOD_DEF0	SFP10_TX_FAULT	SFP10_TX_DISABLE	MDC	MDIO	MISO2	SS2	VSS	IMP_VOL_REF	IMP_RXD0	IMP_RXCLK	DNP	W
Y	Q_SGMII_TDN0	VSS	VSS	VSS	PLL_TESTP	VSS	VSS	PVTMON_DAC	SFP10_LOS	SFP10_MOD_DEF0	SFP11_TX_FAULT	SYNCE_REFCLK_OUT_VALID	SFP11_TX_DISABLE	VSS	DATA3	DATA2	MISO1	SS1	IMP_RXDV	IMP_RXD1	IMP_RXD2	IMP_RXD3	Y
AA	Q_SGMII_TDP0	VSS	Q_SGMII_RDN0	VSS	XTAL_CMP_P	XTAL_AVDD	VSS	VSS	SYNCIN_1588	SYNCE_RECOV_CLK_VALID	SYNCE_REFCLK0	SYNCE_REFCLK_OUT	SFP11_LOS	SFP11_MOD_DEF0	DATA1	SS0	MOSI1	LED_26_SCLK	IMP_TXEN	IMP_TXD1	IMP_TXD3	IMP_TXCLK	AA
AB	VSS	VSS	Q_SGMII_RDP0	VSS	XTAL_CMP_N	XTALN	XTALP	VSS	SYNCOUT_1588	DNP	SYNCE_RECOV_CLK1	SYNCE_RECOV_CLK_VALID	DNP	DATA0	DNP	SCK1	LED_27_SDATA	DNP	IMP_TXD0	IMP_TXD2	VSS		AB
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	

Chapter 8: Electrical Characteristics

8.1 Absolute Maximum Ratings

Table 26: Absolute Maximum Ratings[a]

Parameter	Symbol	Min.	Max.	Unit
3.3V Supply Voltage	VDDO_3P3, AVDD3P3_PHY0, AVDD3P3_PHY1 AVDD3P3_PHY2, AVDD3P3_PHY3, BVDD3P3 LDO_AVDD, MDIO_VDDO[b]	–0.5	+3.63	V
2.5V Supply Voltage	RGMII_VDDO[c]	–0.5	+2.75	V
1.5V Supply Voltage	RGMII_VDDO[c], RGMII_VDDP[c]	–0.5	+1.65	V
1.8V Supply Voltage	VDDP_1P8, OTP_VDD, AVDD_PVTMON, PLL_VDD1P8, XTAL_VDD1P8, UPI_VDD18 UPI_VDD18_int RGMII_VDDP[c], MDIO_VDDP[b]	–0.5	+1.98	V
1.2V Supply Voltage	DDR_VDDO, DDR_VDDO_CK MDIO_VDDO[b],MDIO_VDDP[b]	–0.5	+1.32	V
1.0V Supply Voltage	VDDC_1P0, AVDD0P9_PHY0, AVDD0P9_PHY1 AVDD0P9_PHY2, AVDD0P9_PHY3, PHYPLL_VDD0P9, QSGMII_P_R_VDD1P0 QSGMII_T_VDD1P0, XFI_P_R_VDD1P0 XFI_T_VDD1P0, RESCAL_pad_i_VDD1p0	–0.5	+1.1	V
Maximum Junction Temperature	T_{J_MAX}	–	+110	°C
Commercial Ambient Temperature (Operating)	T_A	0	+70	°C
Industrial Ambient Temperature (Operating)	T_A	–40	+85	°C
Operating Humidity	–	–	+85	%
Storage Temperature	T_{STG}	–40	+125	°C
Storage Humidity	–	–	60	%

a. These specifications indicate levels where permanent damage to the device may occur. Functional operation is not guaranteed under these conditions. Operation at maximum conditions for extended periods may adversely affect long-term reliability of the device.

b. MDC/MDIO for 3.3V/1.2V.

c. RGMII interface for 2.5V/1.5V.

8.2 Recommended Operating Conditions and DC Characteristics

NOTE: Refer to *BCM53161XU Hardware Design Guide* for more information on voltage tolerances and power supplies decoupling.

NOTE: The voltage tolerances are ±3% on 1.0V and ±5% on all other supplies. The 1.0V ±3% does not apply to VDDC_1P0 (AVS). The actual voltage level and tolerance on the VDDC_1P0 supply is controlled by AVS. AVS is required for the device to operate properly and the voltage range is 0.85V to 1.10V.

Table 27: Recommended Operating Conditions

Symbol	Nominal Value	Description
VDDC_1P0	1.0V	1.0V core power (AVS)
AVDD0P9_PHY0	1.0V	1.0V analog power (GPHY)
AVDD0P9_PHY1	1.0V	
AVDD0P9_PHY2	1.0V	
AVDD0P9_PHY3	1.0V	
PHYPLL_VDD0P9	1.0V	1.0V PLL power for GPHY
QSGMII_P_R_VDD1P0	1.0V	1.0V power supply for QSGMII
QSGMII_T_VDD1P0	1.0V	
XFI_P_R_VDD1P0	1.0V	1.0V power supply for Eagle
XFI_T_VDD1P0	1.0V	
RESCAL_pad_i_VDD1p0	1.0V	1.0V power for RESCAL (non-AVS)
UPI_VDD18_int	1.8V	1.8V power for UPI
UPI_VDD18	1.8V	
PLL_VDD1P8	1.8V	1.8V System PLL power. (for both PLL1 and LCPLL)
AVDD_PVTMON	1.8V	1.8V pvtmon power supply
XTAL_VDD1P8	1.8V	1.8V power for XTAL
OTP_VDD	1.8V	1.8V OTP power
VDDP_1P8	1.8V	1.8V general I/O VDDP power
MDIO_VDDP	1.8/1.2V	1.8/1.2V I/O VDDP doe MDC/MDIO
RGMII_VDDP	1.8V/1.5V	1.8V/1.5V I/O VDDP for WAN port
MDIO_VDDO	3.3/1.2V	3.3/1.2V I/O power for MDC/MDIO
VDDO_3P3	3.3V	3.3V general I/O power
AVDD3P3_PHY0	3.3V	3.3V analog power (GPHY)
AVDD3P3_PHY1	3.3V	
AVDD3P3_PHY2	3.3V	
AVDD3P3_PHY3	3.3V	
BVDD3P3	3.3V	3.3V BIAS power for GPHY
LDO_AVDD	3.3V	3.3V power for LDO
RGMII_VDDO	2.5V/1.5V	2.5V/1.5V I/O power for WAN port (PAD_wan_*).

8.2.1 Standard 3.3V Signals

These specifications apply to all 3.3V signals, such as Serial Flash, MII, MFIO, I^{2}C, MDC/MDIO, SyncE pins, JTAG interfaces, and clock reset pins.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input voltage	V_{IN}	–	–0.3	–	3.63	
Input low voltage	V_{IL}	–	–	–	0.8	V
Input high voltage	V_{IH}	–	2.0	–	–	V
Output low voltage	V_{OL}	IOL = 4 mA[a]	–	–	0.4	V
Output low current	I_{OL}	VOL = 0.4V	4.0	–	–	mA
Output high voltage	V_{OH}	IOH = –4 mA	2.4	–	–	V

a. For BCM5316X, increase IOL from 4 mA to 6 mA for VOL Max value to meet specifications at higher than 90°C ambient thermal conditions.

8.2.2 Standard 2.5V Signals

These specifications apply to all 2.5V signals, such as RGMII interface.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input voltage	V_{IN}	–	–0.3	–	2.75	
Input low voltage	V_{IL}	–	–	–	0.8	V
Input high voltage	V_{IH}	–	1.7	–	–	V
Output low voltage	V_{OL}	–	–	–	0.4	V
Output high voltage	V_{OH}	–	2.0	–	–	V

8.2.3 REFCLK Input Timing

Table 28: REFCLK Input Timing

Parameter	Symbol	Min.	Typ.	Max.	Unit
Frequency	C_{freq}	–	25	–	MHz
Accuracy	–	–15	–	+15	ppm
RMS Jitter (noise bandwidth: 10 kHz – 5 MHz)	–	–	0.444	0.651	ps
RMS Jitter (noise bandwidth: 10 kHz – 1 MHz)	–	–	0.281	0.392	ps
ESR	–	–	–	15	ohm
Frequency	C_{freq}	–	156.25	–	MHz
Accuracy	–	–50	–	+50	ppm
RMS Jitter	–	–	–	0.7	ps
Rise/Fall time (20%~80%)	T_r/T_f	–	200	300	ps

8.2.4 SGMII DC Characteristics

Table 29: SGMII DC Characteristics

Parameter	Symbol	Min.	Max.	Unit
Output differential voltage SOUT±	V_{OD}	400	1200	mV
Input Voltage range SGIN±	V_{IN}	50	1000	mV
Input differential threshold SGIN±	V_{ID}	–	50	mV

8.2.5 SGMII Transmit Timing

Table 30: SGMII Transmit Timing

Parameter	Symbol	Min.	Max.	Unit
Fall time (20% to 80%) SGOUT±	T_F	100	200	ps
Rise time (20% to 80%) SGOUT±	T_R	100	200	ps

8.2.6 QSGMII Transmitter

Table 31: QSGMII Transmitter

Parameter	Symbol	Min.	Typ.	Max.	Unit
Baud Rate	T_{Baud}	-	5.000	–	Gsym/s
Output Differential Voltage (into floating Load R_{load}=100 ohm)	T_{DIFF}	400	-	1200	mVppd
Differential Resistance	T_{RD}	80	100	120	Ohms
Recommended Output Rise and Fall Time (20% to 80%)	T_R/ T_F	30	–	–	Ps
Transmitter Common Mode Noise	TN_{CM}	–	–	5% of T_{DIFF}	mVppd
Output current short	T_{IS}	–	100	mA	–
Output Common Mode Voltage	T_{CM}	735	–	1135	–
Output Amplitude	–	–	–	–	–

8.2.7 QSGMII Receiver

Table 32: QSGMII Receiver

Parameter	Symbol	Min.	Typ.	Max.	Unit
Baud Rate	R_{Baud}	–	5.0	–	Gsym/s
Output Differential Voltage (into floating Load R_{load}=100Ω)	R_{DIFF}	100	–	750	mVppd

8.2.8 XFI Transmitter Performance Specification
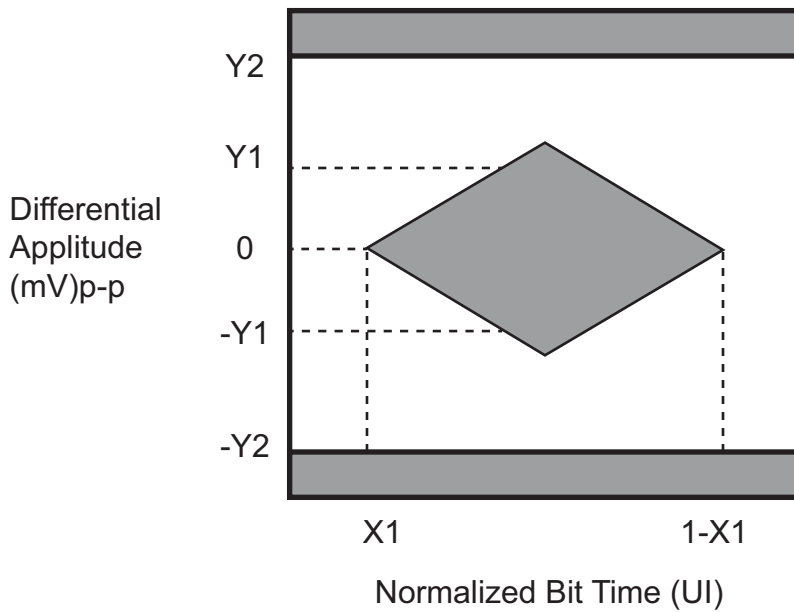
Figure 21: XFI Far-End Eye Mask

Table 33: XFI Far-End Eye Mask

Parameter	Min.	Typ.	Max.	Unit
Nominal VCO center frequency	–	10.3125	–	–
Total jitter	–	–	0.61	–
Total non-EQJ Jitter	–	–	0.41	–
Eye mask X1	–	–	0.305	UI
Eye mask Y1	60	–	–	mV
Eye mask Y1	–	–	410	mV

8.2.9 XFI Transmitter DC Characteristics

Table 34: XFI Transmitter DC Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Output Voltage, differential	V_{od1V}	0.5	1.0	1.1	V_{ptpd}
Output Voltage, common mode	V_{ocm}	–	0.5	–	V
Output Voltage fall time (20% to 80%)	t_{fall}	24	–	47	ps
Output Voltage rise time (20% to 80%)	t_{rise}	24	–	47	Ps

8.2.10 XFI Receiver Input Performance Specification

Table 35: XFI Receiver Input Performance Specification

Parameter	Min.	Typ.	Max.	Unit
Total jitter	–	–	0.65	UI
Total non-EQJ Jitter	–	–	0.45	UI
Eye mask X1	–	–	0.325	UI
Eye mask Y1	55	–	–	mV
Eye mask Y2	–	–	525	mV

8.2.11 XFI Receiver DC Characteristics

Table 36: XFI Receiver DC Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Input Voltage, differential	V_{id}	85	–	1600	mVppd
Input Voltage, common mode	$V_{CM\text{-}RX}$	400	750	1100	mV
Input voltage, peak	$V_{max\text{-}RX}$	0	–	1500	mV

8.2.12 RGMII Pin Operation at 2.5V VDDO_RGMII

Table 37: RGMII Pin Operation at 2.5V VDDO_RGMII

Parameter	Symbol	Min.	Max.	Unit	Condition
Input high voltage, RGMII pin	V_{IH}	1.70	OVDD_RGMII	V	–
Input low voltage, RGMII pin	V_{IL}	–0.30	+0.70	V	–
Output high voltage, RGMII pin	V_{OH}	2.0	–	V	I_{OH} = –1 mA
Output low voltage, RGMII pin	V_{OL}	–	0.4	V	I_{OL} = 1 mA

8.2.13 RGMII Pin Operation at 1.5V VDDO_RGMII

Table 38: RGMII Pin Operation at 1.5V VDDO_RGMII

Parameter	Symbol	Min.	Max.	Unit	Condition
Input high voltage, RGMII pin	V_{IH}	0.5xOVDD_RGMII+0.1	OVDD_RGMII	V	HSTL
Input low voltage, RGMII pin	V_{IL}	–0.30	0.5xOVDD_RGMII–0.1	V	HSTL
Output high voltage, RGMII pin	V_{OH}	OVDD_RGMII-0.4	–	V	HSTL
Output low voltage, RGMII pin	V_{OL}	–	0.4	V	HSTL

8.3 Power Consumption

8.3.1 Power Consumption

Table 39: BCM53161X Estimated Power Consumption

Symbol	Part	Power Rail	Conditions	Min.	Typical	Max.	Unit
Current	BCM53161X	3.3V	Estimated	–	19.251	46.253	mA
		1.8V	Estimated	–	47.748	78.311	mA
		1.0V digital core	Estimated	–	1821.365	2214.350	mA
		1.0V analog	Estimated	–	277.230	359.750	mA
Power			Estimated	–	2248.068	2867.697	mW
This power consumption was estimated with the following conditions:							
■ Full traffic running with all interfaces.							
■ Junction Temperature (Tj) @ 110°C for Max case and 25°C for typical case.							
■ VDDC_1P0 = 1.05V							
In others power rails: +5% for a max case and normal value for a typical case.							

Chapter 9: Timing Characteristics

9.1 Reset and Clock Timing

Figure 22: Reset and Clock Timing
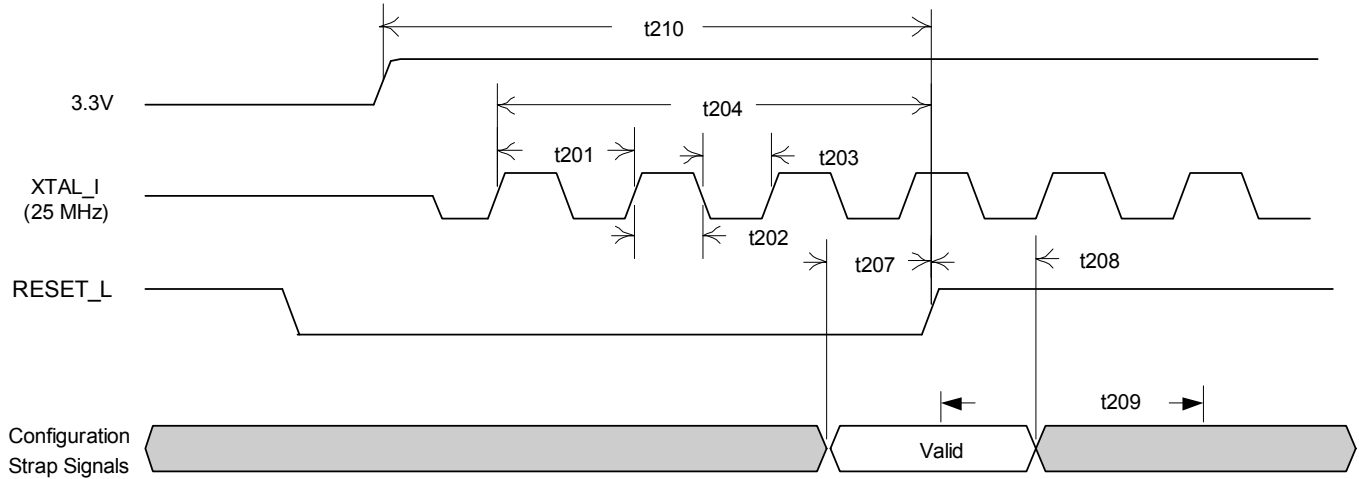
Table 40: Reset and Clock Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t201	XTAL_I frequency	–	25.0000	–	MHz
t202	XTAL_I high time	–	20	–	ns
t203	XTAL_I low time	–	20	–	ns
t204	RESET_L low pulse duration	50	–	–	ms
t207	Configuration valid setup to RESET_L rising	50	–	–	µs
t208	Configuration valid hold from RESET_L rising	120	–	–	ns
t209	RESET_L deassertion to normal operation	–	1.0	–	ms
t210	Reset low hold time after power supplies stabilize	100	–	–	ms

9.2 RGMII Interface Timing

The following specifies timing information regarding the IMP interface pins when configured in RGMII mode.

9.2.1 RGMII Output Timing (Normal Mode)
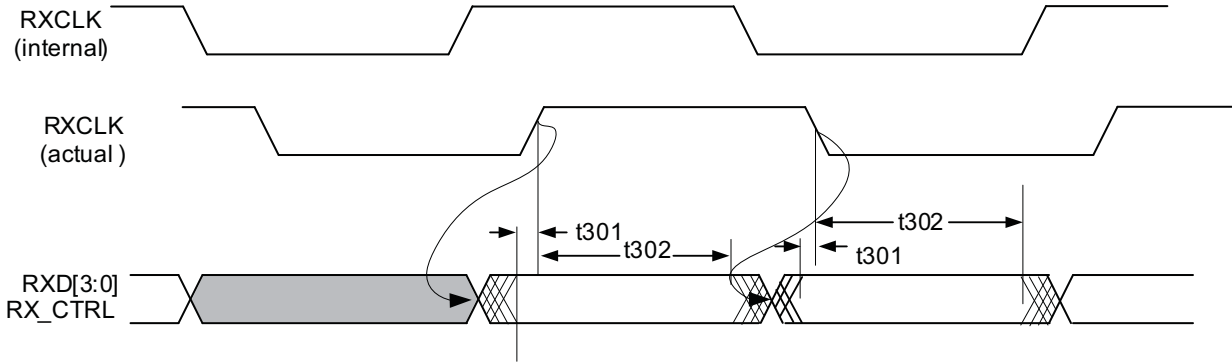
Figure 23: RGMII Output Timing (Normal Mode)
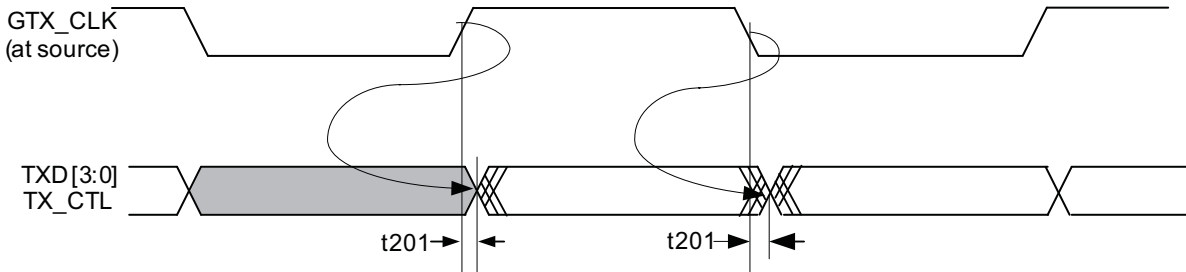
NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 41: RGMII Output Timing (Normal Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_TXC clock period (1000M mode)	–	7.2	8	8.8	ns
MII1_TXC clock period (100M mode)	–	36	40	44	ns
MII1_TXC clock period (10M mode)	–	360	400	440	ns
TskewT: Data to clock output skew	t201	–500 (1000M)	0	+500 (1000M)	ps
TskewT: Data to Clock at 1.5V mode	t201	–750 (1000M)	0	+500 (1000M)	ps
Duty cycle for 1000M (GE)	–	45	50	55	%
Duty cycle for 10/100M (FE)	–	40	50	60	%

NOTE: The output timing in 10/100M operation is always as specified in the delayed mode.

9.2.2 RGMII Output Timing (Delayed Mode)

Figure 24: RGMII Output Timing (Delayed Mode)
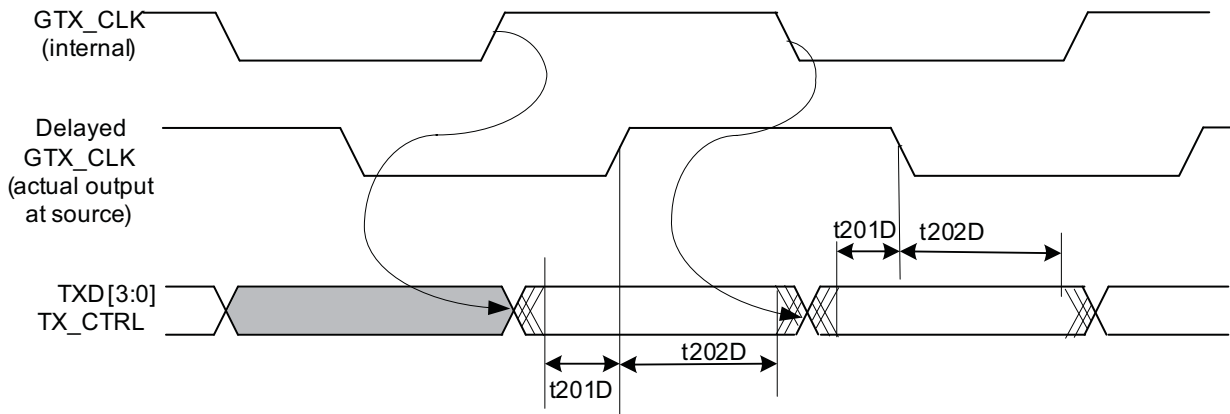
NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 42: RGMII Output Timing (Delayed Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_TXC clock period (1000M mode)	–	7.2	8	8.8	ns
MII1_TXC clock period (100M mode)	–	36	40	44	ns
MII1_TXC clock period (10M mode)	–	360	400	440	ns
TsetupT Data valid to clock transition: Available setup time at the output source (delayed mode)	t201D	1.2 (all speeds)	2.0	–	ns
TholdT Clock transition to data valid: Available hold time at the output source (delayed mode)	t202D	1.2 (all speeds)	2.0	–	ns
TsetupT Data valid to clock transition: Available setup time at the output source (1.5V mode)	t201D	1.0 (all speeds)	2.0	–	ns
TholdT Clock transition to data valid: Available hold time at the output source (1.5V mode)	t202D	1.0 (all speeds)	2.0	–	ns
Duty cycle for 1000M (GE)	–	45	50	55	%
Duty cycle for 10/100M (FE)	–	40	50	60	%

9.2.3 RGMII Input Timing (Normal Mode)
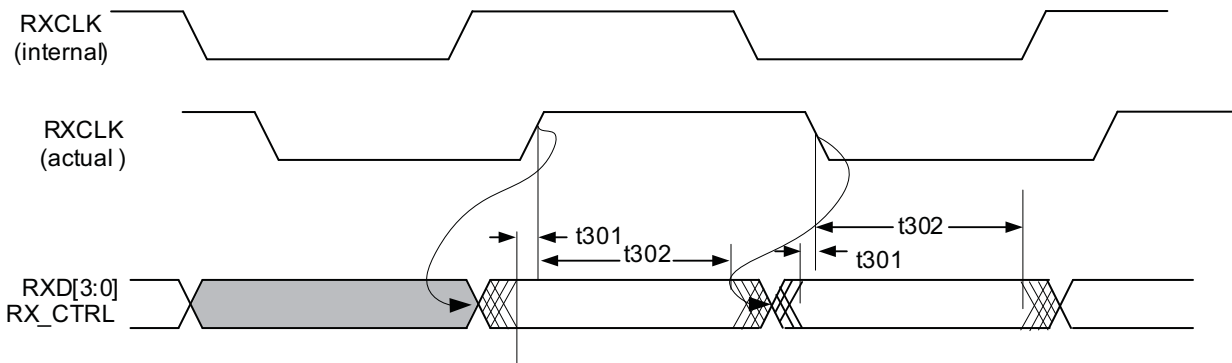
Figure 25: RGMII Input Timing (Normal Mode)

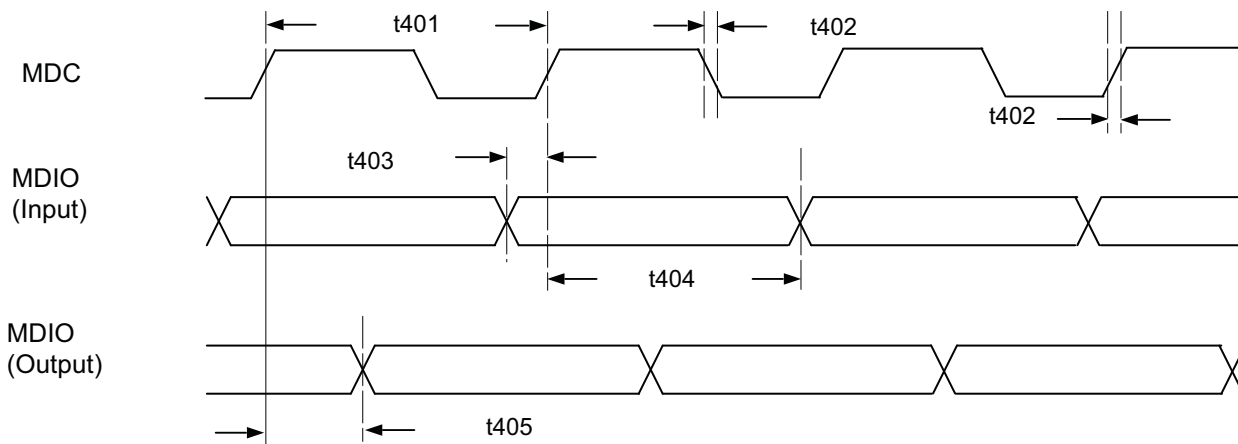**NOTE:** Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 43: RGMII Input Timing (Normal Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_RXC clock period (1000M mode)	–	7.2	8	8.8	ns
MII1_RXC clock period (100M mode)	–	36	40	44	ns
MII1_RXC clock period (10M mode)	–	360	400	440	ns
TsetupR Input setup time: Valid data to clock	t301	1.0	2.0	–	ns
TholdR Input hold time: Clock to valid data	t302	1.0	2.0	–	ns
Duty cycle for 1000M (GE)	–	45	50	55	%
Duty cycle for 10/100M (FE)	–	40	50	60	%

9.2.4 RGMII Input Timing (Delayed Mode)

Figure 26: RGMII Input Timing (Delayed Mode)

NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 44: RGMII Input Timing (Delayed Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
TsetupR	t301D	−1.0 (1000M)	–	–	ns
Input setup time (delayed mode)		−1.0 (10/100M)	–	–	ns
TholdR	t302D	3.0 (1000M)	–	–	ns
Input hold time (delayed mode)		9.0 (10/100M)	–	–	ns

9.3 MDC/MDIO Timing

The following specifies timing information regarding the MDC/MDIO interface pins.

Figure 27: MDC/MDIO Timing (Slave Mode)

NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 45: MDC/MDIO Timing (Slave Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MDC cycle time	t401	80	–	–	ns
MDC high/low	–	30	–	–	ns
MDC rise/fall time	t402	–	–	10	ns
MDIO input setup time to MDC rising	t403	7.5	–	–	ns
MDIO input hold time from MDC rising	t404	7.5	–	–	ns
MDIO output delay from MDC rising	t405	0	–	45	ns

Figure 28: MDC/MDIO Timing (Master Mode)
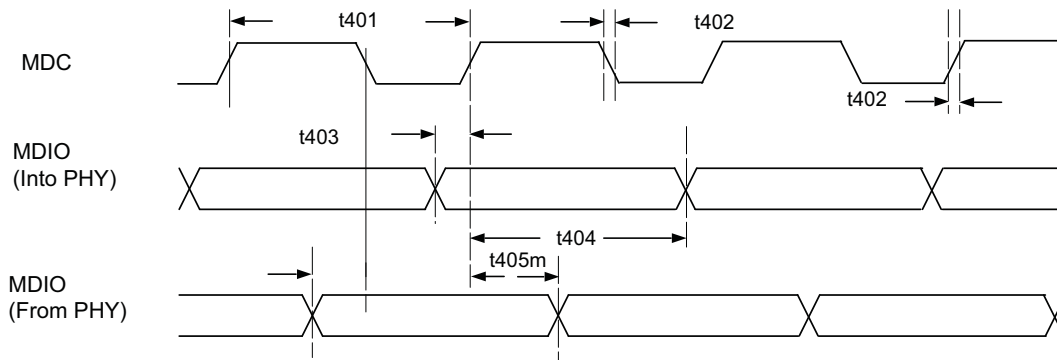
Table 46: MDC/MDIO Timing (Master Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MDC cycle time	t401	400	–	–	ns
MDC high/low	–	160	–	240	ns
MDC rise/fall time	t402	–	–	10	ns
MDIO input setup time to MDC rising	t403	20	–	–	ns
MDIO input hold time from MDC rising	t404	7.5	–	–	ns
MDIO output delay from MDC rising	t405	0	–	30	ns

9.4 Serial Flash Timing

Figure 29: Serial Flash Timing Diagram
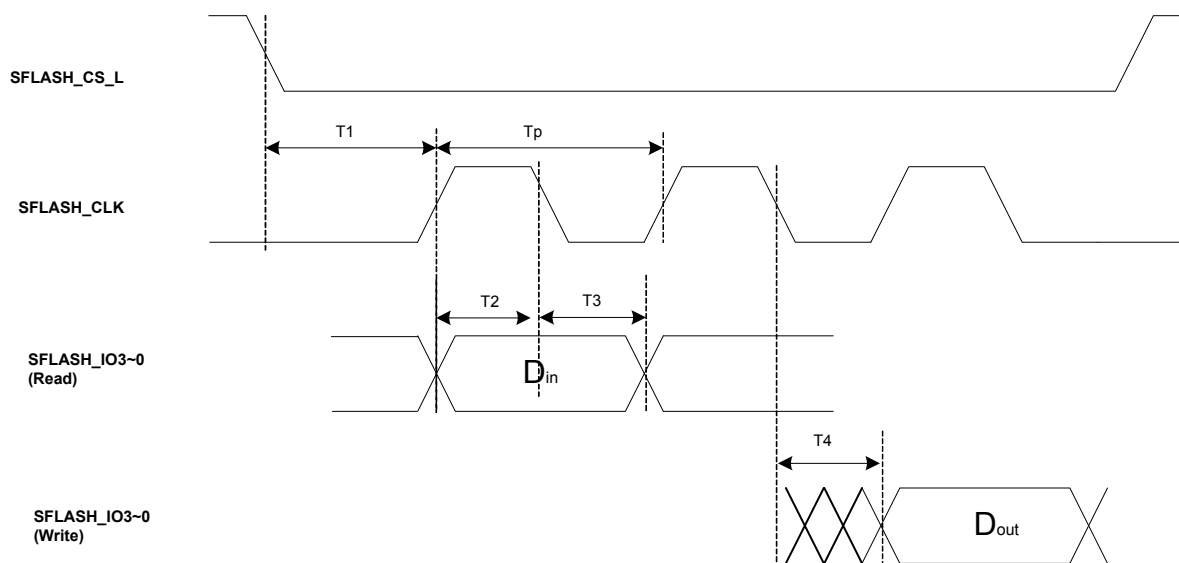
Table 47: Serial Flash Timing

Parameter	Descriptions	Min.	Typ.	Max.	Unit
f_{FREQ}	SFlash_CLK frequency	–	–	62.5	MHz
t_P	Cycle time: SFLASH_CLK period	16	–	–	ns
t_1	Delay time: SFLASH_CS_L low to SFLASH_CLK rising edge	–	1	–	t_P
t_2	Input Setup time: SFLASH_IOx valid to SFLASH_CLK falling edge	10	–	–	ns
t_3	Input Hold time: SFLASH_CLK falling edge to SFLASH_IOx invalid	0	–	–	ns
t_4	Output valid time: SFLASH_IOx valid to SFLASH_CLK rising edge	6	–	–	ns

9.5 SPI Interface Timing

9.5.1 BCM53161XU SPI-1 Master Interface Timing (A1)

Figure 30: SPI-1 Timing, SS Asserted During SCK Low
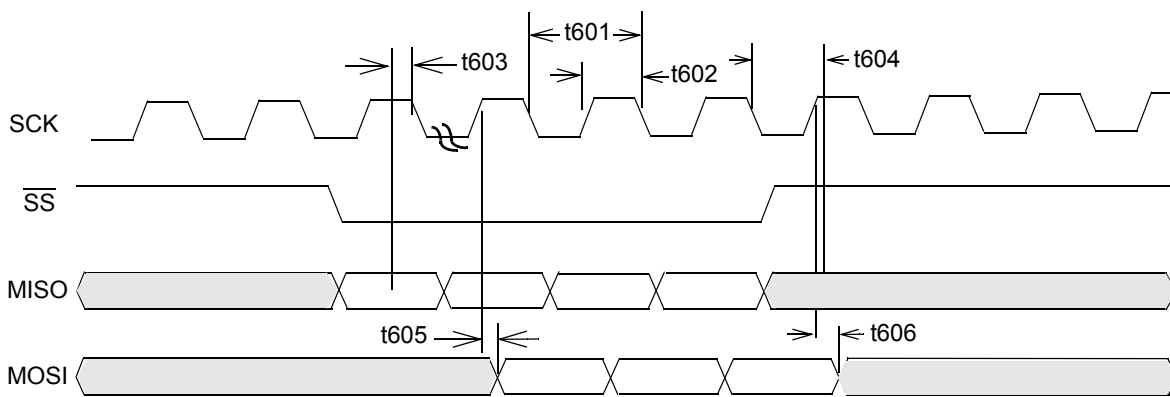
Table 48: SPI-1 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	–	–	ns
t602	SCK High/Low Time	–	–	–	ns
t603	MISO to SCK Setup Time	7	–	–	ns
t604	MISO to SCK Hold Time	0	–	–	ns
t605	SCK to MOSI Valid	–	–	6	ns
t606	SCK to MOSI Invalid	0	–	–	ns

9.5.2 BCM53161XU SPI-2 Slave Interface Timing (A1)

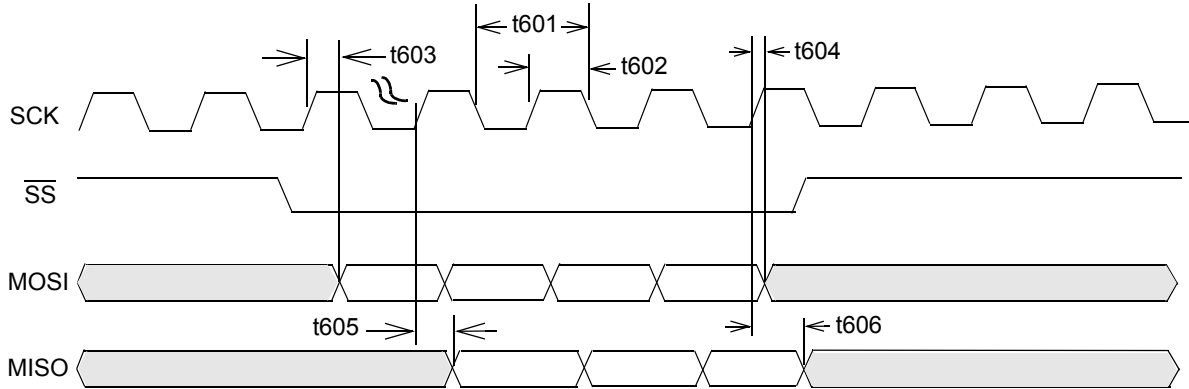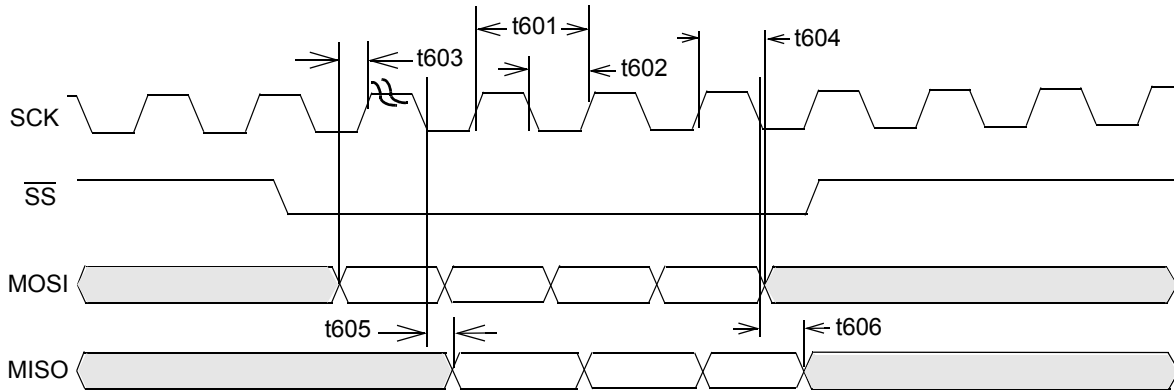**Figure 31: SPI-2 Timing, SS Asserted During SCK Low**

Table 49: SPI-2 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	–	–	ns
t602	SCK High/Low Time	–	–	–	ns
t603	MOSI to SCK Setup Time	5	–	–	ns
t604	MOSI to SCK Hold Time	3	–	–	ns
t605	SCK to MISO Valid	–	–	7	ns
t606	SCK to MISO Invalid	0	–	–	ns

9.5.3 BCM53161XU SPI-1 Master Interface Timing (B0)

Figure 32: SPI-1 Timing, $\overline{SS}$ Asserted During SCK High
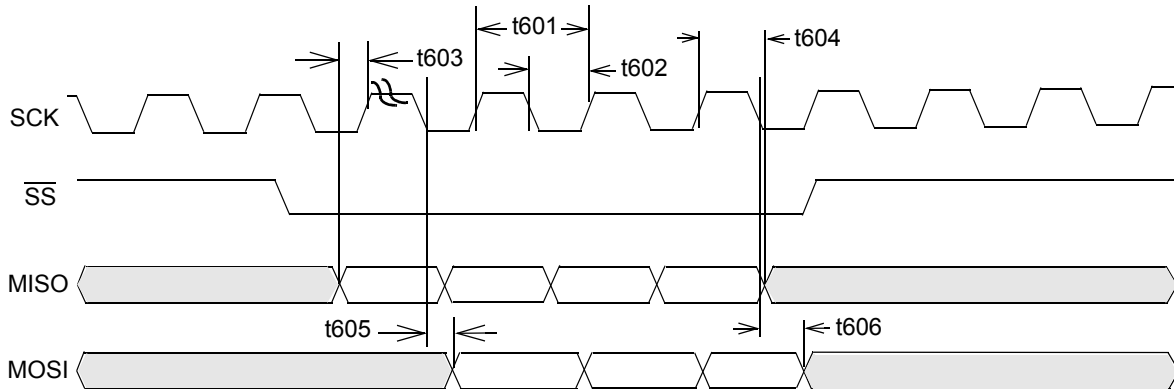
Table 50: SPI-1 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	–	–	ns
t602	SCK High/Low Time	–	–	–	ns
t603	MISO to SCK Setup Time	7	–	–	ns
t604	MISO to SCK Hold Time	0	–	–	ns
t605	SCK to MOSI Valid	–	–	6	ns
t606	SCK to MOSI Invalid	0	–	–	ns

9.5.4 BCM53161XU SPI-2 Slave Interface Timing (B0)

Figure 33: SPI-2 Timing, $\overline{SS}$ Asserted During SCK High

Table 51: SPI-2 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	–	–	ns
t602	SCK High/Low Time	–	–	–	ns
t603	MOSI to SCK Setup Time	5	–	–	ns
t604	MOSI to SCK Hold Time	3	–	–	ns
t605	SCK to MISO Valid	–	–	7	ns
t606	SCK to MISO Invalid	0	–	–	ns

9.6 JTAG Interface

JTAG timing is synchronous to the JTAG_TCK clock.

Figure 34: JTAG Interface
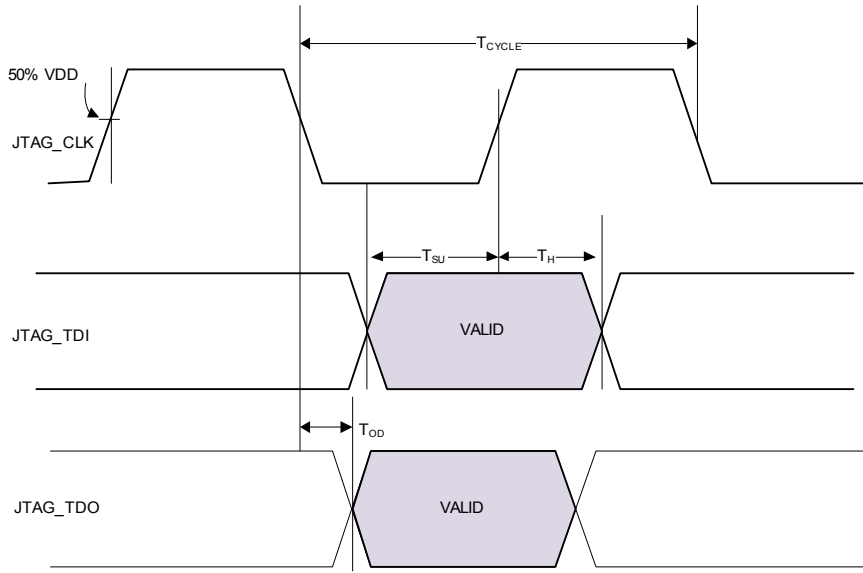
Table 52: JTAG Interface

Parameter	Description	Min.	Typ.	Max.	Unit
T_{CYCLE}	JTAG Cycle Time	50	–	–	ns
T_{SU}	Input Setup Time	12.5	–	–	ns
T_{H}	Input Hold Time	12.5	–	–	ns
T_{OD}	Output Delay Time Measured from Falling Edge of JTAG_TCK	–	–	22	ns

9.7 BSC Timing

Figure 35: BSC Interface
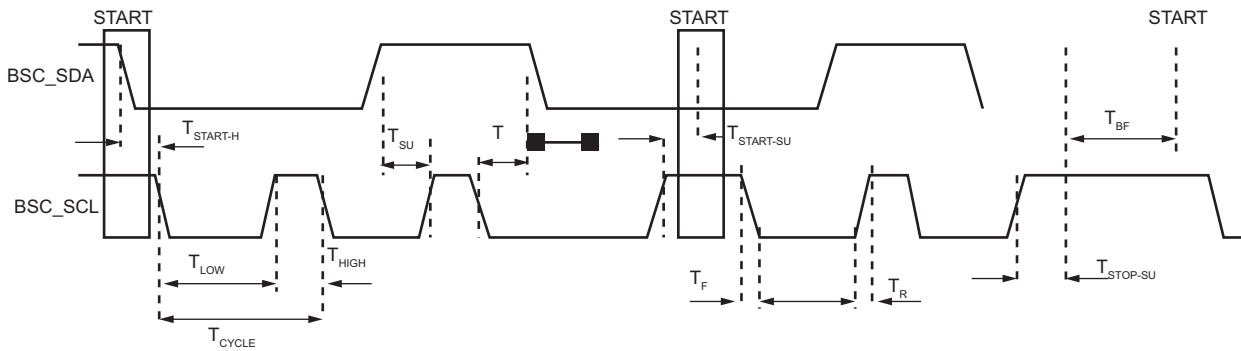
Table 53: BSC Interface

Parameter	Description	Min.	Typ.	Max.	Unit
T_{CYCLE}	BSC_SCL Cycle Time	10	–	100	ns

Table 53: BSC Interface (Continued)

Parameter	Description	Min.	Typ.	Max.	Unit
T_{LOW}	BSC_SCL Low Time	4.7	–	–	ns
T_{HIGH}	BSC_SCL High Time	4.0	–	–	ns
T_H	Data Hold Time	300	–	–	ns
T_{SU}	Data Setup Time	250	–	–	ns
T_R	Rise Time (Clock and Data, see note below)	–	–	1000	ns
T_F	Fall Time (Clock and Data)	–	–	300	ns
$T_{START-H}$	Hold Time, START, or Repeated START	4.0	–	–	ns
$T_{START-SU}$	Setup Time, Repeated START	4.7	–	–	ns
$T_{STOP-SU}$	Setup Time, STOP	4.0	–	–	ns
T_{BF}	Bus Free Time Between STOP and START	4.7	–	–	ns

NOTE:

■ BSC_SCL and BSC_SDA are open-collector outputs. The rise time is dependent on the strength of the external pull-up resistor, which is recommended to be chosen to meet the rise time requirement.

■ BSC = Broadcom Serial Controller master mode only. It is compatible with I^2C standard. I^2C is copyrighted by Philips/NXP.

9.8 Serial LED Interface Timing

The following specifies timing information regarding the LED interface pins.
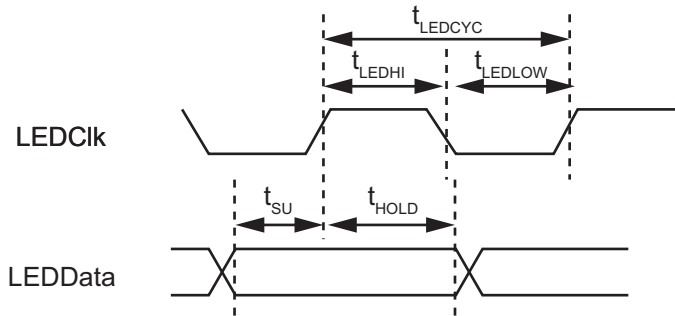
Figure 36: LEDCLK/LEDDATA Timing

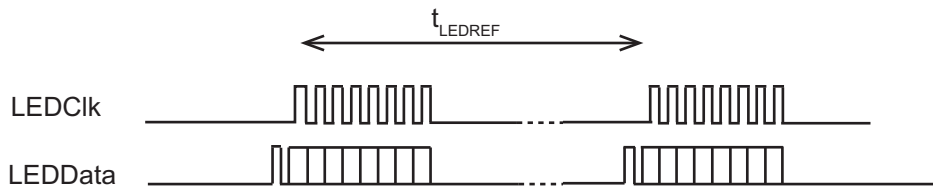**Figure 37: LEDClk/LEDData Refresh Interval**

Table 54: Serial LED Timing

Parameter	Description	Min.	Typ.	Max.	Unit
t_{LEDCYC}	LED clock period	–	200	–	ns
t_{LEDHI}	LED clock high-pulse width	70	100	130	ns
t_{LEDLOW}	LED clock low-pulse width	70	100	130	ns
t_{SU}	LED data setup time	50	90	–	ns
t_{HOLD}	LED data hold time	50	90	–	ns
t_{LEDREF}	LED refresh period	–	30	–	ms

9.9 SGMII/SerDes Timing

Figure 38: SGMII/SerDes Interface Output Timing
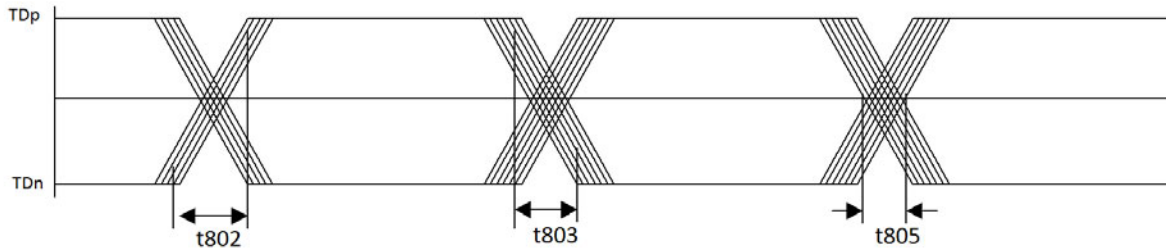
Table 55: SGMII/SerDes Interface Output Timing

Parameter	Description	Min.	Typ.	Max.	Unit
t801	Transmit Data Signaling Speed	–	1.25	–	Gbaud
t802	Transmit Data Rise Time (20% to 80%)	100	–	200	ps
t803	Transmit Data Fall Time (20% to 80%)	100	–	200	ps
t805	Transmit Data Total Jitter	–	–	0.25	UI

Figure 39: SGMII/SerDes Interface Input Timing
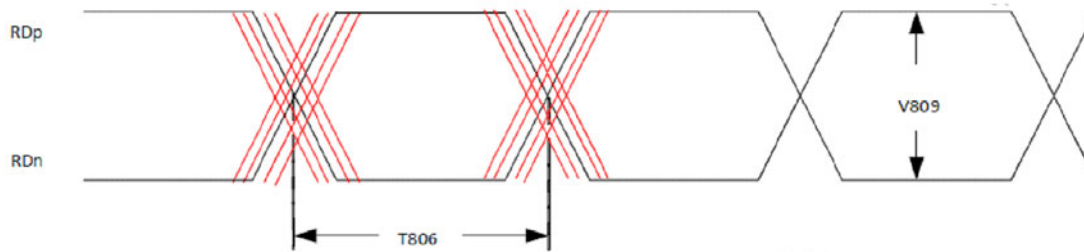
Table 56: SGMII/SerDes Interface Input Timing

Parameter	Description	Min.	Typ.	Max.	Unit
t806	Receive Data Signaling Speed	–	3.125	–	Gbaud
v809	Receive Data Differential Input (pk-pk)	0.1	–	2.0	V

9.10 2.5GE/SerDes Timing

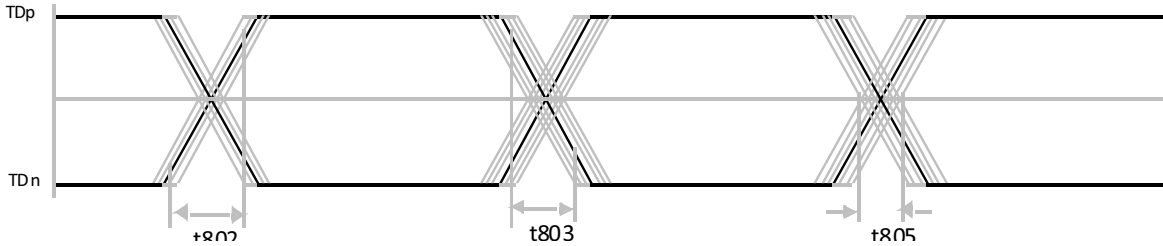**Figure 40: 2.5GE/SerDes Interface Output Timing**

Table 57: 2.5GE/SerDes Interface Output Timing

Parameter	Description	Min.	Typ.	Max.	Unit
t801	Transmit Data Signaling Speed	–	3.125	–	Gbaud
t802	Transmit Data Rise Time (20% to 80%)	30	–	130	ps
t803	Transmit Data Fall Time (20% to 80%)	30	–	130	ps
t805	Transmit Data Total Jitter	–	–	0.35	UI
T_{SKEW}	Transmit Differential Skew	–	–	0.15	ps

Figure 41: 2.5GE/SerDes Interface Input Timing
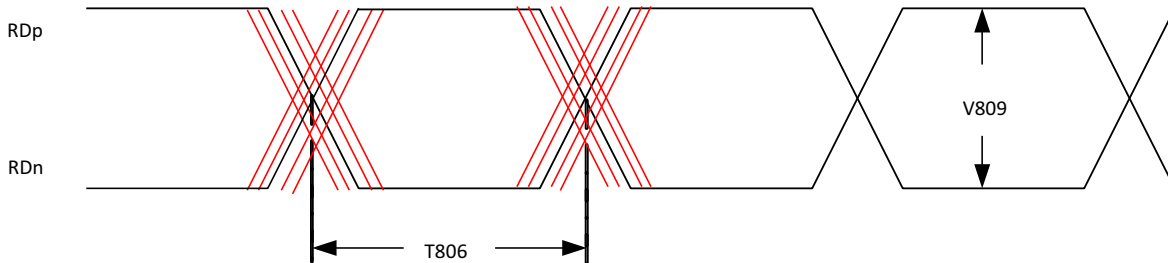
Table 58: 2.5GE/SerDes Interface Input Timing

Parameter	Description	Min.	Typ.	Max.	Unit
t806	Receive Data Signaling Speed	–	3.125	–	Gbaud
v809	Receive Data Differential Input (pk-pk)	–	–	1.6	V

9.11 Synchronous Ethernet Interface

TBD

# Chapter 10: Thermal Characteristics

10.1 BCM53161XU Package with Heat Sink (45×45×15 mm^3)

Table 60: 19x19 mm^2 Package with External Heat Sink 45x45x15 mm^3, 2s2p PCB, T$_A$ = 50°C, P = 4.651W

Device power dissipation, P (W)		4.651				
Ambient air temperature, T$_A$ (°C)		50				
θ$_{JA}$ in still air (°C/W) with external heatsink		11.67				
θ$_{JB/AVG}$ (°C/W)		11.96				
θ$_{JC}$ (°C/W)		4.07				
2s2p board, 45x45x15 mm^3 estHS						
Package Thermal Performance Curve						
Air Velocity		**T$_{J, MAX}$**	**T$_T$**	**θ$_{JA, JMA}$**	**Ψ$_{JT}$**	**Ψ$_{JB, AVG}$**
m/s	ft/min	(°C)	(°C)	(°C/W)	(°C/W)	(°C/W)
0	0	104.3	89.7	11.67	3.14	6.35
0.5	98.4	93.1	78.4	9.28	3.17	6.07
1	196.9	87.9	73.1	8.16	3.19	5.89
2	393.7	84.1	69.2	7.33	3.21	5.77
3	590.6	82.0	67.0	6.88	3.22	5.71

Chapter 11: Mechanical Information

Figure 42: BCM53161XU 19×19 mm^2 Mechanical Information
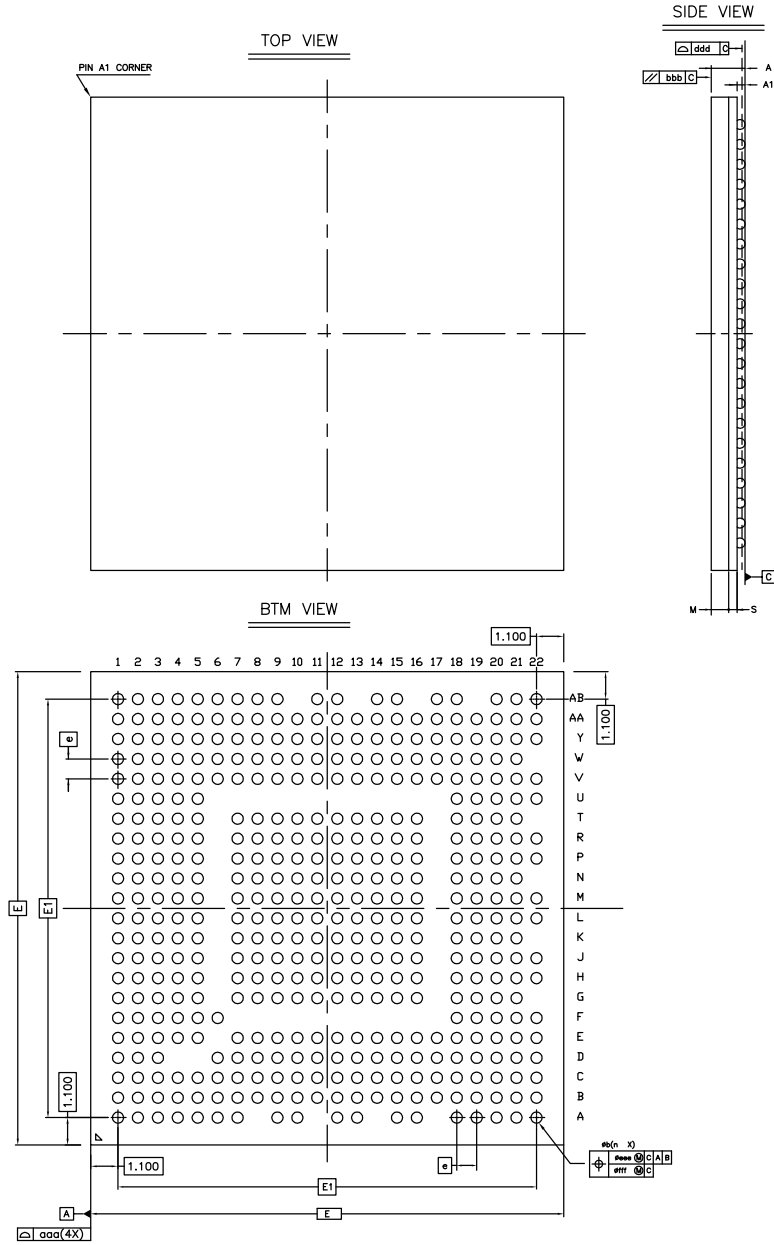
			Symbol	Common Dimensions		
				MIN.	NOM.	MAX.
Package :				LFBGA		
Body Size:	X		E	19.000		
	Y		D	19.000		
Ball Pitch :			e	0.800		
Total Thickness :			A	1.267	1.352	1.437
Mold Thickness :			M	0.700	Ref.	
Substrate Thickness :			S	0.332	Ref.	
Ball Diameter :				0.400		
Stand Off :			A1	0.270		0.370
Ball Width :			b	0.380	–	0.480
Package Edge Tolerance :			aaa	0.075		
Mold Parallelism :			bbb	0.200		
Coplanarity:			ddd	0.120		
Ball Offset (Package) :			eee	0.150		
Ball Offset (Ball) :			fff	0.080		
Ball Count :			n	425		
Edge Ball Center to Center :	X		E1	16.800		
	Y		D1	16.800		

Chapter 12: Ordering Information

Table 61: Ordering Information

Part Number	Operational Mode	Package	Ambient Temperature
BCM53161XUB1KLFBG	Unmanaged	19×19 mm^2, 425-pin FBGA	0°C to 70°C

Revision History

53161XU-DS100-R; April 11, 2018

Initial release.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Broadcom Limited](#):

[BCM53161XUB0KLFBG](#)   [BCM53161XUB1KLFBG](#)